AVX Surface Mount Ceramic Capacitor Products



Version 14.1



Ceramic Chip Capacitors



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How to Order





Commercial Surface Mount Chips

EXAMPLE: 08055A101JAT2A

0805	5	<u>A</u>	101	<u>J*</u>	<u>A</u>	<u> </u>	2	<u>A**</u>
Size (L" x W") 0101* 0201 0402 0603 0805 1206 1210 1812	Voltage 4 = 4V 6 = 6.3V Z = 10V Y = 16V 3 = 25V D = 35V 5 = 50V 1 = 100V 2 = 200V	Dielectric A = NPO(COG) C = X7R D = X5R F = X8R G = Y5V U = U Series W = X6S Z = X7S	Capacitance 2 Sig. Fig + No. of Zeros Examples: 100 = 10 pF 101 = 100 pF 102 = 1000 pF 223 = 22000 pF 224 = 220000 pF 105 = 1µF	Tolerance B = ±.10 pF C = ±.25 pF D = ±.50 pF F = ±1% (≥ 10 pF) G = ±2% (≥ 10 pF) J = ±5% K = ±10%	Failure Rate A = N/A 4 = Automotive	Terminations T = Plated Ni and Sn 7 = Gold Plated U = Conductive Expoxy for Hybrid Applications Z = FLEXITERM® X = FLEXITERM®	Packaging Available 2 = 7" Reel 4 = 13" Reel 7 = Bulk Cass. 9 = Bulk U = 4mm TR (01005) Contact	Special Code A = Std K = 30K (0603 2mm pitch) 22K (0805/1206 <0.030"/ 0.76mm) H = 18K (0603/0805/1206 <0.037" / 0.94mm) J = 15K (0805/1206 <0.050" / 1.27mm)
1825 2220 2225 *EIA 01005		Factory for Voltages 9 = 300V X = 350V 8 = 400V	106 = 10µF 107 = 100µF For values below 10 pF, use "R" in place of Decimal point, e.g., 9.1 pF = 9R1.	$\begin{split} M &= \pm 20\% \\ Z &= +80\%, \\ &-20\% \\ P &= +100\%, \\ &-0\% \end{split}$		with 5% min lead (X7R & X8R only) Contact Factory For 1 = Pd/Ag Term	Factory For Multiples	1 = 12K (0805/1206 <0.055 / 1.4mm) **Non std options upon approval from the factory

^{*} B, C & D tolerance for ≤10 pF values.

Standard Tape and Reel material (Paper/Embossed) depends upon chip size and thickness.

See individual part tables for tape material type for each capacitance value.

NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers. For Tin/Lead Terminations, please refer to LD Series

High Voltage MLC Chips

EXAMPLE: 1808AA271KA11A

1808	A	A	271	K	A	<u>T</u>	1	A
AVX	Voltage	Temperature	Capacitance	Capacitance	Failure	Termination	Packaging/	Special
Style	C = 600V/630V	Coefficient	Code	Tolerance	Rate	1= Pd/Ag	Marking	Code
0805	A = 1000V	A = C0G	(2 significant digits	COG: $J = \pm 5\%$	A=Not	T = Plated Ni	1 = 7" Reel	A = Standard
1206	S = 1500V	C = X7R	+ no. of zeros)	$K = \pm 10\%$	Applicable	and Sn	3 = 13" Reel	
1210	G = 2000V		Examples:	$M = \pm 20\%$		B = 5% Min Pb	9 = Bulk	
1808	W = 2500V		10 pF = 100	X7R: $K = \pm 10\%$		Z = FLEXITERM®		
1812	H = 3000V		100 pF = 101	$M = \pm 20\%$		X = FLEXITERM®		
1825	J = 4000V	1	1,000 pF = 102	Z = +80%,		with 5% min		
2220	K = 5000V	22	2,000 pF = 223	-20%		lead (X7R only)		
2225		220	0,000 pF = 224					
3640			$1 \mu F = 105$					

NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers. For Tin/Lead Terminations, please refer to LD Series

Not RoHS Compliant





For RoHS compliant products, please select correct termination style.



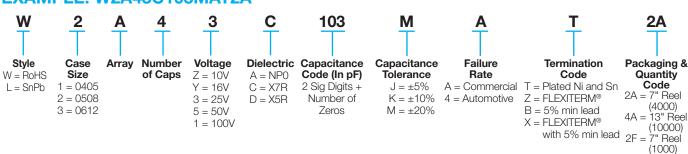
How to Order





Capacitor Array





NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

Low Inductance Capacitors (LICC)

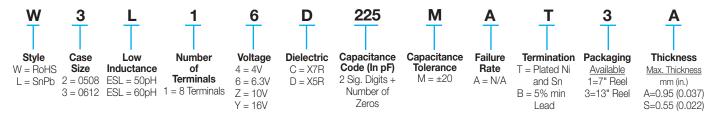
EXAMPLE: 0612ZD105MAT2A



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

Interdigitated Capacitors (IDC)

EXAMPLE: W3L16D225MAT3A

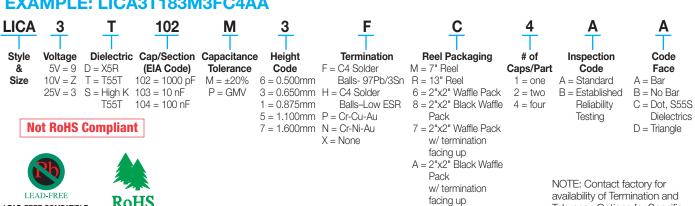


NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

Low Inductance Decoupling Capacitor Arrays (LICA)

EXAMPLE: LICA3T183M3FC4AA

RoHS



For RoHS compliant products, please select correct termination style.

LEAD-FREE COMPATIBLE COMPONENT



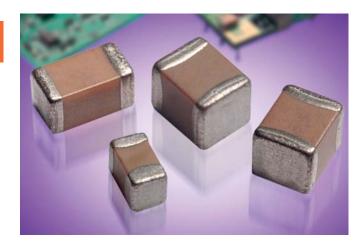
C = 4"x4" Waffle Pack

w/ clear lid

COG (NPO) Dielectric

General Specifications



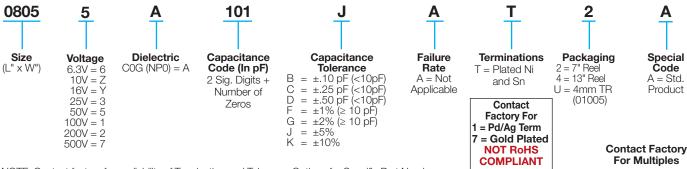


COG (NP0) is the most popular formulation of the "temperature-compensating," EIA Class I ceramic materials. Modern COG (NP0) formulations contain neodymium, samarium and other rare earth oxides.

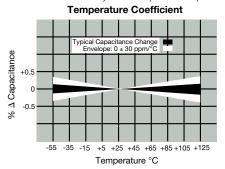
COG (NP0) ceramics offer one of the most stable capacitor dielectrics available. Capacitance change with temperature is 0 $\pm 30 \mathrm{ppm/^\circ C}$ which is less than $\pm 0.3\%$ $\Delta\mathrm{C}$ from -55°C to +125°C. Capacitance drift or hysteresis for COG (NP0) ceramics is negligible at less than $\pm 0.05\%$ versus up to $\pm 2\%$ for films. Typical capacitance change with life is less than $\pm 0.1\%$ for COG (NP0), one-fifth that shown by most other dielectrics. COG (NP0) formulations show no aging characteristics.

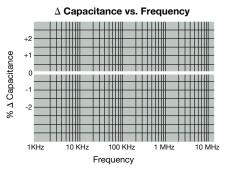
PART NUMBER (see page 2 for complete part number explanation)



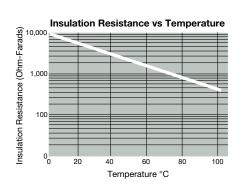


NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.



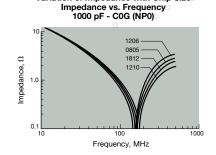


Variation of Impedance with Chip Size



Impedance vs. Frequency 0805 - COG (NPO) 10 pF vs. 1000 pF vs. 100

Variation of Impedance with Cap Value



Impedance vs. Frequency
1000 pF - COG (NPO) vs X7R
0805

10.00

X7R
NPO

1000

Frequency, MHz

Variation of Impedance with Ceramic Formulation



C0G (NP0) Dielectric



Specifications and Test Methods

Parame	ter/Test	NP0 Specification Limits	Measuring Conditions			
	perature Range	-55°C to +125°C	Temperature Cycle Chamber			
Capac	itance	Within specified tolerance	Freq.: 1.0 MHz ± 10% for cap ≤ 1000 pF			
	Q	<30 pF: Q≥ 400+20 x Cap Value	$1.0 \text{ kHz} \pm 10\% \text{ for cap} > 1000 \text{ pF}$			
	<u>-</u>	≥30 pF: Q≥ 1000	Voltage: 1.0Vrms ± .2V			
Insulation	Resistance	100,000MΩ or 1000MΩ - μF,	Charge device with rated voltage for			
		whichever is less	60 ± 5 secs @ room temp/humidity Charge device with 300% of rated voltage for			
Dielectric	: Strength	No breakdown or visual defects	1-5 seconds, w/charge and discharge current limited to 50 mA (max) Note: Charge device with 150% of rated voltage for 500V devices.			
	Appearance	No defects	Deflection: 2mm			
Resistance to	Capacitance Variation	±5% or ±.5 pF, whichever is greater	Test Time: 30 seconds √ 1mm/sec			
Flexure Stresses	Q	Meets Initial Values (As Above)	V V			
	Insulation Resistance	≥ Initial Value x 0.3	90 mm —			
Solde	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at 230 \pm 5°C for 5.0 \pm 0.5 seconds			
	Appearance	No defects, <25% leaching of either end terminal				
	Capacitance Variation	≤ ±2.5% or ±.25 pF, whichever is greater	Dip device in eutectic solder at 260°C for 60			
Resistance to Solder Heat	Q	Meets Initial Values (As Above)	seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.			
Solder Heat	Insulation Resistance	Meets Initial Values (As Above)				
	Dielectric Strength	Meets Initial Values (As Above)				
	Appearance	No visual defects	Step 1: -55°C ± 2° 30 ± 3 minutes			
	Capacitance Variation	≤ ±2.5% or ±.25 pF, whichever is greater	Step 2: Room Temp ≤ 3 minutes			
Thermal Shock	Q	Meets Initial Values (As Above)	Step 3: +125°C ± 2° 30 ± 3 minutes			
oo	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp ≤ 3 minutes			
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 hours at room temperature			
	Appearance	No visual defects				
	Capacitance Variation	≤ ±3.0% or ± .3 pF, whichever is greater	Charge device with twice rated voltage in			
Load Life	Q (C=Nominal Cap)	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	test chamber set at $125^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 1000 hours (+48, -0).			
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamber and stabilize at room temperature for 24 hours			
	Dielectric Strength	Meets Initial Values (As Above)	before measuring.			
	Appearance	No visual defects				
	Capacitance Variation	≤ ±5.0% or ± .5 pF, whichever is greater	Store in a test chamber set at 85°C ± 2°C/			
Load Humidity	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied.			
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber and stabilize at room temperature for 24 ± 2 hours			
	Dielectric Strength	Meets Initial Values (As Above)	before measuring.			

COG (NP0) Dielectric





PREFERRED SIZES ARE SHADED

SIZE 0101* 0201 0402 0603 0805 1206 Soldering Reflow Only Reflow Only Reflow/Wave Reflow/Wave Reflow/Wave Reflow/Wave All Paper **Packaging** All Paper All Paper All Paper Paper/Embossed Paper/Embossed 1.60 ± 0.15 (0.063 ± 0.006) 2.01 ± 0.20 (0.079 ± 0.008) (L) Length 0.016 ± 0.0008 (0.024 ± 0.001) (0.040 ± 0.004) (0.126 ± 0.008) 0.20 ± 0.02 0.30 ± 0.03 0.81 ± 0.15 1.25 ± 0.20 (W) Width (0.008 ± 0.0008) (0.011 ± 0.001) (0.020 ± 0.004) (0.032 ± 0.006) (0.049 ± 0.008) (0.063 ± 0.008) 0.50 ± 0.25 (0.020 ± 0.010) 0.25 ± 0.15 (0.010 ± 0.006) 0.35 ± 0.15 (0.014 ± 0.006) 0.10 ± 0.04 0.15 ± 0.05 (0.006 ± 0.002) (t) Terminal (0.020 ± 0.010) (in.) (0.004 ± 0.016) 16 25 50 25 50 50 100 50 100 50 100 Cap (pF) 1.0 1.8 G G G G 2.2 В G 3.9 G G 4.7 5.6 ВВ G G G G G G G G 6.8 12 G G 15 18 В G G G G G G G G G 22 33 39 В G G G 56 G G G G G G G G 120 150 180 220 G М М G 390 470 560 Ρ 680 820 Q Q G G G 1200 1500 2200 M M 2700 3300 Ν М Q 3900 4700 5600 М 6800 М 8200 Cap 0.010 (µF) 0.012 0.015 0.018 0.022 0.027 0.039 0.068 0.082 100 200 200 500 WVDC 50 16 16 100 SIZE 0101 0402 0603 0805 0201 1206 Letter 0.56 0.90 0.94 1.27 1.40 1.78 2.29 2.54 2.79 **Thickness** (0.013)(0.009)(0.022)(0.028)(0.040)(0.050)(0.060)(0.070)(0.090)(0.100)(0.110)

*EIA 01005

PAPER



EMBOSSED

C0G (NP0) Dielectric



Capacitance Range

PREFERRED SIZES ARE SHADED

PREF																				
SIZ	Έ			1210					1812				1825			2220			2225	
Solde			F	Reflow Or	nly				eflow On			R	leflow On	ıly	F	Reflow O	nly	R	eflow Or	nly
Packa	ging mm			er/Embo 3.20 ± 0.2					Emboss 4.50 ± 0.3				Emboss 4.50 ± 0.30			I Embos: 5.70 ± 0.4			Emboss 5.72 ± 0.2	
(L) Length	(in.)		(0	0.126 ± 0.0	08)			(0	$.177 \pm 0.0$	12)		(0.	177 ± 0.01	12)	(0.	$.225 \pm 0.0$	16)	(0	$.225 \pm 0.0$	10)
(W) Width	mm (in.)		(0	2.50 ± 0.2 0.098 ± 0.0	08)			(0	3.20 ± 0.2 .126 ± 0.0	08)		(0.	6.40 ± 0.40 252 ± 0.01	16)	(0.	5.00 ± 0.4 .197 ± 0.0	16)	(0	6.35 ± 0.2 .250 ± 0.0	10)
(t) Terminal	mm (in.)			0.50 ± 0.2 0.020 ± 0.0					0.61 ± 0.3 .024 ± 0.0				0.61 ± 0.36 024 ± 0.01			0.64 ± 0.3 .025 ± 0.0			0.64 ± 0.39 .025 ± 0.0	
Cap	WVDC 0.5	25	50	100	200	500	25	50	100	200	500	50	100	200	50	100	200	50	100	200
(pF)	1.0 1.2 1.5																			
	1.8															_			- -	
	2.7 3.3															<u> </u>	<u></u>			*
	3.9																(-	\int) <u> </u> T
	4.7 5.6 6.8															†				
	8.2 10					J										_	I	' ' ' 	I	I
	12 15					J														
	18 22					J														
	27 33					J														
	39 47					J														
	56 68					J														
	82 100					J														
	120 150					J														
	180					J														
	220 270					J														
	330 390					J M														
	470 560	J	J	J	J	M M														
	680 820	J	J	J	K	P P														
	1000 1200	J P	J P	P P	P P	P P	K K	K K	N N	N N	M M	M M	M M	M M				M M	M M	P P
	1500	Р	Р	Р	Р	P	K	K	N	N	М	М	М	М				М	М	Р
	1800 2200	P P	P P	P P	P P		K K	K K	N N	N N	M P	M X	M X	M M				M M	M M	P P
	2700 3300	P P	P P	P P	Р		K K	K	N N	P P	Q Q	X	X	M X			X	M	M M	P P
	3900 4700	P P	P P	P P			K K	K K	N N	P P	Q Q	X X	X	X X	X	X	X	M M	M M	P P
	5600 6800	P	P P	P			K K	K	P X	P X	X	X	X	X	X	X	X	M M	M M	P
Con	8200 0.010	P P	Р				K K	M M	- /	- /		Χ	X	X	X	Х	X	M M	M M	P P
Cap (µF)	0.012	P	N N				K	M				X	Х	Х	X	X	X	М	М	Р
	0.015						P P	P				X	X	X	X	X	X	M	M M	Y
	0.022						P P	P P				X	X	X Y	X	X		M P	Y	Y
	0.033 0.039						P X	P X				X	X		X Y	X		X X	Y	Y
	0.047 0.068						X Z	X Z				Х			Y Z			X	Z Z	
	0.082						Z Z	Z							Z Z			X Z	Z Z	
	WVDC	25	50	100	200	500	25	50	100	200	500	50	100	200	50	100	200	50	100	200
l otto:	SIZE			1210	0			V I	1812			D 1	1825		/ 1	2220	7		2225	
Letter Max. Thickness	A 0.33 (0.013)	0.5 (0.0)	56 22) ((0.71 (0.028)	G 0.90 (0.035)	0.0)	94	1.02 (0.040)	1.27 (0.050)	1.4	40	P 1.52 (0.060)	1.78 (0.070)		29	2.54 (0.100)	2.79 (0.110)		
			Р	PAPER								EMBO	SSED							

RF/Microwave C0G (NP0) Capacitors (RoHS)



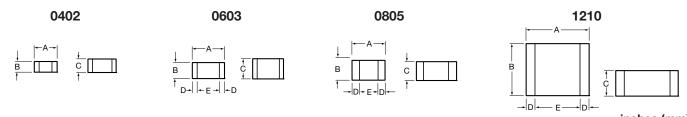
Ultra Low ESR, "U" Series, C0G (NP0) Chip Capacitors

GENERAL INFORMATION

"U" Series capacitors are COG (NP0) chip capacitors specially designed for "Ultra" low ESR for applications in the communications market. Max ESR and effective capacitance

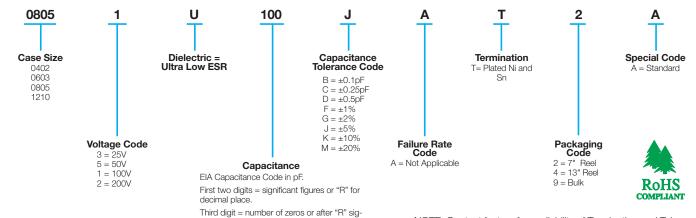
are met on each value producing lot to lot uniformity. Sizes available are EIA chip sizes 0402, 0603, 0805, and 1210

DIMENSIONS: inches (millimeters)



inches (mm) Size В C D 0402 0.039±0.004 (1.00±0.1) 0.020±0.004 (0.50±0.1) 0.024 (0.6) max N/A N/A 0603 0.060±0.010 (1.52±0.25) 0.030±0.010 (0.76±0.25) 0.036 (0.91) max 0.010±0.005 (0.25±0.13) 0.030 (0.76) min 0805 0.079±0.008 (2.01±0.2) 0.049±0.008 (1.25±0.2) 0.040±0.005 (1.02±0.127) 0.020±0.010 (0.51±0.255) 0.020 (0.51) min 1210 0.126±0.008 (3.2±0.2) 0.098±0.008 (2.49±0.2) 0.050±0.005 (1.27±0.127) 0.025±0.015 (0.635±0.381) 0.040 (1.02) min

HOW TO ORDER



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

ELECTRICAL CHARACTERISTICS

Capacitance Values and Tolerances:

Size 0402 - 0.2 pF to 22 pF @ 1 MHz Size 0603 - 1.0 pF to 100 pF @ 1 MHz Size 0805 - 1.6 pF to 160 pF @ 1 MHz Size 1210 - 2.4 pF to 1000 pF @ 1 MHz

Temperature Coefficient of Capacitance (TC):

0±30 ppm/°C (-55° to +125°C)

Insulation Resistance (IR):

 $10^{12}~\Omega$ min. @ 25°C and rated WVDC $10^{11}~\Omega$ min. @ 125°C and rated WVDC

Working Voltage (WVDC):

 Size
 Working Voltage

 0402
 50, 25 WVDC

 0603
 200, 100, 50 WVDC

 0805
 200, 100 WVDC

 1210
 200, 100 WVDC

Dielectric Working Voltage (DWV):

250% of rated WVDC

Equivalent Series Resistance Typical (ESR):

0402 - See Performance Curve, page 9
0603 - See Performance Curve, page 9
0805 - See Performance Curve, page 9
1210 - See Performance Curve, page 9

Marking: Laser marking EIA J marking standard (except 0603) (capacitance code and tolerance upon request).

MILITARY SPECIFICATIONS

Meets or exceeds the requirements of MIL-C-55681



RF/Microwave C0G (NP0) Capacitors (RoHS)



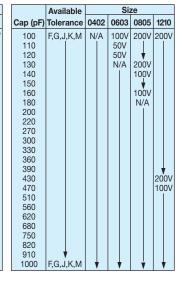
Ultra Low ESR, "U" Series, C0G (NP0) Chip Capacitors

CAPACITANCE RANGE

	Available		Size			
Cap (pF)	Tolerance	0402	0603	0805	1210	
0.2	B,C	50V	N/A	N/A	N/A	
0.3						
0.4						
0.5	B,C					
0.6	B,C,D					
0.7	l T					
0.8	↓					
0.9	B,Č,D	₩	₩	₩	₩	
	B,C,D	↓	V	V	•	

	Available	Size								
Cap (pF)	Tolerance	0402	0603	0805	1210					
1.0	B,C,D	50V	200V	200V	200V					
1.1										
1.2 1.3										
1.3										
1.5										
1.6										
1.7										
1.8										
1.9 2.0										
2.1										
2.2										
2.4										
2.7										
3.0 3.3										
3.6										
3.9										
4.3										
4.7										
5.1										
5.6 6.2	B,C,D									
6.8	B,C,J,K,M	•	•		*					

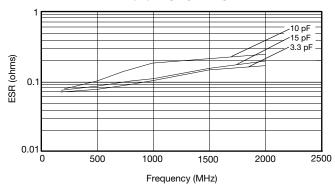
Cap (pF) Tolerance 0402 0603 080	
8.2	0V 200\
11	



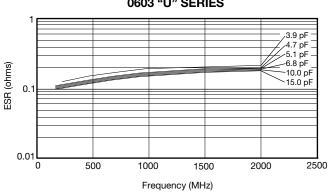
RoHS

ULTRA LOW ESR, "U" SERIES

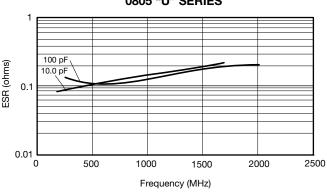
TYPICAL ESR vs. FREQUENCY 0402 "U" SERIES



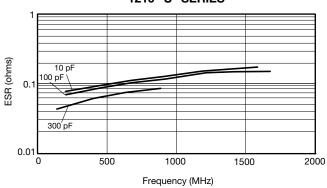
TYPICAL ESR vs. FREQUENCY 0603 "U" SERIES



TYPICAL ESR vs. FREQUENCY 0805 "U" SERIES



TYPICAL ESR vs. FREQUENCY 1210 "U" SERIES



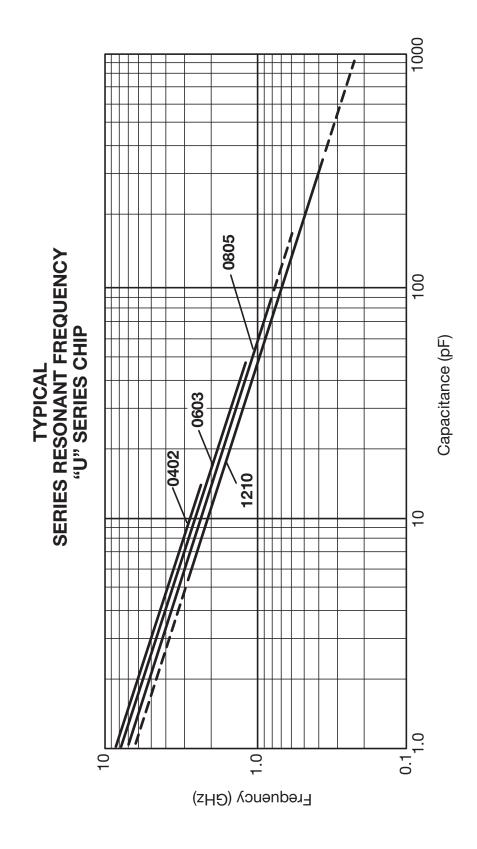
ESR Measured on the Boonton 34A



RF/Microwave C0G (NP0) Capacitors



Ultra Low ESR, "U" Series, C0G (NP0) Chip Capacitors



RF/Microwave C0G (NP0) Capacitors (Sn/Pb)



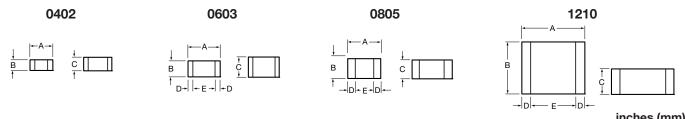
Ultra Low ESR, "U" Series, C0G (NP0) Chip Capacitors

GENERAL INFORMATION

"U" Series capacitors are COG (NPO) chip capacitors specially designed for "Ultra" low ESR for applications in the communications market. Max ESR and effective capacitance

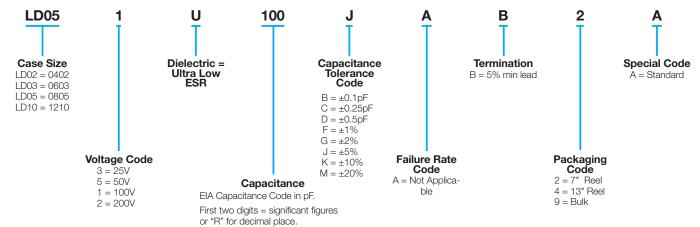
are met on each value producing lot to lot uniformity. Sizes available are EIA chip sizes 0402, 0603, 0805, and 1210.

DIMENSIONS: inches (millimeters)



					mones (mm)
Size	Α	В	С	D	E
0402	0.039±0.004 (1.00±0.1)	0.020±0.004 (0.50±0.1)	0.024 (0.6) max	N/A	N/A
0603	0.060±0.010 (1.52±0.25)	0.030±0.010 (0.76±0.25)	0.036 (0.91) max	0.010±0.005 (0.25±0.13)	0.030 (0.76) min
0805	0.079±0.008 (2.01±0.2)	0.049±0.008 (1.25±0.2)	0.040±0.005 (1.02±0.127)	0.020±0.010 (0.51±0.254)	0.020 (0.51) min
1210	0.126±0.008 (3.2±0.2)	0.098±0.008 (2.49±0.2)	0.050±0.005 (1.27±0.127)	0.025±0.015 (0.635±0.381)	0.040 (1.02) min

HOW TO ORDER



Third digit = number of zeros or after

"R" significant figures.

Not RoHS Compliant

ELECTRICAL CHARACTERISTICS

Capacitance Values and Tolerances:

Size 0402 - 0.2 pF to 22 pF @ 1 MHz Size 0603 - 1.0 pF to 100 pF @ 1 MHz Size 0805 - 1.6 pF to 160 pF @ 1 MHz Size 1210 - 2.4 pF to 1000 pF @ 1 MHz

Temperature Coefficient of Capacitance (TC):

0±30 ppm/°C (-55° to +125°C)

Insulation Resistance (IR):

 $10^{12}~\Omega$ min. @ 25°C and rated WVDC $10^{11}~\Omega$ min. @ 125°C and rated WVDC

Working Voltage (WVDC):

 Size
 Working Voltage

 0402
 - 50, 25 WVDC

 0603
 - 200, 100, 50 WVDC

 0805
 - 200, 100 WVDC

 1210
 - 200, 100 WVDC

Dielectric Working Voltage (DWV):

250% of rated WVDC

Equivalent Series Resistance Typical (ESR):

0402 - See Performance Curve, page 12 0603 - See Performance Curve, page 12 0805 - See Performance Curve, page 12 1210 - See Performance Curve, page 12

Marking: Laser marking EIA J marking standard (except 0603) (capacitance code and tolerance upon request).

MILITARY SPECIFICATIONS

Meets or exceeds the requirements of MIL-C-55681



RF/Microwave C0G (NP0) Capacitors (Sn/Pb)



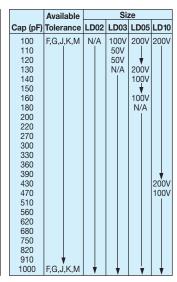
Ultra Low ESR, "U" Series, C0G (NP0) Chip Capacitors

CAPACITANCE RANGE

Available		Siz	<u> </u>	
Tolerance	LD02	LD03	LD05	LD10
B,C	50V	N/A	N/A	N/A
l ì				
B,C				
B,C,D				
B,Ċ,D	₩	▼	▼	₩
	B,C B,C B,C,D	B,C 50V B,C B,C,D	B,C 50V N/A B,C B,C,D	B,C B,C,D

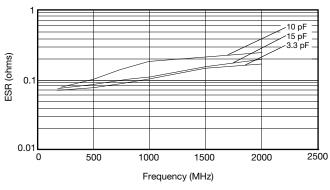
	Available	Size							
Cap (pF)	Tolerance	LD02	LD03	LD05	LD10				
1.0	B,C,D	50V	200V	200V	200V				
1.1									
1.2									
1.3 1.4									
1.5									
1.6									
1.7									
1.8									
1.9									
2.0 2.1									
2.2									
2.4									
2.7									
3.0									
3.3									
3.6 3.9									
4.3									
4.7									
5.1									
5.6	*								
6.2	B,C,D	ļ							
6.8	B,C,J,K,M	7	1	V	•				

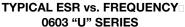
	Available	Size							
Cap (pF)	Tolerance	LD02	LD03	LD05	LD10				
Cap (pF) 7.5 8.2 9.1 10 11 12 13 15 18 20 22 24 27 30 33 36 39 43 47 51 56 68 75 82	Tolerance B,C,J,K,M B,C,J,K,M F,G,J,K,M	50V V 50V N/A		200V					
91		V	V	•	V				

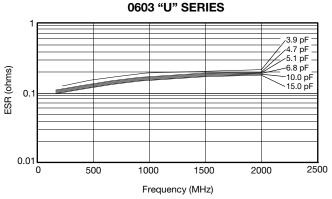


ULTRA LOW ESR, "U" SERIES

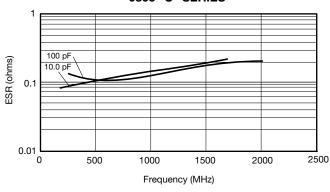
TYPICAL ESR vs. FREQUENCY 0402 "U" SERIES



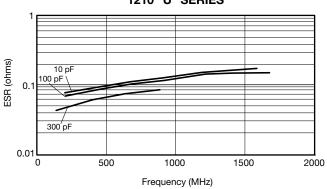




TYPICAL ESR vs. FREQUENCY 0805 "U" SERIES



TYPICAL ESR vs. FREQUENCY 1210 "U" SERIES



ESR Measured on the Boonton 34A



Designer Kits

Communication Kits "U" Series



"U" SERIES KITS

0402

	Kit 5000 UZ														
Cap. Value pF	Tolerance	Cap. Value pF	Tolerance												
0.5 1.0 1.5 1.8	D (: 0.1 mD)	4.7 5.6 6.8 8.2	B (±0.1pF)												
2.2 2.4 3.0 3.6	B (±0.1pF)	10.0 12.0 15.0	J (±5%)												

^{***25} each of 15 values

0603

	Kit 40	00 UZ	
Cap. Value pF	Tolerance	Cap. Value pF	Tolerance
1.0 1.2 1.5 1.8 2.0 2.4 2.7 3.0 3.3 3.9 4.7 5.6	B (±0.1pF)	6.8 7.5 8.2 10.0 12.0 15.0 18.0 22.0 27.0 33.0 39.0 47.0	B (±0.1pF)

^{***25} each of 24 values

0805

	Kit 30	00 UZ	
Cap. Value pF	Tolerance	Cap. Value pF	Tolerance
1.0 1.5 2.2 2.4 2.7 3.0 3.3 3.9 4.7 5.6 7.5 8.2 9.1 10.0 12.0	B (±0.1pF)	15.0 18.0 22.0 24.0 27.0 33.0 36.0 39.0 47.0 56.0 68.0 82.0 100.0 130.0 160.0	J (±5%)

^{***25} each of 30 values

1210

	Kit 35	00 UZ	
Cap. Value pF	Tolerance	Cap. Value pF	Tolerance
2.2 2.7 4.7 5.1 6.8 8.2 9.1	B (±0.1pF)	36.0 39.0 47.0 51.0 56.0 68.0 82.0	
10.0 13.0 15.0 18.0 20.0 24.0 27.0 30.0	J (±5%)	100.0 120.0 130.0 240.0 300.0 390.0 470.0 680.0	J (±5%)

^{***25} each of 30 values

X8R/X8L Dielectric







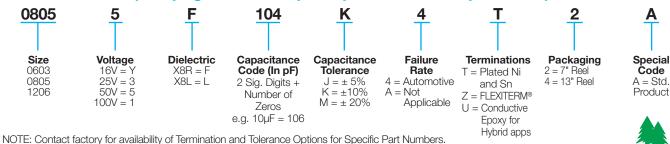
AVX has developed a range of multilayer ceramic capacitors designed for use in applications up to 150°C. These capacitors are manufactured with an X8R and an X8L dielectric material. X8R material has capacitance variation of ±15% between -55°C and +150°C. The X8L material has capacitance variation of $\pm 15\%$ between -55°C to 125°C and $\pm 15/-40\%$ from ± 125 °C to ± 150 °C.

The need for X8R and X8L performance has been driven by customer requirements for parts that operate at elevated temperatures. They provide a highly reliable capacitor with low loss and stable capacitance over temperature.

They are ideal for automotive under the hood sensors, and various industrial applications. Typical industrial application would be drilling monitoring system. They can also be used as bulk capacitors for high temperature camera modules.

Both X8R and X8L dielectric capacitors are automotive AEC-Q200 qualified. Optional termination systems, tin, FLEXITERM® and conductive epoxy for hybrid applications are available. Providing this series with our FLEXITERM® termination system provides further advantage to customers by way of enhanced resistance to both, temperature cycling and mechanical damage.

PART NUMBER (see page 2 for complete part number explanation)





				X8 I	R											X8L						
5	SIZE	(603		08	05		1206			SIZE			0603			0805			12	06	
	WVDC	25V		50V	25V	50V	25	V 50V			WVI	DC	25V	50V	100V	25V	50V	100V	16V	25V	50V	100V
331	Cap 330	G		G	J	J				331	Cap	330		G	G		J	J				
471	(pF) 470	G		G	J	J				471	(pF)	470		G	G		J	J				
681	680	G		G	J	J				681		680		G	G		J	J				
102	1000	G		G	J	J	J	J		102		1000		G	G		J	J				
152	1500	G		G	J	J	J	J		152		1500		G	G		J	J			J	J
222	2200	G		G	J	J	J			222		2200		G	G		J	J			J	J
332	3300	G		G	J	J	J			332		3300		G	G		J	J			J	J
472	4700	G		G	J	J	J			472		4700		G	G		J	J			J	J
682	6800	G		G	J	J	J	J		682		6800		G	G		J	J			J	J
103	Cap 0.01	G		G	J	J	J	J		103		0.01		G	G		J	J			J	J
153	(μF) 0.015	G		G	J	J	J	J		153		0.015	G	G		J	J	J			J	J
223	0.022	G		G	J	J	J	J		223		0.022	G	G		J	J	J			J	J
333	0.033	G		G	J	J	J			333		0.033	G	G		J	J	N			J	J
473	0.047	G		G	J	J	J			473		0.047	G	G		J	J	N			J	J
683	0.068	G			N	N	M			683		0.068	G	G		J	J				J	J
104	0.1				N	N	М			104		0.1	G	G		J	J				J	М
154	0.15				N	N	М			154		0.15				J	N		J	J	J	Q
224	0.22				N		M			224		0.22				N	N		J	J	J	Q
334	0.33						М			334		0.33				N			J	М	Р	Q
474 684	0.47		_				М		_	474		0.47				N			М	М	Р	
105	0.68		_						_	684 105		0.68					1		M			
105	WVDC	25V		50V	25V	50V	25'	V 50V	_	105	WVI	1	25V	50V	100V	25V	50V	100V	16V	25V	50V	100V
				SUV			25		_				20V		1007	23V		1000	100			1000
	SIZE		603		08	05		1206			SIZE			0603			0805			12	U6	
Lette	r A			E	(à	J	K	N	1	N	F		Q		X	Υ		Z			C-Q200
Max.	0.33	0.	56	0.71	0.9	90 0	.94	1.02	1.2	27	1.40	1.3	52	1.78	2.	.29	2.54	2	.79		Qua	alified
Thickne	ess (0.013)			(0.028	3) (0.0		037)	(0.040)	(0.0)	50)	(0.055)	(0.0	060)	(0.070)		090)	(0.100		110)			
				PAPER	 R			EMBOSSED														



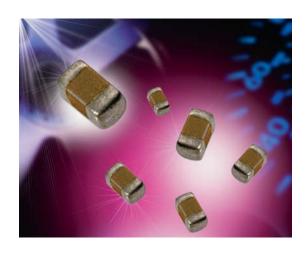
X8R/X8L Dielectric

General Specifications

APPLICATIONS FOR X8R AND X8L CAPACITORS

- All market sectors with a 150°C requirement
- Automotive on engine applications
- Oil exploration applications
- Hybrid automotive applications
 - Battery control
 - Inverter / converter circuits
 - Motor control applications
 - Water pump
- Hybrid commercial applications
 - Emergency circuits
 - Sensors
 - Temperature regulation



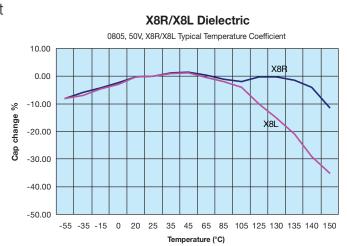


ADVANTAGES OF X8R AND X8L MLC CAPACITORS

- Both ranges are qualified to the highest automotive AEC-Q200 standards
- Excellent reliability compared to other capacitor technologies
- RoHS compliant
- Low ESR / ESL compared to other technologies
- Tin solder finish
- FLEXITERM® available
- Epoxy termination for hybrid available
- 100V range available

ENGINEERING TOOLS FOR HIGH VOLTAGE MLC CAPACITORS

- Samples
- Technical Articles
- Application Engineering
- Application Support





X8R/X8L Dielectric



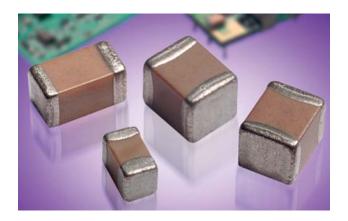
Specifications and Test Methods

Parame		X8R/X8L Specification Limits	Measuring					
Operating Temp		-55°C to +150°C	Temperature Cycle Chamber Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V					
Capac	itance	Within specified tolerance						
Dissipation	on Factor	\leq 2.5% for \geq 50V DC rating \leq 3.5% for 25V DC and 16V DC rating	_					
Insulation I	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roo					
Dielectric	Strength	No breakdown or visual defects	Charge device with 300 1-5 seconds, w/charge limited to 50 Note: Charge device voltage for 50	and discharge current 0 mA (max) with 150% of rated 00V devices.				
	Appearance	No defects	Deflectio					
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3	-				
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)	V	1mm/sec				
	Insulation Resistance	≥ Initial Value x 0.3	90 r	nm —				
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.					
	Appearance	No defects, <25% leaching of either end terminal						
	Capacitance	≤ ±7.5%						
	Variation Dissipation		Dip device in eutectic :					
Resistance to Solder Heat	Factor	Factor Meets Initial Values (As Above)		temperature for 24 ± 2 g electrical properties.				
Solder Heat	Insulation Resistance	Meets Initial Values (As Above)	Tiodis belore measurin	g electrical properties.				
	Dielectric Strength	Meets Initial Values (As Above)						
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes				
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes				
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes				
OHOUR	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes				
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles ar 24 ± 2 hours at room					
	Appearance	No visual defects		3311 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3				
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 test chamber set					
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	urs (+48, -0)				
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test ch at room temperatu					
	Dielectric Strength	Meets Initial Values (As Above)	before me	easuring.				
	Appearance	No visual defects	Store in a test chamb	or oot at 9500 : 000/				
	Capacitance Variation	≤ ±12.5%	85% ± 5% relative hu	midity for 1000 hours				
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from cham	and humidity for				
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours be	Tore measuring.				



General Specifications





X7R formulations are called "temperature stable" ceramics and fall into EIA Class II materials. X7R is the most popular of these intermediate dielectric constant materials. Its temperature variation of capacitance is within $\pm 15\%$ from -55°C to +125°C. This capacitance change is non-linear.

Capacitance for X7R varies under the influence of electrical operating conditions such as voltage and frequency.

X7R dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

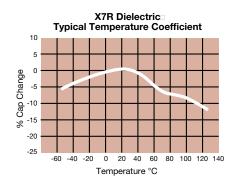
**See FLEXITERM® X7R section

RoHS

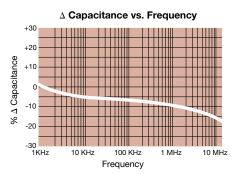
PART NUMBER (see page 2 for complete part number explanation)

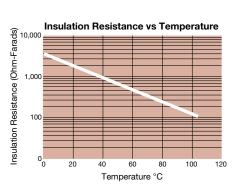
0805	<u>5</u>	<u>c</u>	103	<u>M</u>	A	<u>T</u>	<u>2</u>	<u>A</u>
	Voltage 4V = 4 6.3V = 6 10V = Z 16V = Y 25V = 3	Dielectric X7R = C	Capacitance Code (In pF) 2 Sig. Digits + Number of Zeros	Capacitance Tolerance $J = \pm 5\%^*$ $K = \pm 10\%$ $M = \pm 20\%$	Failure Rate A = Not Applicable	Terminations T = Plated Ni and Sn 7 = Gold Plated* Z = FLEXITERM®**	Packaging 2 = 7" Reel 4 = 13" Reel 7 = Bulk Cass. 9 = Bulk	Special Code A = Std. Product
	50V = 5 100V = 1 200V = 2			*≤1µF only, contact factory for additional values		*Optional termination	Contact Factory For	

NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.



500V = 7





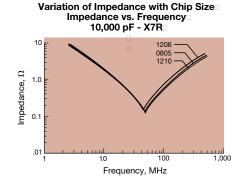
Multiples

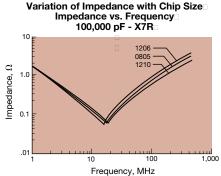
Impedance vs. Frequency
1,000 pF vs. 10,000 pF - X7R
0805

10.00

10.00 pF
10,000 pF
10,000 pF
10,000 pF
10,000 pF
10,000 pF
10,000 pF

Variation of Impedance with Cap Value









Specifications and Test Methods

Parame		X7R Specification Limits	Measuring	Conditions					
Operating Temp		-55°C to +125°C	Temperature C	ycle Chamber					
Capac		Within specified tolerance ≤ 2.5% for ≥ 50V DC rating ≤ 3.0% for 25V DC rating ≤ 3.5% for 25V and 16V DC rating ≤ 5.0% for ≤ 10V DC rating	Freq.: 1.0 k Voltage: 1.0						
Insulation I	Resistance	100,000M Ω or 1000M Ω - μF, whichever is less	Charge device with 120 ± 5 secs @ roo	om temp/humidity					
Dielectric	Strength	No breakdown or visual defects	Charge device with 300 1-5 seconds, w/charge limited to 50 Note: Charge device voltage for 50	and discharge current) mA (max) with 150% of rated					
	Appearance	No defects	Deflection: 2mm						
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3						
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)	V						
	Insulation Resistance	≥ Initial Value x 0.3	90 n						
Solder	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at 230 \pm 5 for 5.0 \pm 0.5 seconds						
	Appearance	No defects, <25% leaching of either end terminal	•						
	Capacitance	≤ ±7.5%							
	Variation		Dip device in eutectic s	solder at 260°C for 60					
Resistance to	Dissipation Factor	Meets Initial Values (As Above)	seconds. Store at room						
Solder Heat	Insulation	Meets Initial Values (As Above)	hours before measuring	g electrical properties.					
	Resistance Dielectric	Meets Initial Values (As Above)							
	Strength Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes					
	Capacitance		·						
	Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes					
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes					
OHOOK	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes					
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and 24 ± 2 hours at room						
	Appearance	No visual defects		.cporataro					
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 test chamber set						
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	ırs (+48, -0)					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test ch at room temperatur	e for 24 ± 2 hours					
	Dielectric	Meets Initial Values (As Above)	before me	easuring.					
	Strength	,							
	Appearance	No visual defects	Store in a test chambe	er set at 85°C ± 2°C/					
	Capacitance Variation	≤ ±12.5%	85% ± 5% relative hur						
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated						
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from cham room temperature	and humidity for					
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours bet	iore measuring.					







PREFERRED SIZES ARE SHADED

				•								ш														П				
SIZI	E	0101		0201			0402	2				0603	}						0805	5						12	206			
Solder	ina	Reflow Only	Re	flow C	nlv	Ret	flow/V	Vave			Re	flow/V	Vave					Ref	low/V	Vave						Refloy	v/Wav	e.		
Packag		Paper/Embossed	_	II Pap			All Pap					All Pap								ossed	1						mboss			
(L) Length	mm (in.)	0.40 ± 0.02 (0.016 ± 0.0008)	0.	.60 ± 0.	.03	1	$.00 \pm 0$ $.040 \pm 0$.10			1	$.60 \pm 0$ $.63 \pm 0$.15					2.	01 ± 0. 179 ± 0.	.20	<u> </u>					3.20	± 0.20 ± 0.008			
(W) Width	mm	0.20 ± 0.02		$.30 \pm 0.$			$.50 \pm 0$.81 ± 0							25 ± 0								± 0.20	,		
(VV) VVIGUT	(in.)	(0.008 ± 0.0008))11 ± 0.			020 ± 0					032 ± 0							149 ± 0.								± 0.008)		
(t) Terminal	mm (in.)	0.20 ± 0.02 (0.008 ± 0.0008)		.15 ± 0. 106 ± 0.			.25 ± 0 010 ± 0					.35 ± 0 014 ± 0							50 ± 0. 20 ± 0.								± 0.25 ± 0.010)		
	WVDC	10	10	16	25	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
Cap	100	A	А	Α	А																									
(pF)	150 220	A A	A A	A	A			С																						
	330	А	Α	Α	А			С					G	G	G		J	J	J	J	J	J								K
	470	A	Α	Α				С					G	G	G	l	J	J	J	J	J	J								K
	680	A	A	A				С					G	G	G	_	J	J	J	J	J	J								K
	1000 1500	A	A A	Α				C					G	G	G		J	J	J	J	J	J		J	J	J	J	J	J	K M
	2200		A					C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
	3300		Α				С	С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М
	4700		A			_	C	С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
Cap	6800 0.010		A			C	C		_		-	-	G	G		 	J	J	J	J	J	J	_	J	J	J	J	J	J	P
(µF	0.015		^			C						G	G				J	J	J	J	J	J		J	J	J	J	J	M	
de.	0.022					C	С					G	G				J	Ĵ	J	J	J	N		Ĵ	Ĵ	J	Ĵ	J	М	
	0.033					С	С					G	G				J	J	J	J	N			J	J	J	J	J	М	
	0.047					С	C				G	G	G				J	J	J	J	N			J	J	J	J	J	M	
	0.068		-			C	C		-	G	G	G	G		-	\vdash	J	J	J	J	N		_	J	J	J	J	M	P	
	0.15					U			G	G	u	u	u				J	J	J	l N	N			J	J	J	J	Q	-	
	0.22								G	G		J*					J	Ĵ	N	N	N			Ĵ	Ĵ	Ĵ	Ĵ	Q		
	0.33																N	N	N	N	N			J	J	М	Р	Q		
	0.47											J*					N	N	N	N	N			М	M	M	P	Q		
	0.68		-			-				J*	J*					-	N N	N N	N N	N				M	M	Q	Q	Q		
	1.5									0	0						IN	14	IN	14				P	Q	Q	\ \ \	Q		
	2.2								J*										P*					Q	Q	Q		Q*		
"	3.3																													
	4.7															P*	P*	P*						Q*	Q*	Q*	Q*			
	10 22		-			-								-		P^	P*						Q*	Q* Q*	Q*	Q*				_
	47																						Q	Q						
	100																													
	WVDC	10	10	16	25	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
	SIZE	0101		0201			0402	2				0603	3						0805	5						12	206			
1,,44				_		^		- 1		17		h 4					<u> </u>		^		V		\/		7					
Letter Max.	0.33	C 3 0.56		E .71		G).90		J 0.94		1.02		1.2		1.4			52		Q .78		X 2.29		Y 2.54		2.79)				
Thickness				028)		.90 .035)	1	0.94)	(0.04		(0.05		(0.0			060)		070)		2.29).090)		2.54 0.100))	(0.11					
monness	(0.01	(0.022)	,	PER	0)	.000)		0.007	/	(0.04	~ <i>)</i>	10.00	,0,	(0.0	.00)	,		DSSE		10	,,,,,,,		0.100	7	(0.11	<i>-</i> /				
			1 / ٦	L 1													-1410													

^{*}Optional Specifications - Contact factory





PREFERRED SIZES ARE SHADED

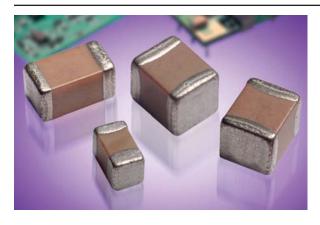
SIZ	Έ				1210					18	312		18	25		22	220		22	25
Solde	ring			F	Reflow On	ly				Reflo	w Only		Reflow	v Only		Reflo	w Only		Reflov	w Only
Packa	ging				er/Embos						bossed		All Emb				bossed			bossed
(L) Length	mm (in.)				3.20 ± 0.20 .126 ± 0.00						± 0.30 ± 0.012)		4.50 ± (0.177 ±				± 0.40 ± 0.016)			± 0.25 + 0.010)
(W) Width	mm				2.50 ± 0.20)				3.20	± 0.20		6.40 ±	0.40		5.00	± 0.40		(0.225 ± 0.010) 6.35 ± 0.25	
(VV) VVIGITI	(in.) mm				0.098 ± 0.00 0.50 ± 0.25						± 0.008) ± 0.36		(0.252 ±				± 0.016) ± 0.39			± 0.010) ± 0.39
(t) Terminal	(in.)				0.30 ± 0.20						± 0.00 ± 0.014)		(0.024 ±				± 0.39 ± 0.015)			± 0.39 ± 0.015)
	WVDC	10	16	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100
Cap (pF)	100 150																' '	_	ا سا	l
(pr)	220																			~
	330															┌ ~))	ÎT
	470 680) <u> </u> _		4
-	1000															 	_	العرا		
	1500	J	J	J	J	J	J	М	1									t		
	2200 3300	J	J	J	J	J	J	M									\vdash			
	4700	J	J	J	J	J	J	M	l											
	6800	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	M												
Cap	0.010	J	J	J	J	J	J	M	K	K	K	K	М	М		X	X	X	М	Р
(μF	0.015 0.022	J	J	J	J	J .I	J	PQ	K K	K K	K	P	M M	M M		X	X	X	M M	P P
	0.033	J	J	J	J	J	J	Q	K	K	K	X	M	M		X	X	X	M	P
	0.047	J	J	J	J	J	J		K	K	K	Z	М	М		X	X	X	М	Р
-	0.068	J	J	J	J	J J	M		K	K	K	Z	M	M		X	X	X	M	P
	0.15	J	J	J	Ĵ	M	Z		K	K	P		M	M		X	X	X	M	P
	0.22	J	J	J	J	Р	Z		K	K	Р		М	М		X	X	X	М	Р
	0.33 0.47	J M	J M	J M	J M	Q Q			K K	M P	Х		M M	M M		X	X	X X	M M	P P
	0.68	M	M	P	X	X			M	Q			M	P		X	X	Α	M	P
	1.0	N	N	P	X	Z			М	X			М	Р		X	X		М	Р
	1.5 2.2	N X	N X	Z Z	Z Z	Z Z			Z Z	Z Z			М			X	X		M M	X
	3.3	X	X	Z	Z				Z			<u> </u>				X	Z		IVI	
	4.7	X	X	Z	Z				Z							×	Z			
	10 22	Z Z*	7*	Z*				-	-			+			Z	Z	\vdash			
	47																			
	100																			
	WVDC	10	16	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100
SIZ	<u> </u>	1210			1210					18	312		18	25		22	20		22	25
Letter	А	C E G J K				K	М		N	Р	Q		Х	Υ	Z					
Max.	0.33	0.5		0.71	0.90	0.		1.02	1.27		.40	1.52	1.78		.29	2.54	2.79	,		
Thickness	(0.013)	(0.0)	/	,	(0.035)	(0.0)37)	(0.040)	(0.050) (0.0	055)	(0.060)	(0.070)	(0.0	090)	(0.100)	(0.110))		
		3) (0.022) (0.028) (0.035) (0.037) (PAPER								EMBC	SSED									

^{*}Optional Specifications - Contact factory









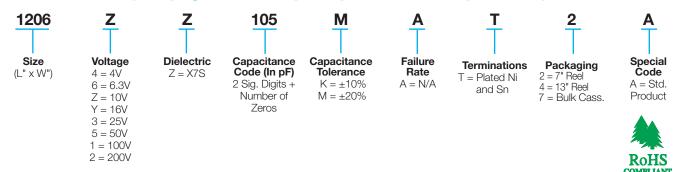
GENERAL DESCRIPTION

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitance s within $\pm 22\%$ from -55°C to ± 125 °C. This capacitance change is non-linear.

Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency.

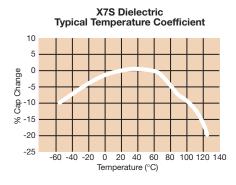
X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

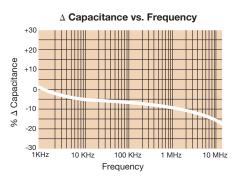
PART NUMBER (see page 2 for complete part number explanation)

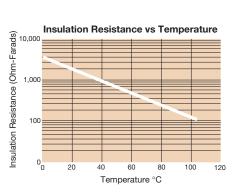


NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.

TYPICAL ELECTRICAL CHARACTERISTICS



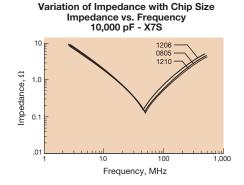


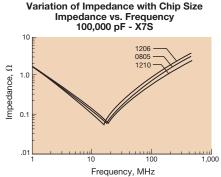


Impedance vs. Frequency 1,000 pF vs. 10,000 pF - X7S 0805

Frequency, MHz

Variation of Impedance with Cap Value









Specifications and Test Methods

	ter/Test	X7S Specification Limits	Measuring					
Operating Temp		-55°C to +125°C	Temperature C	ycle Chamber				
Capac	itance	Within specified tolerance						
		≤ 2.5% for ≥ 50V DC rating	Freq.: 1.0 k					
Dissipation	on Factor	≤ 3.0% for 25V DC rating	Voltage: 1.0					
2.00. 04.1.		≤ 3.5% for 16V DC rating	For Cap > 10 μF, (0.5Vrms @ 120Hz				
		≤ 5.0% for ≤ 10V DC rating	01 1 1 11					
Insulation	Resistance	100,000MΩ or 1000MΩ - μF,	Charge device with					
		whichever is less	120 ± 5 secs @ ro Charge device with 300					
Dielectric	Strength	No breakdown or visual defects	1-5 seconds, w/charge	and discharge current				
	Appearance	No defects	Deflection					
	Capacitance	≤ ±12%	Test Time: 3					
Resistance to	Variation	≤±12%	7	7 1mm/sec				
Flexure	Dissipation	Mosta Initial Values (As Above)						
Stresses	Factor	Meets Initial Values (As Above)						
	Insulation	 ≥ Initial Value x 0.3						
	Resistance		→ 90 r					
Solder	rability	≥ 95% of each terminal should be covered	Dip device in eutection					
		with fresh solder	for 5.0 ± 0.	5 seconds				
	Appearance	No defects, <25% leaching of either end terminal						
	Capacitance Variation	≤ ±7.5%						
	Dissipation		Dip device in eutectic :					
Resistance to	Factor	Meets Initial Values (As Above)	seconds. Store at room					
Solder Heat	Insulation		hours before measurin	g electrical properties.				
	Resistance	Meets Initial Values (As Above)						
	Dielectric	A4						
	Strength	Meets Initial Values (As Above)						
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes				
	Capacitance	≤ ±7.5%	Step 2: Room Temp ≤ 3 minutes					
	Variation		Step 2. Noom temp \(\sigma \) Thindtes					
Thermal	Dissipation	Meets Initial Values (As Above)	Step 3: +125°C ± 2° 30 ± 3 minute					
Shock	Factor Insulation	, ,	Step 3: +125°C ± 2° 30 ± 3 minutes					
	Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes				
	Dielectric		Repeat for 5 cycles ar	nd measure after				
	Strength	Meets Initial Values (As Above)	24 ± 2 hours at room					
	Appearance	No visual defects						
	Capacitance	≤ ±12.5%	Charge device with 1.5					
	Variation	2 2 12.0 / 0	test chamber set					
	Dissipation	≤ Initial Value x 2.0 (See Above)	for 1000 hoเ	urs (+48, -0)				
Load Life	Factor	= 11 maa. vanaa / 2.0 (000 / 100 / 0)	Remove from test ch	and atabilize				
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	at room temperatu					
	Dielectric	· · · · · · · · · · · · · · · · · · ·	before me					
	Strength	Meets Initial Values (As Above)	0010101111	sacarii igi				
	Appearance	No visual defects	0					
	Capacitance	≤ ±12.5%	Store in a test chamb					
	Variation	≥ ±12.070	$85\% \pm 5\%$ relative hu					
Load	Dissipation	< Initial Value x 2.0 (See Above)	(+48, -0) with rate	u voltage applied.				
Humidity	Factor	≤ Initial Value x 2.0 (See Above)	Remove from cham	her and stahilize at				
	Insulation	≥ Initial Value x 0.3 (See Above)	room temperature					
	Resistance	= 11 11 101 Valdo X 0.0 (000 / 100 Vo)	24 ± 2 hours be					
	Dielectric	Meets Initial Values (As Above)						
	Strength	1						





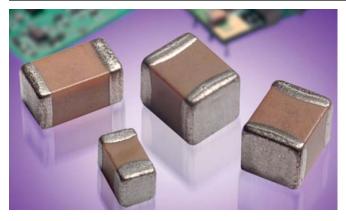
Capacitance Range

PREFERRED SIZES ARE SHADED

					ED					1						
SIZ	E	0402		0	603		0805		12	06		121	0			
Solder	ring	Reflow/W	ave	Reflo	w/Wave	Re	flow/Wave	R	eflow	/Wave	9	Reflow	Only			
Packag		All Pap	er	All	Paper	Pape	r/Embossed	Par	er/Er	nboss	ed	Paper/Em				
(L) Length	mm (in.)	1.00 ± 0. (0.040 ± 0.1	10	1.60	0 ± 0.15 3 ± 0.006)	2	.01 ± 0.20 .079 ± 0.008)	T	3.20 ±			3.20 ± (0.126 ±	0.20			
(W) Width	mm	$0.50 \pm 0.$			± 0.15		.25 ± 0.20			0.20	,	2.50 ±				
(VV) VVIGITI	(in.)	(0.020 ± 0.0)			2 ± 0.006		0.008) ± 0.008			0.008)	(0.098 ±				
(t) Terminal	mm (in)	0.25 ± 0.			± 0.15 ± 0.006)		.50 ± 0.25		0.50 ±		۸	0.50 ±				
	(in.) WVDC	(0.010 ± 0.0	000)	6.3	25	(0.0	020 ± 0.010) 4	6.3	10	50.010	100	(0.020 ± 6.3				
Cap	100	0.0		0.0	20	+	-	0.0	10	50	100	0.0				
(pF)	150															
	220							L			~>	~ ₩	~			
	330							-	<				\ ^ =			
	470 680								(_	رر	ヽレ) <u>↓</u> !			
	1000				-	+-		+	_		J		_			
	1500										مبيأ	-				
	2200										t	1				
	3300							Ť								
	4700															
	6800							\vdash			_					
Cap (µF	0.010 0.015															
(µi	0.013															
	0.033	С						\vdash			\neg					
	0.047	С														
-	0.068	С														
	0.10	С														
	0.15 0.22				G											
	0.22			G	G			+			-					
	0.47			G												
	0.68			G												
	1.0			G												
	1.5						N	Q								
	2.2 3.3				1		N N	Q		\vdash	-					
	4.7						N	Q	Q		Q					
	10						14	· ·	Q	Q	Q					
	22							T				Z				
	47															
	100							-								
	WVDC	6.3		6.3	25		4	6.3	10		100	6.3				
	SIZE	0402		0	603		0805		12	06		121	U			
Letter	А	С	Е		G	J	K	М		N		Р	Q	Х	Υ	Z
Max.	0.33	0.56	0.7		.90	0.94	1.02	1.27		1.4		1.52	1.90	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.02		035)	(0.037)	(0.040)	(0.05		(0.05		(0.060)	(0.075)	(0.090)	(0.100)	(0.110)
	,		PAPE	R								EMBC	SSED		. ,	



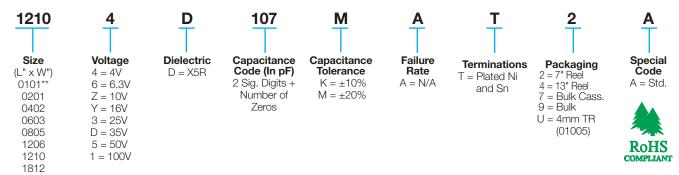
General Specifications



GENERAL DESCRIPTION

- General Purpose Dielectric for Ceramic Capacitors
- EIA Class II Dielectric
- Temperature variation of capacitance is within ±15% from -55°C to +85°C
- Well suited for decoupling and filtering applications
- Available in High Capacitance values (up to 100µF)

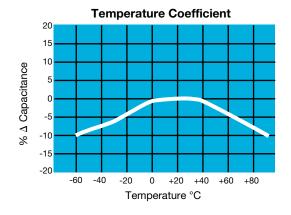
PART NUMBER (see page 2 for complete part number explanation)

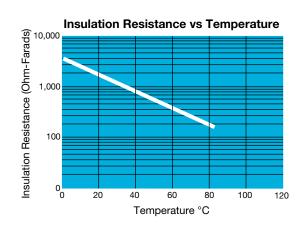


**EIA 01005

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

TYPICAL ELECTRICAL CHARACTERISTICS







Specifications and Test Methods

Parame	ter/Test	X5R Specification Limits	Measuring	
Operating Temp		-55°C to +85°C	Temperature C	ycle Chamber
Capac		Within specified tolerance ≤ 2.5% for ≥ 50V DC rating ≤ 3.0% for 25V DC rating ≤ 12.5% Max. for 16V DC rating and lower Contact Factory for DF by PN	Freq.: 1.0 k Voltage: 1.0 For Cap > 10 μF, (Vrms ± .2V
Insulation I	Resistance	10,000MΩ or 500MΩ - μ F, whichever is less	Charge device with 120 ± 5 secs @ ro	
Dielectric	Strength	No breakdown or visual defects	Charge device with 300 1-5 seconds, w/charge limited to 50	and discharge current
	Appearance	No defects	Deflection	
Resistance to	Appearance Capacitance Variation Dissipation Factor Insulation Resistance Tability Appearance Capacitance Variation Dissipation Factor Insulation Dissipation Factor Insulation Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Dissipation Factor Insulation Factor Insulation	≤ ±12%	Test Time: 3	80 seconds 7 1mm/sec
Flexure Stresses	capacitance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Capacitance Variation Dissipation Factor Insulation Resistance Capacitance Variation Dissipation Factor Insulation Pactor Insulation Factor Insulation Resistance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength	Meets Initial Values (As Above)	V	
		≥ Initial Value x 0.3	90 r	
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.	
		No defects, <25% leaching of either end terminal		
	Resistance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Capacitance Variation Dissipation Factor Insulation Resistance	≤ ±7.5%	Din dovice in outcetic	and ar at 06000 for 60
Resistance to	Insulation Pactor Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric	Meets Initial Values (As Above)	Dip device in eutectic seconds. Store at room	temperature for 24 ± 2
Solder Heat	capacitance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric	Meets Initial Values (As Above)	hours before measurin	g electrical properties.
	capacitance Capacitance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric	Meets Initial Values (As Above)		
		No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes
Thermal Shock		Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes
Snock		Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
		Meets Initial Values (As Above)	Repeat for 5 cycles ar 24 ± 2 hours at room	
		No visual defects	Charge device with	
	Variation	≤ ±12.5%	test chamber set at 85°((+48, -0). Note: Contact	ct factory for *optional
Load Life	_ '	≤ Initial Value x 2.0 (See Above)	specification part numl < 1.5X rate	
		≥ Initial Value x 0.3 (See Above)	Remove from test ch	namber and stabilize
	Strength	Meets Initial Values (As Above)	at room temperatu before me	
	Appearance	No visual defects	Ctoro in a toot about	or not at 9500 : 000/
	Appearance Capacitance Variation Dissipation Factor Insulation Pactor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Pactor	≤ ±12.5%	Store in a test chamb 85% ± 5% relative hu	midity for 1000 hours
Load Humidity	Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rate	
			Remove from cham	Der and Stadilize at
	Resistance	≥ Initial Value x 0.3 (See Above)	room temperature 24 ± 2 hours be	







PREFERRED SIZES ARE SHADED

Cas	e Size	01	01*			0201					04	02						0603							0805			
Solo	dering	Reflo	w Only		Re	eflow O	nly				Reflow	/Wave	;				Ret	flow/W	ave					Re	flow/W	ave		
Pack	kaging	Paper/E	mbossed		P	All Pape	er				All P	aper					Α	All Pape	er					Pape	r/Emb	ossed		
(L) Length	mm	0.40	± 0.02			.60 ± 0.0						£ 0.10						.60 ± 0.1							.01 ± 0.2			
(W) Width	(in.) mm		± 0.0008) ± 0.02	_		0.24 ± 0.0 0.30 ± 0.0			\vdash		0.040 =				_			063 ± 0.0				_			079 ± 0.0			
(VV) VVIGUT	(in.)	(0.008 :	± 0.0008			.30 ± 0.0)11 ± 0.0					(0.020 :							0.01 ± 0.10							.20 ± 0.2 0.0 ± 0.0			
(t) Terminal	mm 6- \		± 0.04			.15 ± 0.0					0.25 :							$.35 \pm 0.1$.50 ± 0.2			
Vol	(in.)	6.3	± 0.016)	4	6.3	006 ± 0.0	16	25	4	6.3	(0.010 :	16	25	50	4	6.3	10.0	014 ± 0.0	25	35	50	4	6.3	10	020 ± 0.0	25	35	50
Cap (pF)	100 101	0.0	В	· ·	0.0	10	10	A	H	0.0	10	10	20	- 00	<u> </u>	0.0	10	10	20	- 00	- 00	<u> </u>	0.0	10	10	20	- 00	
oup (pr)	150 151		В					A																				
	220 221		В					Α						С														
	330 331		В					Α						С														
	470 471		В					Α						С														
	680 681		В					Α						С														
	1000 102		В				Α	Α						С														
	1500 152	В	В				A	A	<u> </u>					С														
	2200 222	В	В			A	A	A	<u> </u>					С														
	3300 332	В	В	_		A	A	A	<u> </u>				_	С	_						^	_						
	4700 472 6800 682	B B	B B	_		A A	A	A	<u> </u>				C		├						G G	_						
Cap (µF)	0.01 103	В	В			A	A	A	\vdash				С		_				G	G	G	_						
Сар (µг)	0.015 153	В	D			А	A	А	\vdash				C		-				G	G	G	_						
	0.013 133	В		_	Α				\vdash			С	C		_				G	G	G	_						N
	0.033 333	В		-	А				┢			С	0		-				G	G	G	_						N
	0.047 473	В			Α				\vdash			С	С						G	G	G							N
-	0.068 683	В		\vdash					\vdash			С			\vdash				G	_	G							N
	0.1 104	В			Α	Α					С	С	С	С					G	G	G					N	N	N
	0.15 154																		G							N	N	
	0.22 224	В		Α	Α	Α				С	С	С						G	G							N	N	N
	0.33 334																	G	G							N		
	0.47 474			Α	Α				С	С	С	С						G	J							N	Р	Р
	0.68 684																	G								N		
	1.0 105			Α	Α				С	С	С	С			G	G	G	G	J	G	G				N	N	Р	Р
	1.5 155									-	-																	-
	2.2 225			А	А				С	С	С				G	G	J	J	J				NI.	N	N	N	Р	Р
	3.3 335 4.7 475	<u> </u>								Г					J	J	J	J G				NI.	N	N	NI.	NI.	Р	Р
	4.7 475 10 106	-		_					E E	E					J K	J	J	G				N N	N N	N N	N N	N P	P	P
	22 226	 								E					K	K	J					N N	N N	IN P	N P	-		
	47 476	<u> </u>		 					\vdash			-			- 1	-17						P	P	-	-			_
	100 107	 		\vdash			\vdash	\vdash	\vdash						\vdash							P				\vdash		_
Vol	Itage:	6.3	10	4	6.3	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	35	50	4	6.3	10	16	25	35	50
	e Size	_	01*	0201						<u> </u>	04		<u> </u>	<u> </u>				0603							0805			

	Letter	A	В	С	E	G	J	K	М	N	Р	Q	X	Υ	Z
	Max.	0.33	0.22	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Th	ickness	(0.013)	(0.009)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
				PAPER						Е	MBOSSE	D			

NOTE: Contact factory for non-specified capacitance values

*EIA 01005







PREFERRED SIZES ARE SHADED

Case Size					206							1210							1812			
Soldering					v/Wav							flow O						Re	eflow O	nly		
Packaging			Р	aper/E	mboss	sed					Pape	r/Embo	ossed					All	Embos	sed		
(L) Length mm (in.)					± 0.20 ± 0.008)							3.20 ± 0.1 126 ± 0.1							.50 ± 0.3			
(W) Width mm				1.60	± 0.20						- 1	2.50 ± 0.1	20					3	.20 ± 0.2	.0		
(in.) (t) Terminal mm					± 0.008) ± 0.25				<u> </u>		(0.	0.098 ± 0.00	008)			<u> </u>			126 ± 0.0			
(i) Terrifia fin.)					± 0.25 ± 0.010)							020 ± 0.0							.01 ± 0.3)24 ± 0.0			
Voltage:	4	6.3	10	16	25	35	50	100	4	6.3	10	16	25	35	50	4	6.3	10	16	25	35	50
Cap (pF) 100 101																						
150 151																						
220 221									\vdash							_						
330 331	_								<u> </u>							<u> </u>						
470 471 680 681	_								\vdash							\vdash						
1000 102	_								\vdash							\vdash						
1500 152	\vdash								\vdash							\vdash						
2200 222									\vdash							\vdash						
3300 332																						
4700 472																						
6800 682																						
Cap (µF) 0.01 103																						
0.015 153																						
0.022 223									<u> </u>							<u> </u>						
0.033 333 0.047 473									<u> </u>							<u> </u>						
0.047 473									\vdash							\vdash						
0.000 000	_								\vdash							\vdash						
0.15 154									\vdash							\vdash						
0.22 224									\vdash							\vdash						
0.33 334																						
0.47 474					Q	Q								Χ	Χ							
0.68 684																						
1.0 105					Q	Q	Q	Q					Χ	Χ	Χ							
1.5 155																						
2.2 225			Q	Q	Q	Q	Q	Q	<u> </u>				Х	Z	Z	_						
3.3 335 4.7 475	_	Q	Q Q	^	Q	Q	Q	V	<u> </u>		Q	^	Z	Z	Z	<u> </u>						
10 106	Q Q	Q	Q	Q	Q	Q	X	Х	\vdash	Χ	X	Q Z	Z	Z	Z	\vdash				Z		
22 226	Q	Q	Q	Q	Q	Q	٨		Z	Z	Z	Z	Z			\vdash				L		
47 476	Q	Q	Q	Q	Q.				Z	Z	Z	Z				\vdash	Z					
100 107	Q	Q	~						Z	Z	Z	Z										
Voltage	4 6.3 10 16 25 35 50 10								4	6.3	10	16	25	35	50	4	6.3	10	16	25	35	50
Case Size				12	.06							1210							1812			

Thicknes		(0.009)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
Max.	0.33	0.22	0.56	0.71	0.90	0.94	1.02	1 27	1.40	1.52	1.78	2.29	2.54	2.70
Letter	Α	В	С	E	G	J	K	M	N	Р	Q	X	Υ	Z

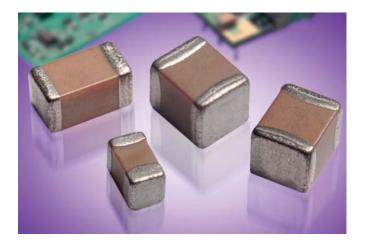
NOTE: Contact factory for non-specified capacitance values

*EIA 01005

Y5V Dielectric





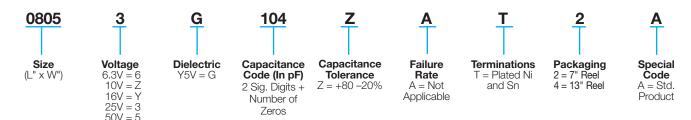


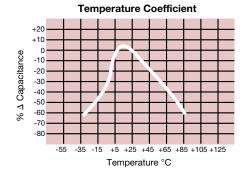
Y5V formulations are for general-purpose use in a limited temperature range. They have a wide temperature characteristic of +22% -82% capacitance change over the operating temperature range of -30°C to +85°C.

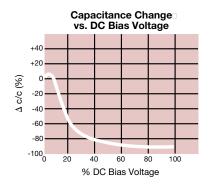
These characteristics make Y5V ideal for decoupling applications within limited temperature range.

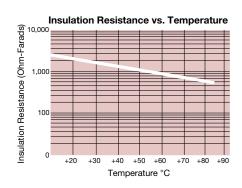


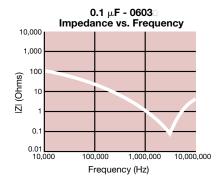
PART NUMBER (see page 2 for complete part number explanation)

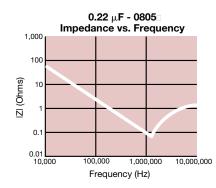


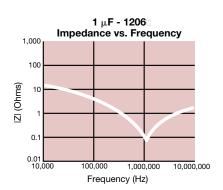














Y5V Dielectric



Specifications and Test Methods

	ter/Test	Y5V Specification Limits	Measuring	
	perature Range	-30°C to +85°C	Temperature C	Cycle Chamber
	on Factor	Within specified tolerance ≤ 5.0% for ≥ 50V DC rating ≤ 7.0% for 25V DC rating ≤ 9.0% for 16V DC rating ≤ 12.5% for ≤ 10V DC rating		0Vrms ± .2V 0.5Vrms @ 120Hz
Insulation	Resistance	10,000MΩ or 500MΩ - μF, whichever is less	120 ± 5 secs @ ro	h rated voltage for om temp/humidity
Dielectric	Strength	No breakdown or visual defects	limited to 5	e and discharge current 0 mA (max)
	Appearance	No defects		on: 2mm
Resistance to	Appearance Capacitance Variation Dissipation Factor Insulation Resistance ability Appearance Capacitance Variation Dissipation Factor Insulation Eactor Insulation Factor Insulation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Dissipation Dissipation	≤ ±30%	Test Time: 5	30 seconds 7 1mm/sec
Flexure Stresses		Meets Initial Values (As Above)		
		≥ Initial Value x 0.1		mm
Solde	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0	c solder at 230 ± 5°C .5 seconds
		No defects, <25% leaching of either end terminal		
	cerature Range itance itance In Factor Resistance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric	≤ ±20%		
Resistance to	serature Range itance In Factor Resistance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance ability Appearance Capacitance Variation Dissipation Factor Insulation Resistance Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance	Meets Initial Values (As Above)	seconds. Store at room	
Solder Heat		Meets Initial Values (As Above)	hours before measurin	g electrical properties.
		Meets Initial Values (As Above)		
		No visual defects	Step 1: -30°C ± 2°	30 ± 3 minutes
	Variation	≤ ±20%	Step 2: Room Temp	≤ 3 minutes
Thermal Shock	Factor	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes
Onook	Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Strength	Meets Initial Values (As Above)	Repeat for 5 cycles at 24 ±2 hours at room	
		No visual defects	Charge device with t	wice reted velters in
	Variation	≤ ±30%	test chamber se	et at 85°C ± 2°C
Load Life	Factor	≤ Initial Value x 1.5 (See Above)	for 1000 ho	
	Resistance	≥ Initial Value x 0.1 (See Above)	Remove from test ch at room temperatu	re for 24 ± 2 hours
	Strength	Meets Initial Values (As Above)	before m	easuring.
		No visual defects	Store in a test chamb	
	esistance Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric	≤ ±30%	85% ± 5% relative hu	
Load Humidity		≤ Initial Value x 1.5 (See above)	(+48, -0) with rate	
	Insulation Resistance	≥ Initial Value x 0.1 (See Above)	Remove from cham room temperature 24 ± 2 hours be	e and humidity for
		Meets Initial Values (As Above)	Z4 ± Z HOUIS DE	nore measumy.



Y5V Dielectric





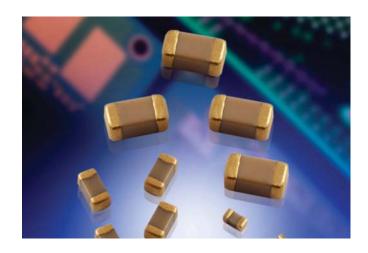
PREFERRED SIZES ARE SHADED

														ш	1				3					
SIZI	E	02	201			0402				06	603			080)5			12	06			1:	210	
Solder	ring	Reflo	w Only		R	eflow/Wa	ave			Reflov	v/Wave			Reflow/	Wave			Reflow	/Wave			Reflo	w Only	
Packag	ging	All F	Paper			All Pape	r			All F	aper		F	aper/Em	bossed		F	Paper/Er	nbossed	1		Paper/E	mbosse	ed
(L) Length	mm (in.)		± 0.03 ± 0.001)			.00 ± 0.1				1.60 :	± 0.15 ± 0.006)			2.01 ± (0.079 ±				3.20 ± (0.126 ±					± 0.20 ± 0.008)
(W) Width	mm (in.)		± 0.03 ± 0.001)			0.50 ± 0.1 020 ± 0.0				.81 ± (0.032 :	0.15 ± 0.006)			1.25 ± (0.049 ±				1.60 ± (0.063 ±					± 0.20 ± 0.008)
(t) Terminal	mm (in.)		± 0.05 ± 0.002)			0.25 ± 0.1 010 ± 0.0				0.35 : (0.014 :				0.50 ± (0.020 ±				0.50 ± (0.020 ±					± 0.25 (± 0.010)	
	WVDC	6.3	10	6	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
Cap (pF)	820 1000 2200		A A																	_			₩-	• • • • • • • • • • • • • • • • • • •
Cap (µF)	4700 0.010 0.022	A A	A		C																		\mathcal{D}	ŢT
	0.047 0.10 0.22	А			CCC					G	G	G				K				i		-		ı
	0.33									G														
	0.47				^	С				G	G													
	1.0			С	С				G	G				N	N	N	_	М	М	М				N
	2.2 4.7				С								N	N				Р				N	N	
	10.0												N				Q	Q			Х	Q	Q	
	22.0								†								Q				X			
	47.0																							
	WVDC	6.3	10	6	6 10 16 25 50 1			10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	
SIZI	E	02	201	0402				06	03			080)5			12	06			1:	210			
					0402																			
Letter	А		C	Е		G	J		K		М	N		Р		Q	Χ		Υ		7			
Max.	0.33		.56	0.71		0.90			1.02		1.27	1.40		1.52		.78	2.29		2.54		79			
Thickness	(0.013)	(0.0	022)	(0.028				(0.040)	(0	.050)	(0.05	5)	(0.060)	(0.0	070)	(0.09	0) ((0.100)	(0.1	110)				





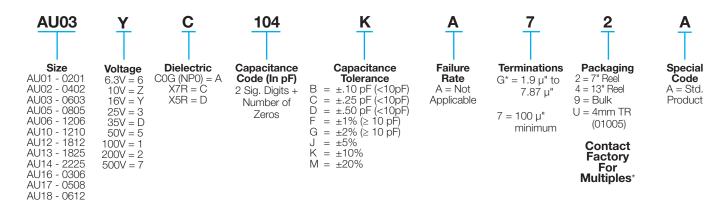
General Specifications



AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of Gold. This termination is indicated by the use of a "7" or "G" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. Please contact the factory if you require additional information on our MLCC Gold Termination.



PART NUMBER



^{*} Contact factory for availability.



Capacitance Range (NP0 Dielectric)

PREFERRED SIZES ARE SHADED

								•	D									0			
SIZ	ΖE	Αl	J01		AU02			AU	J03				AU05					AL	J06		
Solde	ering	Reflow Wire	/Epoxy/ Bond*	Ret V	flow/Epo	ixy/		Reflow/ Wire	/Epoxy/ Bond			Re	flow/Epo	oxy/				Reflow, Wire	/Epoxy/ Bond		
Packa	aging	_	Paper		All Paper				aper				er/Embo					Paper/Er		1	
(L) Length	mm	0.60	± 0.03		1.00 ± 0.1	0		1.60 :	± 0.15				2.01 ± 0.2	20				3.20	± 0.20 ± 0.008)	-	
(W) Width	(in.) mm	0.30	± 0.001 ± 0.03		0.040 ± 0.0 0.50 ± 0.1	0		0.063 =	± 0.15				.079 ± 0.0 1.25 ± 0.2	20				1.60	± 0.20		
(VV) VVIGUT	(in.) mm		± 0.001) ± 0.05		.020 ± 0.0 0.25 ± 0.1			0.032 =					0.049 ± 0.00 0.50 ± 0.20						± 0.008) ± 0.25		
(t) Terminal	(in.)		± 0.003 ± 0.002)		0.23 ± 0.1 0.010 ± 0.0			(0.014 :					0.30 ± 0.2 0.020 ± 0.0						± 0.23 ± 0.010)		
Con	WVDC	16	25	16	25	50	16	25	50	100	16	25	50	100	200	16	25	50	100	200	500
Cap (pF)	0.5 1.0	A A	A	C	C	C	G G	G G	G G	G G	J J	J	J	J J	J	J J	J	J	J	J	J
u- /	1.2	Α	А	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	1.5	A	A	C	C	C	G G	G G	G G	G G	J	J	J	J	J	J	J	J	J	J	J
	2.2	A	A	Č	Č	C	G	G	G	G	J	J	J	Ĵ	Ĵ	J	J	J	Ĵ	J	J
	2.7	A	A	C	C	C	G G	G G	G G	G G	J	J	J	J	J	J	J	J	J	J	J
	3.3	A A	A A	C	C	C	G	G	G	G	J J	J	J	J J	J	J J	J	J	J	J	J
	4.7	Α	A	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	5.6 6.8	A A	A	C	C	C	G G	G G	G G	G G	J J	J	J	J	J	J J	J	J	J	J	J
-	8.2	Α	А	С	С	С	G	G	G	G	J	Ĵ	J	J	J	Ĵ	J	Ĵ	J	Ĵ	J
	10 12	A A	A	C	C	C	G G	G G	G G	G G	J J	J	J	J	J	J J	J	J	J	J	J
	15	A	A	C	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	18	A	A	C	C	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	22 27	A A	A	C	C	C	G G	G G	G G	G G	J J	J	J	J	J	J J	J	J	J	J	J
	33	Α	А	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	39 47	A A	A	C	C	C	G G	G G	G G	G G	J J	J	J	J	J	J J	J	J	J	J	J
	56	Α	А	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	68 82	A A	A	C	C	C	G G	G G	G G	G G	J J	J	J	J J	J	J J	J	J	J	J	J
	100	A	A	C	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	120 150			C	C	C	G G	G G	G G	G G	J J	J	J	J	J	J J	J	J	J	J	J
	180			С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	220 270			C	C	C	G G	G G	G G	G G	J J	J	J	J	J M	J J	J	J	J	J	M M
-	330			С	С	С	G	G	G	G	J	J	J	J	M	J	J	J	J	J	M
	390 470			C C	C	C	G G	G G	G G		J J	J	J	J	M M	J J	J	J	J J	J	M M
	560			C	C	U	G	G	G		J	J	J	J	M	J	J	J	J	J	M
	680						G	G	G		J	J	J	J		J	J	J	J	J	Р
	820 1000						G G	G G	G G		J	J	J	J		J	J	J	J	M Q	_
	1200										J	J	J			J	J	J	J	Q	
	1500 1800						-				J	J	J			J	J	J M	M M	Q	_
	2200										J	Ĵ	N			J	Ĵ	М	Р		
	2700 3300						_				J	J	N			J	J	M	P P		
	3900										J	J				J	J	M	Р		
	4700										J	J				J	J	M	Р		
	5600 6800															J M	M	M			
Con	8200															M M	M				
Cap (µF)	0.010 0.012			I	I	l	I	l								IVI	IVI				
	0.015		1	. >	~_~	√W.															
	0.018 0.022		×		<u></u>		-														
	0.027		1	(للر.	ŢŢ														
	0.033 0.039			_	<u> </u>	-															
	0.047		1		T T																<u> </u>
	0.068 0.082			ı	· I	ı	ı														
	0.1																				
	WVDC	16	25				16	25	50	100	16	25	50	100	200	16	25	50	100	200	500
	SIZE	AL	J01		AU02			AU	J03				AU05					ΑL	J06		

^{*} Contact factory

Letter	А	С	Е	G	J	K	М	N	Р	Q	Χ	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSED			





Capacitance Range (NP0 Dielectric)

PREFERRED SIZES ARE SHADED

SIZE			AU10					AU12				AU13			AU14	
Soldering		Re	flow/Epo	xy/			Re	eflow/Epo	xy/			Reflow/Epoxy. Wire Bond*	/		Reflow/Epo: Wire Bond	ky/
Packaging			Vire Bond er/Embo					Vire Bond				All Embossed			All Emboss	
(L) Length mm (in.)			3.20 ± 0.20 126 ± 0.00)				4.50 ± 0.30 .177 ± 0.0	0			4.50 ± 0.30 (0.177 ± 0.012)			5.72 ± 0.25 (0.225 ± 0.01	
MM Width mm		2	2.50 ± 0.20)				3.20 ± 0.20	0			6.40 ± 0.40			6.35 ± 0.25	
(t) Terminal mm		(0.50 ± 0.00	5				.126 ± 0.0 0.61 ± 0.3	6			(0.252 ± 0.016) 0.61 ± 0.36			(0.250 ± 0.01 0.64 ± 0.39	
(in.)	25	50	$\frac{020 \pm 0.0^{\circ}}{100}$	200	500	25	50	.024 ± 0.0	200	500	50	(0.024 ± 0.014)	200	50	(0.025 ± 0.01	200
Cap 0.5 (pF) 1.0																
1.2																
1.5																
2.2 2.7														.1-	<i>></i>	€ W
3.3														-	\leq	$\int \int_{\mathbb{T}}$
3.9 4.7															$\supset \bot$)) \
5.6 6.8																
8.2															' '	
10 12			J													
<u>15</u>					_											
22 27					J											
33					J											
39 47					J J											
56 68					J											
82					J											
100 120					J											
150 180					J											
220 270					J											
330					J											
390 470					M M											
560 680	J	J	J	J	M M											
820	J	J	J	J	М	1/	I/	IZ.	IZ.				M	M	14	D
1000 1200	J	J	J	J M	M M	K K	K K	K K	K K	M M	M M	M M	M M	M M	M M	P P
1500 1800	J	J	J	M M	М	K K	K K	K	K	M	M M	M M	M M	M M	M M	P P
2200 2700	J	J	J	Q Q		K K	K K	K	K P	P Q	M M	M M	M M	M M	M M	P P
3300	J	J	J	Q		K	K	K	Р	Q	М	М	М	M	М	Р
3900 4700	J	J	M M			K K	K K	K	P P	Q Q	M M	M M	M M	M M	M M	P P
5600 6800	J	J				K K	K K	M M	P X	Х	M M	M M	M M	M M	M M	P P
8200	J	J				K	М	М			М	М	.vi	M	М	Р
Cap 0.010 (μF) 0.012	J	J				K K	M M	М			M M	M M		M M	M M	P P
0.015 0.018	-					M	M M				M P	M M		M M	M M	Y
0.022 0.027						M M	M M				P P			M P	Y Y	Y Y
0.033						М	М				Р			Р	r	Y
0.039 0.047						M M	M M				P P			P P		
0.068 0.082						M M	M M							P Q		
0.1	<u> </u>							165	000			100	000	Q	162	0.55
WVDC SIZE	25	50	100 AU10	200	500	25	50	100 AU12	200	500	50	100 AU13	200	50	100 AU14	200
* Contact factors											•			•		

^{*} Contact factory

Letter	А	С	E	G	J	K	М	N	Р	Q	X	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSED			





Capacitance Range (X7R Dielectric)

PREFERRED SIZES ARE SHADED

								E																		
SIZ	ZE		AU02	2				AU03	3						AU05	5			ı			Αl	J06			
Solde	ering	Refl Wi	ow/Ep	ooxy nd*			Ref W	low/Epire Bo	ooxy nd*					Ref W	low/Ep ire Boi	ooxy nd*					I	Reflow Wire	/Epox Bond	çy		
Packa	aging	Α	II Pap	er			Α	II Pap	er					Pape	r/Emb	ossed	l				Pa	aper/E	mbos	sed		
(L) Length	mm		$00 \pm 0.$					$.60 \pm 0.$.01 ± 0.								± 0.20			
(E) Longin	(in.)		40 ± 0 .					$63 \pm 0.$							0.079 ± 0.0								± 0.008	3)		
(W) Width	mm (in.)	(0.0)	50 ± 0. 20 ± 0.	004)			(0.0	.81 ± 0. .32 ± 0.	006)					(0.0)	.25 ± 0.:)49 ± 0.:	008)						(0.063	± 0.20 ± 0.008	3)		
(t) Terminal	mm (in.)		25 ± 0. 10 ± 0.					.35 ± 0.)14 ± 0.							.50 ± 0. .020 ± 0.								± 0.25 ± 0.010	0)		
	WVDC	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
Cap	100																									
(pF)	150			_																						
	220	_		С	_	G G G				_	- 1						_		-		-		-	17		
	330 470			C		G G G						J	J	J	J	J	J								K	
	680			C		G G G						J	J	J	J	J	J								K	
	1000			C		G G G G G G							J	J	J	J	J	J							-	K
	1500			C									Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ		J	J	J	J	J	J	М
	2200			С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М
	3300		С	С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М
	4700		С	С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М
	6800	С	С						G	G			J	J	J	J	J	J		J	J	J	J	J	J	Р
Cap (µF	0.010	С						_	G	G			J	J	J	J	J	J		J	J	J	J	J	J	Р
(µF	0.015 0.022	C						G	G				J	J	J	J	J	J		J	J	J	J	J	M	
	0.022	U			\vdash			G	G				J	J	J	J	N	IN		J	J	J	J	J	M	_
	0.047						G	G	G				Ĵ	J	J	Ĵ	l N			Ĵ	IJ	J	J	J	l M	
	0.068						G	G	G				Ĵ	Ĵ	Ĵ	Ĵ	N			Ĵ	Ĵ	J	Ĵ	Ĵ	P	
	0.10		C*			G	G	G	G				J	J	J	J	N			J	J	J	J	М	Р	
	0.15				G	G							J	J	J	N	N			J	J	J	J	Q		
	0.22				G	G							J	J	N	N	N			J	J	J	J	Q		
	0.33							14					N	N	N	N	N			J	J	М	Р	Q		
	0.47 0.68							J*					N N	N N	N N	N	N			M	M	M Q	PQ	Q		
	1.0					J*	J*						N	N	N*					M	M	Q	Q	Q		_
	1.5					0	0						14	IN	14					P	Q	Q	Q	Q	1	
	2.2				J*										P*					Q	Q	Q				
	3.3																									
	4.7												P*	P*						Q*	Q*	Q*				
	10											P*								Q*	Q*					
	22																		Q*							
	47 100																									
	WVDC	16	25	50	6.3	6.3 10 16 25 50 100 200 (6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
	SIZE	_	AU0		AU03							0.0	10	_	AU05		100	200	0.0	10	110		J06	1 100	200	000

^{*} Contact factory

Letter	A	С	E	G	J	K	M	N	Р	Q	X	Υ	Z	
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79	
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)	
	PAPER					EMBOSSED								



= Under Development





Capacitance Range (X7R Dielectric)

PREFERRED SIZES ARE SHADED

SIZE		
Packaging	AU14	
Packaging	Reflow/Epoxy/ Wire Bond*	
(L) Length mm (in.) (0.126 ± 0.008) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.177 ± 0.012) (0.126 ± 0.008) (0.126 ± 0	All Embossed	
(W) Width mm (in.) (in.) 2.50 ± 0.20 (0.098 ± 0.008) 3.20 ± 0.20 (0.126 ± 0.008) 6.40 ± 0.40 (0.252 ± 0.016) (t) Terminal mm (in.) (in.) 0.50 ± 0.25 (0.020 ± 0.010) 0.61 ± 0.36 (0.024 ± 0.014) 0.61 ± 0.36 (0.024 ± 0.014) WDC 10 16 25 50 100 200 500 50 100 200 500 50 100 (pF) 150 220 330 470 4	5.72 ± 0.25 (0.225 ± 0.010)	
(t) Terminal mm (in.)	6.35 ± 0.25	
(in.) (0.020 ± 0.010) (0.024 ± 0.014) (0.024 ± 0.014) WVDC 10 16 25 50 100 200 500 50 100 200 500 50 100 (pF) 150 220 330 470 680 1000 1500 1500 1500 1500 1500 1500 15	(0.250 ± 0.010) 0.64 ± 0.39	
Cap 100 (pF) 150 220 330 470 680 1000 1500 J J J J J J M M 1500 2200 J J J J J J J M M 1500 4700 J J J J J J J M M 1500 6800 J J J J J J J J M M 1500 G800 J J J J J J J J M M 1500 G800 J J J J J J J J M M 1500 G800 J J J J J J J M M 1500 G800 J J J J J J J J M M 1500 G800 J J J J J J J J M M 1500 G800 J J J J J J J J M M 1500 G800 J J J J J J J J M M 1500 G800 J J J J J J J J J M M 1500 G800 J J J J J J J J J J J J J J M M 1500 G800 J J J J J J J J J J J J J J J J J J	(0.025 ± 0.015)	
(pF) 150 220 330 470 680 1000 1500 J J J J J J M M 2200 J J J J J J J M M 200 1500 J J J J J J J M M 200 1500 J J J J J J J M M 200 1500 J J J J J J J M M 200 1500 J J J J J J J M M 200 1500 J J J J J J J M M 200 1500 J J J J J J J M M M M M M M M M M M M	50 100	
220 330 470 680 1000 1500 J J J J J J M 2200 J J J J J J M 4700 J J J J J J M 4700 6800 J J J J J J J M 6800 Oap 0.010 J J J J J J M Cap 0.010 J J J J J J M K K K K M M		
470 680 1000 1500 J J J J J J M M 1500 J J J J J J M M 1500 J J J J J J M M 1500 J J J J J J J M M 1500 J J J J J J J M M 1500 J J J J J J J M M 1500 J J J J J J J M M 1500 J J J J J J J M M 1500 J J J J J J J M M 1500 J J J J J J J M M 1500 J J J J J J J M M M M M M M M M M M M	\sim	
680 1000 1500 J J J J J M M 2200 J J J J J J M M 4700 6800 J J J J J J J M M 6800 J J J J J J M M 6800 Cap 0.010 J J J J J J M K K K M M M) <u> </u> 1	
1000 1500 2200 J J J J J M 3300 J J J J J M 4700 J J J J J M 6800 J J J J J J M Cap 0.010 J J J J J M K K K M M		
1500 J J J J J M M 2200 J J J J J J M M 3300 J J J J J J M M 4700 J J J J J J J M M 6800 J J J J J J J M M M Cap 0.010 J J J J J J M K K K K M M		
3300 J J J J J J M M 4700 J J J J J J M M M M M M M M M M M M M		
4700 J J J J J J M 6800 J J J J J J M Cap 0.010 J J J J J J M K K K M M	+ + -	
6800 J J J J J J M Cap 0.010 J J J J J J M K K K K M M		
Cap 0.010 J J J J J J M K K K M M		
	M P	
(µF 0.015 J J J J J P K K P M M	M P	
0.022 J J J J J J Q K K K P M M 0.033 J J J J J J J Q K K K X M M	M P	
0.033 J J J J J J J K K K Z M M	M P	
0.068 J J J J J J M K K Z M M	M P	
0.10 J J J J M K K Z M M	M P	
0.15 J J J J M Z K K P M M M 0.22 J J J J P Z K K K P M M M	M P	
0.22 J J J J P Z K K P M M 0.33 J J J J Q K M X M M	M P	
0.47 M M M Q K P M M	M P	
0.68 M M P X X M Q M P	M P	
1.0 N N P X Z M X M P	M P	
1.5 N N Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	M X	
3.3 X X Z Z Z	101	
4.7 X X Z Z Z Z Z		
10 Z Z Z		
22 Z Z Z 47		
100		
WVDC 10 16 25 50 100 200 500 50 100 200 500 50 100	50 100	
SIZE AU10 AU12 AU13	AU14	

* Contact factory

Letter	А	С	Е	G	J	K	М	N	Р	Q	Χ	Υ	Z	
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79	
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)	
	PAPER					FMBOSSED.								

MLCC Gold Termination – AU Series



Capacitance Range (X5R Dielectric)

PREFERRED SIZES ARE SHADED

																ш						П	_					П														
SIZ	ZE		Αl	U0	1	Τ			Αl	J02					_	AU0	3					AU	05					ΑL	J06					-	AU 1	0			I	ΑU	12	
Solde	ering	Re	eflow Nire	v/Ep	poxy nd*	/		Re	flow Vire	/Epo	oxy/		Г	F	Reflo	ow/E	pox	y/			Ref	low/ lire F	Epo Bond	xy/			Re	flow, Vire I	/Epo	xy/			F	Reflo	w/E	pox	y/					
Packa	aging		All I			†			All F				H			l Par							nbo		<u></u>				mbo		<u> </u>			aper								_
(L) Length	mm		0.60	± 0	.03	Ť			1.00	± 0.1	0		t		1.	60 ± 0	0.15				2	.01 ±	0.20	0			- ;	3.20	± 0.2	0				3.2	20 ± (0.20						_
	(in.)		0.30		.001)	+			0.50				⊢			63 ± (o)		⊢			0.00			_			± 0.0 ± 0.2					(0.12	26 ± 0 50 ± 0		3)					
(W) Width	(in.)				.001)	ı		(0.	.020	± 0.0	04)		l		(0.0)	32 ± (0.00				(0.0)49 ±	0.00	08)			(0.	.063	± 0.0	(80				(0.09)	98 ± (300.0	3)					
(t) Terminal	mm (in.)		0.15		.05	Т			0.25				Π			35 ± (14 ± (0.25 0.0						± 0.2 ± 0.0					0.5	00 ± 0		2)					
	WVDC		10		25		4 6		10			50	4	6.3		14 ± 1			50	6.3					50	6.3					50	4					35	50	6.3	10	25	50
Cap	100	A	A	A		-	Ť	0.0		1.0		100	Ė	0.0		1.0	1	- 00	100	0.0						0.0		10			- 00	Ė	0.0						0.0			
(pF)	150	Α	Α	A		_							l																													ı
	220	Α	Α	Α	A							С																	L '				1		l	l	ı	1				
	330	Α	А	Α		_						С																				>	_		~	W_						
	470	A	A	A								С	ı																١,	•	-L	_	_		\leq	7	\leq					ı
	680	A	A	A	_	-	+					С	⊢				_		-	⊢						_			F		(-	\leq	\nearrow			ノ.	ĴT			_	_	_
	1000 1500	A	A	A		۱						C	ı																		_	Ų	لر	_								ı
	2200	A	A	A		1						C	ı																			Ì	٧.									ı
	3300	Α	A	Ť		†	\top					C	Н						T	T						Н			<u> </u>				τ						Н	\dashv		_
	4700	Α	A			1					С		1						G										lι													ı
	6800	Α	Α			1					С		l						G																							ı
Сар	0.010	Α	А			Τ					С		П						G																							_
(μF)	0.015	Α				1					С		l				G	G	G																							ı
	0.022	Α		1	-	+	_			С	С		┡				G	G	G						N	_														_		_
	0.033	Α				1				С			l				G	G	G						N	l																ı
	0.047 0.068	Α				1				C	С		l				G	G	G						N	l																ı
	0.10	Α		+	+	+		С	С	С	С	\vdash	⊢				G		G	Н			N		N	\vdash						\vdash	\dashv				_		\vdash	\dashv	-	_
	0.15	^				1		U					l				G		u				N	N	IN																	ı
	0.22					1		C*					l			G	G						N	N							Q											ı
	0.33	Г		T		T	1									G	G						Ν																	\neg		_
	0.47					(C*	C*								G							Ν			l			Q	Q								Χ				ı
	0.68	╙	_	1	\perp	1	_					_	╙			G			_	L			Ν			_														_	_	_
	1.0					(C*	C*	C*					G	G	G	J*			N	Ν	N	Ν		P*				Q	Q						Х	Х	Х				ı
	1.5 2.2						C*	C*.					G*	G*	J*	J*				N N	N	N	N			l		Q	Q							Z	Х					i
	3.3	\vdash	\vdash	+	+	Ŧ		7	_				J*	J*	J*	J*			1			IV	IN			Q	Q	Q	W			\vdash	_					_	H	\dashv	-	
	3.3 4.7						F*						J*	J*	J*	J				N N	N	N*	N*			Q	Q	Q	Q						Q	Z						ı
	10					f							K*	J*						P*	P*	P*	*			Q	Q	Q	Q*					Χ	Z	Z					Ζ	i
	22			T		T	\top						Г							P*	*					Q*	Q*	Q*					Z	Z	Z	Z				\neg		_
	47																									Q*							Z*									ı
	100	L	-	\perp	-	4	\perp					_	⊢	-	-	-	1		_	_						_						Z*	Z*						Щ	_	_	_
	WVDC	6.3	_	_		5	4 (6.3		16	25	50	4	6.3	10		25	35	50	6.3	10	16		35	50	6.3	10		25	35	50	4	6.3			25	35	50		10		50
SIZ	Z E		Αl	10.	1				AL	J02			1		- 1	4U0	3			1		AU	U5					AU	106					F	\U1	U			ı	AU ¹	12	

* Contact factory

Letter	А	С	Е	G	J	K	М	N	Р	Q	Х	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSED			

= Under Development

= *Optional Specifications - Contact factory

NOTE: Contact factory for non-specified capacitance values



MLCC Gold Termination – AU Series



0612/0508/0306/Gold LICC (Low Inductance Chip Capacitors)

SIZE			03	06				()508	3			(061	2	
Packaging				osse					boss					bos		
Length mm (in.)		(0	.032 :	± 0.15 ± 0.00	06)			(0.05	7 ± 0 0 ± 0	.010)			(0.06		.010)	
Width mm (in.)				± 0.15 ± 0.00					0 ± 0 0 ± 0					0 ± 0 6 ± 0	1.25 1.010)	
WVDC	4	6.3	10	16	25	50	6.3	10	16	25	50	6.3	10	16	25	50
CAP 0.001																
(µF) 0.0022																
0.0047																
0.010																
0.015																
0.022																
0.047																
0.068																
0.10																
0.15																
0.22																
0.47																
0.68																
1.0																
1.5																
2.2																
3.3																
4.7																
10																

Solid = X7R

= X5R

| = X7S



mm (in.)

0306

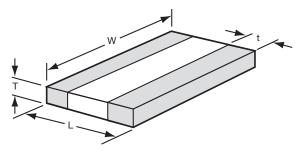
Code Thickness

A 0.61 (0.024)

	mm (in.)
	0508
Code	Thickness
S	0.56 (0.022)
V	0.76 (0.030)
Α	1.02 (0.040)

	mm (in.)
	0612
Code	Thickness
S	0.56 (0.022)
V	0.76 (0.030)
W	1.02 (0.040)
Α	1.27 (0.050)

PHYSICAL DIMENSIONS AND PAD LAYOUT



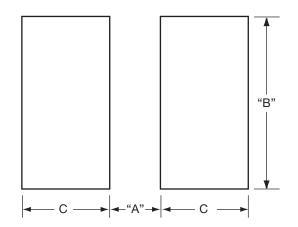
PHYSICAL CHIP DIMENSIONS mm (in)

	L	W	t
0612	1.60 ± 0.25	3.20 ± 0.25	0.13 min.
	(0.063 ± 0.010)	(0.126 ± 0.010)	(0.005 min.)
0508	1.27 ± 0.25	2.00 ± 0.25	0.13 min.
	(0.050 ± 0.010)	(0.080 ± 0.010)	(0.005 min.)
0306	0.81 ± 0.15	1.60 ± 0.15	0.13 min.
	(0.032 ± 0.006)	(0.063 ± 0.006)	(0.005 min.)

T - See Range Chart for Thickness and Codes

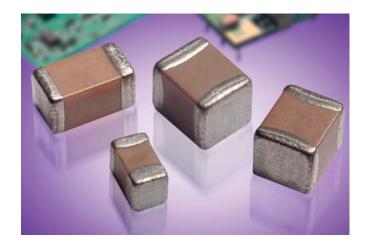
PAD LAYOUT DIMENSIONS mm (in)

		А	В	С
061	2	0.76 (0.030)	3.05 (0.120)	.635 (0.025)
050	8(0.51 (0.020)	2.03 (0.080)	0.51 (0.020)
030)6	0.31 (0.012)	1.52 (0.060)	0.51 (0.020)





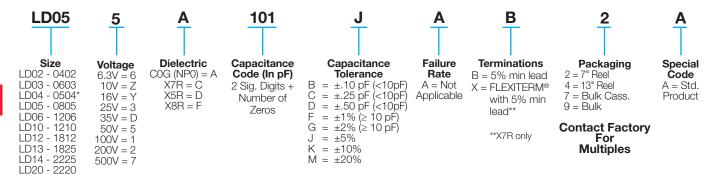
General Specifications



AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

PART NUMBER (see page 2 for complete part number explanation)



^{*}LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

See FLEXITERM® section for CV options

NP0	Refer to page 4 for Electrical Graphs
X7R	Refer to page 17 for Electrical Graphs
X7S	Refer to page 21 for Electrical Graphs
X5R	Refer to page 24 for Electrical Graphs
Y5V	Refer to page 28 for Electrical Graphs





Capacitance Range (NP0 Dielectric)

PREFERRED SIZES ARE SHADED

							3										l		
SIZE	E		LD02			LC	003				LD05					LD0	6		
Solder			eflow/Wa				v/Wave				eflow/Wa					Reflow/\			
Packag	ging mm		All Pape 1.00 ± 0.1				Paper ± 0.15				er/Embos				Pa	aper/Eml 3.20 ± 0			
(L) Length	(in.) mm	(0.0	040 ± 0.0	004)		(0.063	± 0.006) ± 0.15			(0.	079 ± 0.00	08)				(0.126 ± 0	0.008)		
(W) Width	(in.)	(0.0	020 ± 0.0	004)		(0.032	± 0.006)			(0.	0.000 ± 0.000	08)				(0.063 ± 0)	0.008)		
(t) Terminal	mm (in.)		0.25 ± 0.1 010 ± 0.0				± 0.15 ± 0.006)				0.50 ± 0.25 020 ± 0.01					0.50 ± 0 (0.020 ± 0			
Cap	WVDC 0.5	16 C	25 C	50 C	16 G	25 G	50 G	100 G	16 J	25 J	50 J	100 J	200 J	16 J	25 J	50 J	100 J	200 J	500 J
(pF)	1.0	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	1.2 1.5	C	C	C	G G	G G	G G	G G	J	J	J	J	J	J J	J	J J	J	J	J J
	1.8 2.2	CC	C	C	G G	G G	G G	G G	J	J	J	J	J	J J	J	J J	J	J	J J
	2.7	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	3.3 3.9	C	C	C	G G	G G	G G	G G	J	J	J	J	J	J	J	J	J	J J	J J
	4.7 5.6	C	C	C	G G	G	G	G G	J	J	J	J	J	J	J	J	J	J	J
	6.8	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	8.2 10	C	C	C	G G	G G	G G	G G	J	J	J	J	J	J	J	J	J	J	J
	12 15	C	C	C	G G	G G	G	G G	J	J	J	J	J J	J J	J	J	J	J	J J
	18	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	22 27	C	C	C	G G	G G	G G	G G	J	J	J	J	J	J J	J	J J	J	J J	J J
	33	C	C	C	G G	G G	G G	G G	J	J	J	J	J	J	J	J	J	J	J
	47	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J J
	56 68	00	C	C	G G	G G	G G	G G	J	J	J	ا ا	J	J J	J	J	J	つ つ	J
	82	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	100 120	00	C	CC	G G	G G	G G	G G	J	J	J	J	J	J J	J	J	J	J	J J
	150 180	C	C	C	G G	G G	G	G G	J	J	J	J	J	J	J	J	J	J	J
	220	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	М
	270 330	C	C	C	G G	G G	G G	G G	J	J	J	J	M M	J	J	J	J	J	M M
	390 470	C	C	C	G G	G G	G G		J J	J	J	J J	M M	J J	J	J J	J	J J	M M
-	560				G	G	G		J	J	J	J	M	J	J	J	J	J	М
	680 820				G G	G G	G G		J	J	J	ر د		J J	J	J J	J	J M	Р
	1000 1200				G	G	G		J	J	J	J		J	J	J	J	o o	
	1500								J	J	J			J	J	J	М	Q	
	1800 2200								J	J	J N			J	J	M M	M P		
	2700 3300								J	J	N			J	J	M M	P P		
	3900 4700								J J	J				J J	J	М	P P		
	5600							\vdash	J	J				J	J	M	P		
	6800 8200													M M	M M				
Cap (µF)	0.010 0.012													М	M				
(µi)	0.015			1			I												
	0.018 0.022		.	<u>_</u>	\sim	€ W-	•												
	0.027			<	$\overline{}$) (Ţ	\sqcup						<u> </u>					
	0.039		'	$\overline{}$	_		_												
	0.047 0.068		-	Ī	t			$\vdash\vdash\vdash$						_					
	0.082						ı												
	0.1 WVDC	16	25	50	16	25	50	100	16	25	50	100	200	16	25	50	100	200	500
	SIZE		LD02			LI	003				LD05					LD	006		
Letter Max.	A 0.33	0.8		E 0.71	G 0.90		J 0.94	K 1.02		M .27	N 1.40	P 1.5		Q 1.78	X 2.29		Y 2.54	Z 2.79	
Thickness	(0.013)	(0.0)		(0.028)	(0.03		0.94	(0.040		050)	(0.055)	(0.06		0.070)	(0.090		.100)	(0.11	
				PAPER								EI	MBOSS	ED	•				



Capacitance Range (NP0 Dielectric)

PREFERRED SIZES ARE SHADED

PNLF	LINN	LD	SIZ	LJF	·nL	31 1 /	ADL	-0					ПП			П	
SIZ	Œ.			LD10					LD12				LD13			LD14	
Solde				eflow On					eflow Or				Reflow Only			Reflow Onl	
Packa	iging mm			er/Embos 3.20 ± 0.20					Emboss 4.50 ± 0.3				All Embossed 4.50 ± 0.30	<u> </u>		All Embosse 5.72 ± 0.25	
(L) Length	(in.) mm		(0.	126 ± 0.00 2.50 ± 0.20	18)			(0.	177 ± 0.0 3.20 ± 0.2	12)			(0.177 ± 0.012) 6.40 ± 0.40			(0.225 ± 0.01) 6.35 ± 0.25	0)
(W) Width	(in.) mm		(0.	098 ± 0.00	18)			(0.	126 ± 0.0	08)			(0.252 ± 0.016) 0.61 ± 0.36			(0.250 ± 0.01) 0.64 ± 0.39	0)
(t) Terminal	(in.)	OF.	(0.	020 ± 0.01	0)	500	05	(0.	024 ± 0.0	14)	F00	FO	(0.024 ± 0.014)		50	(0.025 ± 0.01	5)
Cap	WVDC 0.5	25	50	100	200	500	25	50	100	200	500	50	100	200	50	100	200
(pF)	1.0 1.2																
	1.5 1.8																
	2.2															<i>></i> ~~	€W-
	2.7 3.3																
	3.9 4.7															\supset	J) ! '
	5.6														1	المبعا	
	6.8 8.2															Tt	
·	10 12					J											
	15 18					J											
	22 27					J											
	33					J											
	39 47					J											
	56 68					J J											
	82					J											
	100 120					J											
	150 180					J											
	220 270					J J											
-	330 390					J M											
	470					М											
	560 680	J J	J	J	J	M M											
	820 1000	J	J	J	J	M M	K	K	K	K	M	M	M	M	M	M	Р
	1200 1500	J	J	J	M M	M M	K K	K K	K K	K K	M M	M M	M M	M M	M M	M M	P P
	1800	J	J	J	М	IVI	K	K	K	K	М	М	М	М	М	M	P
	2200 2700	J	J	J	Q Q		K K	K K	K K	K P	P Q	M M	M M	M M	M M	M M	P P
	3300 3900	J	J	J M			K K	K K	K K	P P	00	M M	M M	M M	M M	M M	P P
	4700 5600	J	J	М			K K	K	K M	P P	Q	M M	M M	M M	M M	M M	P P
	6800	J	J				K	K	М	X		M	M	M	М	М	Р
Сар	8200 0.010	J	J				K	M	M			M M	M		M	M	P P
(μF)	0.012 0.015	J	J				K M	M M		<u> </u>		M M	M M		M M	M M	P Y
	0.018 0.022						M M	M M				P P	M		M M	M Y	Y Y
	0.027						M M	M M				P P			P P	Ý	Ý
	0.039						M	М				Р			Р		
	0.047 0.068						M M	M				Р			P P		
	0.082 0.1						М	М							Q Q		
SIZI	WVDC	25	50	100 LD10	200	500	25	50	100 LD12	200	500	50	100 LD13	200	50	100 LD14	200
Letter	E J			E	G		J	K		M	N	I P I	Q Q	Х	<u>Y</u> Z		
Max.	0.33	0.	56	0.71	0.90		0.94	1.02	. 1	.27	1.40	1.52	1.78	2.29 2	2.54 2.7	79	
Thickness	(0.013)	(0.0)		(0.028) PAPER	(0.03	5) ((0.037)	(0.040)	050)	(0.055)	(0.060) EMBOS		(0.090) (0	.100) (0.1	10)	



Capacitance Range (X8R Dielectric)

	SIZE	L	.D03		LD05		LD06
	WVDC	25V	50V	25V	50V	25V	50V
271	Cap 270	G	G				
331	(pF) 330	G	G	J	J		
471	470	G	G	J	J		
681	680	G	G	J	J		
102	1000	G	G	J	J	J	J
152	1500	G	G	J	J	J	J
182	1800	G	G	J	J	J	J
222	2200	G	G	J	J	J	J
272	2700	G	G	J	J	J	J
332	3300	G	G	J	J	J	J
392	3900	G	G	J	J	J	J
472	4700	G	G	J	J	J	J
562	5600	G	G	J	J	J	J
682	6800	G	G	J	J	J	J
822	8200	G	G	J	J	J	J
103	Cap 0.01	G	G	J	J	J	J
123	(μF) 0.012	G	G	J	J	J	J
153	0.015	G	G	J	J	J	J
183	0.018	G	G	J	J	J	J
223	0.022	G	G	J	J	J	J
273	0.027	G	G	J	J	J	J
333	0.033	G	G	J	J	J	J
393	0.039	G	G	J	J	J	J
473	0.047	G	G	J	J	J	J
563	0.056	G		N	N	M	M
683	0.068	G		N	N	M	M
823	0.082			N	N	M	M
104	0.1			N	N	М	M
124	0.12			N	N	М	M
154	0.15			N	N	М	M
184	0.18			N		М	M
224	0.22			N		М	M
274	0.27					М	M
334	0.33					М	M
394	0.39					М	
474	0.47					М	
684	0.68						
824	0.82						
105	1						
	WVDC	25V	50V	25V	50V	25V	50V
	SIZE		LD03		LD05	L	D06
Letter	A C E	G	J K	1 M		Q X	Y Z
Max.	0.33 0.56 0.71	0.90	1.02	1.27 1.	40 1.52 1.	78 2.29	2.54 2.79
Thickness	(0.013) (0.022) (0.028)		037) (0.040)		055) (0.060) (0.0		(0.100) (0.110)
	(0.020)	(0.000)	(0.0.0)	(2.500) (0.0	(0.000)	, (0.000)	(200)





Capacitance Range (X7R Dielectric)

PREFERRED SIZES ARE SHADED

								ш																		
SIZI	E		LD02	2				LD03	3						LD05	j						LD	006			
Solder	ina	Ref	LD02 effow/Wave All Paper 1.00 ± 0.10 .0040 ± 0.004) 0.550 ± 0.10 .020 ± 0.004) 0.25 ± 0.15 .010 ± 0.006) C C C C C C C C C C C C C C C C C C C					low/W	lave.					Ref	low/W	lave						Reflov	v/Wave	-		
Packag								II Pap							r/Emb								mboss	-		
(L) Length	mm (in.)	1.	00 ± 0 .	10			1.	60 ± 0.	15					2.	01 ± 0. 79 ± 0.	20					- 10	3.20	± 0.20 ± 0.008			
(W) Width	mm							81 ± 0.							25 ± 0.								± 0.20			
(VV) VVIGITI	(in.)							32 ± 0.0							49 ± 0.								± 0.008))		
(t) Terminal	mm							35 ± 0 .							50 ± 0.								± 0.25			
	(in.)				0.0	10				I 100	L 000	0.0	10		20 ± 0.		I 100	Loon	0.0	1 10	1.40		± 0.010)		Looo	500
Cap	WVDC 100	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
(pF)	150																		l							
(pr)	220			C															l							
	330								G	G	G		J	J	J	J	J	J								K
	470								G	G	G	l	J	Ĵ	J	Ĵ	J	J	l							K
	680								G	G	G	l	J	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	l							K
	1000			С					G	G	G		J	J	J	J	J	J								K
	1500								G	G		1	J	J	J	J	J	J	l	J	J	J	J	J	J	М
	2200			С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М
	3300								G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
	4700			С					G	G			J	J	J	J	J	J	l	J	J	J	J	J	J	M
	6800	С	С						G	G			J	J	J	J	J	J	<u> </u>	J	J	J	J	J	J	Р
Cap	0.010	С							G	G			J	J	J	J	J	J	l	J	J	J	J	J	J	Р
(μF	0.015	С						G	G				J	J	J	J	J	J	l	J	J	J	J	J	M	
	0.022	С						G	G			_	J	J	J	J	J	N	<u> </u>	J	J	J	J	J	M	
	0.033						G	G	G				J	J	J	J	N		l	J	J	J	J	J	M	
	0.047							G	G				J	J	J	J	N		l	.]	l .i	J]	J	P	
	0.10		C*			G		G	G				J	J	J	J	N		\vdash	J	J	J	J	M	P	_
	0.15		_		G		-	-	-				J	J	Ĵ	N	N		l	J	Ĵ	J	Ĵ	Q		
	0.22												J	J	N	N	N		l	J	J	J	J	Q		
	0.33												N	N	N	N	N			J	J	М	Р	Q		
	0.47							J*					N	N	N	N	N		l	М	М	М	Р	Q		
	0.68												N	N	N					М	М	Q	Q	Q		
	1.0					J*	J*						N	N	N*				l	M	M	Q	Q	Q		
	1.5																		l	Р	Q	Q				
	2.2				J*										P*			-	_	Q	Q	Q				
	3.3 4.7												P*	P*					l	Q*	Q*	Q*				
	10											P*	Р	Р					l	Q*	Q*	Q				
	22											Г					-	+	Q*	Q	Q					_
	47																		Q							
	100																		l							
	WVDC	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
	SIZE							LD03							LD05		•					LD				
			_		_		0									_								_		
Letter	А								J		K	N		N		Р		Q		Х		Υ		Z		
Max.	0.33								.94		.02	1.2		1.4		1.5		1.78		2.29		2.54		2.79		
Thickness	(0.013)	(0	J. J. J. G.					(0.	037)	(0.	040)	(0.0)	150)	(0.05	5)	(0.06	- /	(0.070))	(0.090))	(0.100) (0.110)		
				PA	G. CO. CO. CO. CO. CO. CO. CO. CO. CO. CO											EN	ивоѕ	SSED								







Capacitance Range (X7R Dielectric)

PREFERRED SIZES ARE SHADED

SI	ZE				LD10					LC	012		LD.	13		LC	20		LD	14
Sold	ering			F	Reflow On	ıly				Reflo	w Only		Reflow	Only		Reflo	w Only		Reflov	v Only
	aging				er/Embo					All Em	bossed		All Emb	ossed		All Em	bossed		All Eml	
(L) Length	mm				3.20 ± 0.20						± 0.30		4.50 ±				± 0.40		5.72 :	
	(in.) mm				0.126 ± 0.00 2.50 ± 0.20						± 0.012) ± 0.20		(0.177 ± 6.40 ±				± 0.016) ± 0.40		(0.225 ± 6.35 ±	
(W) Width	(in.)			(0	0.098 ± 0.00	08)				(0.126	± 0.008)		(0.252 ±	0.016)		(0.197	± 0.016)		(0.250 :	± 0.010)
(t) Terminal	mm (in.)				0.50 ± 0.25 0.020 ± 0.03						± 0.36 ± 0.014)		0.61 ± (0.024 ±				± 0.39 ± 0.015)		0.64 :	± 0.39 ± 0.015)
-	WVDC	10	16	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100
Cap	100																			
(pF)	150																``ا		≪ W-	•
	220 330			-												<u> </u>	<	$<$ $^{-}$		^
	470																(-	J)	كلا	↓
	680															L		<u> </u>		
	1000 1500	J	J	J	J	J	J	M										T T		
	2200	J	J	J	J	J	J	M	l								1 1	1		
	3300	J	J	J	J	J	J	M												
	4700 6800	J	J	J	J	J	J	M	l											
Cap	0.010	J	J	J	J	J	J	M	К	K	K	K	М	М		X	X	Х	М	Р
(μF	0.015	J	Ĵ	Ĵ	J	Ĵ	Ĵ	P	K	K	K	Р	M	М		X	X	X	М	Р
	0.022	J	J	J	J	J	J	Q	K	K	K	Р	М	М		X	X	X	М	Р
	0.033 0.047	J	J	J	J	J	J	Q	K K	K K	K K	X Z	M M	M M		X	X	X	M M	P P
	0.068	J	J	J	J	J	M		K	K	K	Z	M	M		X	X	x	M	P
	0.10	J	J	J	J	J	М		K	K	K	Z	М	М		Х	Х	Х	М	Р
	0.15 0.22	J	J	J	J	M P	Z Z		K K	K K	P		M M	M M		X	X	X	M M	P P
	0.22	J	J	J	J	Q			K	M	X		M	M		X	X	X	M	P
	0.47	М	М	M	М	Q			K	Р			М	М		X	X	X	М	Р
	0.68	M	M	P	X	X			M M	Q			M	P P		X	X		M M	P P
	1.0 1.5	N N	N N	Z	X Z	Z Z			Z	X Z			M	Р		×	X		M	X
	2.2	Х	X	Z	Z	Z			Z	Z						X	X		М	
	3.3	X	X	Z	Z				Z							X	Z			_
	4.7 10	X Z	X Z	Z	Z				Z							X Z	Z			
-	22	Z	Z					1							Z					
	47																			
	100 WVDC	10	16	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100
SIZ		10	10		LD10	100	200	1 300	30)12	300	LD.		20	LC		200	LD	
	'														, ,					
Letter Max.	0.33	0.5		0.71	0.90	0.9		1.02	M 1.27		N .40	P 1.52	Q 1.78		X 29	Y 2.54	2.79			
Thickness		(0.0)		(0.028)	(0.035)		94	(0.040)	(0.050		.40 055)	(0.060)	(0.070)		29	(0.100)	(0.110			
111101111030	(0.010)	(0.0		PAPER	(0.000)	(0.0		(5.0 10)	(0.000	, (0.0		, ,	DSSED	(0.0	, ,	(0.100)	(0.110			
				, u = 1 t								LIVIDO	JULD							



Capacitance Range (X5R Dielectric)

PREFERRED SIZES ARE SHADED

											=						П	_					Ш													\Box	
SIZ	Έ			LD	002					L	.D0	3					LD	05					LD	06					L	.D1	0				LD	12	
Solde	ring		Re	eflow	v/Wa	ave				Reflo	w/V	Vave	,			Re	eflow	/Wa	ve			Re	eflow	/Wa	ve				Reflo	ow/V	Vave	9					
Packa				All P	ape	r				All	Par	er				Pape	er/Er	nbos	ssed			Pape	er/Er	nbo	ssec			Pa	per/	'Emb	ooss	ed					_
(L) Length	mm			1.00 :							0 ± 0							± 0.20					3.20 -							0 ± 0							_
	(in.) mm	_		.040				┢		(0.06	3 ± 0 1 ± 0)					± 0.00			⊢		126 :			-				6 ± 0 0 ± 0)		⊢			—
(W) Width	(in.)			.020						(0.03)					± 0.00					063 :							8 ± 0)					
(t) Terminal	mm			0.25 :							5 ± 0							± 0.25					0.50 =							0 ± 0		Λ.					
	(in.)	1		.010 :			50	1	6.3	(0.01 ₁				50	6.3			± 0.01		50	63		020 -		35	50	4	6.3		0 ± 0	25		50	63	10	25	50
Cap	100	-	0.0	10	10	20	30	4	0.0	10	10	20	00	30	0.0	10	10	20	00	30	0.0	10	10	20	00	30	4	0.0	10	10	20	00	30	0.0	10	20	
(pF)	150																																				
(5:)	220						С																					l		l	l	l	l	I	1		
	330						С	П													Г					П		-			_	_	_	~	١٨/		
	470						С																							-L	\subseteq	_		=	٧٧ <u>~</u>	~	
	680						С																						_	$\overline{}$	\equiv))	ÎΤ	
	1000						С																							<u>_</u>	_ `)]_			_	
	1500						С																									ن	Ī				
	2200						С	H	\vdash	-					_	-					L					Н		-				t					
	3300					С	С							G																ı	ı	ı	ı	ı			
	4700 6800					C								G																							
Cap	0.010					С		H						G							H					Н								+	H		
(µF)	0.015					C						G	G	G																							
(p.,)	0.022				С	C						G	G	G						Ν																	
	0.033				С							G	G	G						N															П		
	0.047				С	С						G	G	G						Ν																	
	0.068				С							G		G						Ν																	
	0.10			С	С	С						G		G				Ν		Ν																	
	0.15											G						N	N																		
	0.22		C*				-	⊢	-	-	G	G				_		N	N		L					Q								╀	Ш		
	0.33	O*	C*								G	G						N						Q	Q								X				
	0.68										G							N						Q	Q								^	1			
	1.0	C*	C*	C*			\vdash	┢	G	G	G	J*			\vdash	\vdash	N	N		P*				Q	Q	Н					Х	Х	Х	Н	Н		—
	1.5								u	u	u	U					IN	IN		-				Q	Q						^	^		1			
	2.2	C*	C*					G*	G*	J*	J*					Ν	N	N					Q	Q							Ζ	X					
	3.3							J*	J*	J*	J*				Ν	N					Q	Q															
	4.7	E*						J*	J*	J*					Ν	N	N*	N*			Q	Q	Q	Q						Q	Z						
	10							K*	J*						N*	N*	N*	*			Q	Q	Q	Q*					Χ	Z	Z					Ζ	
	22														P*	*					Q*	Q*	Q*					Ζ	Z	Z	Z						
	47																				Q*						7+	Z*									
	100 WVDC	1	6.3	10	16	25	50	1	6.3	10	16	25	25	50	6.2	10	16	25	25	50	6.2	10	16	25	35	50	Z* 4	Z* 6.3	10	16	25	25	50	6.0	10	25	
SIZ		4	0.3	_	002	20	_ :JU	4	10.3		D0		30	UU	0.3	110	LD		35	100	0.3	10	LD		30	υU	4	0.3		D1		1 30	1 30	0.3		25)12	_50_
- 312	-	<u> </u>			-02					-	0	_						-55						30					-	יו כ	_					12	—
1,,,,,,	Α		,	`					0						I/					4		_	Г			0			V			V			7		
Letter Max.	0.33			<u>56</u>		0.7			0.90)		J 0.94			K 1.02			М .27		1.4			P 1.5			Q 1.78	2	,	X 2.29	4		.54			<u>7</u> 79		
Thickness			(0.0			(0.0)			0.90			0.94			1.02 1.040))		.2 <i>1</i> 050)		(0.0			c.ı 90.0)			1.7c).07(2.29).090			.54 100)	(0.1			
·······································	(0.010)	_	,0.0	,		9AP	,	-	0.00	٥,	10	,,,,,,	,	10		′/	(0.0	330)		,0.0	30)		(/))SS		~ <i>j</i>	(0		′/	(0.	700	/	(0.1	10)		
						AL	LIT																	AIDC		-U											

= Under Development
= *Optional Specifications – Contact factory

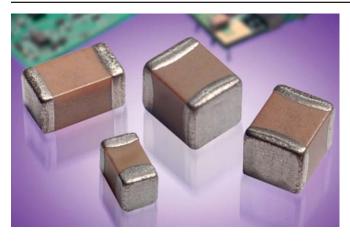
NOTE: Contact factory for non-specified capacitance values



MLCC Low Profile



General Specifications

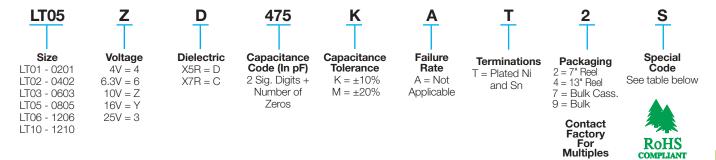


GENERAL DESCRIPTION

AVX introduces the LT series comprising a range of low profile products in our X5R and X7R dielectric. X5R is a Class II dielectric with temperature variation of capacitance within ±15% from -55°C to +85°C. Offerings include 0201, 0402, 0603, 0805 1206, and 1210 packages in compact, low profile designs. The LT series is ideal for decoupling and filtering applications where height clearance is limited.

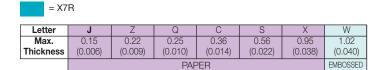
AVX is also expanding the low profile products in our X7R dielectric. X7R is a Class II dielectric with temperature variation of capacitance within $\pm 15\%$ from -55°C to +125°C. Please contact the factory for availability of any additional values not listed.

PART NUMBER (see page 2 for complete part number explanation)



NOTE: Contact factory for availability of tolerance options for specific part numbers.

	SIZE	•	LT	01		LT	02			Lī	T03			LT	05				LT06			LT	10
		WVDC	4	6.3	4	6.3	10	16	4	6.3	16	25	6.3	10	16	25	6.3	10	16	25	50	16	25
Cap	104	0.10	Z	Z		Q		S															
(µF)		0.22										Χ											
		0.47										Χ								Χ			
	105	1.0	Q		С		S				S	Х			Χ	Χ		Χ	Χ	Χ	W		
		1.5																					
		2.2			S	С				S	Χ			Χ	Χ			Χ	Χ	Χ	Χ		
		4.7							S	Χ			Χ	S	Χ			W	W	Χ	Х	W	
	106	10							X/W				Χ	Χ			W	W	W	Χ		W	
		22																					
		47																					
		WVDC	4	6.3	4	6.3	10	16	4	6.3	16	25	6.3	10	16	25	6.3	10	16	25	50	16	25
	SIZE		LT	01		LT	02			Lī	03			LT	05				LT06			LT	10

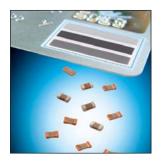




UltraThin Ceramic Capacitors



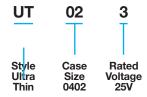




The Ultrathin (UT) series of ceramic capacitors is a new product offering from AVX. The UT series was designed to meet the stringent thickness requirements of our customers. AVX developed a new termination process (FCT - Fine Copper Termination) that provides unbeatable flatness and repeatability. The series includes products < 0.35mm in height and is targeted for applications such as Smart cards, Memory modules, High Density SIM cards, Mobile phones, MP3 players, and embedded solutions.



HOW TO ORDER





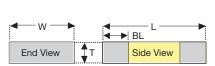


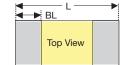








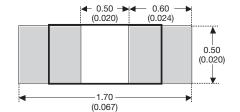




inches (mm)

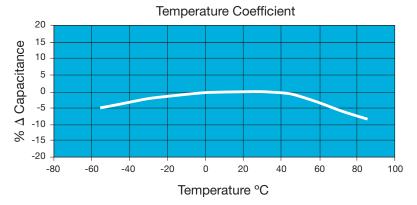
RECOMMENDED SOLDER PAD DIMENSIONS

mm (inches)



PART DIMENSIONS

L	W	Т	BL
1.00 ± 0.10 (0.039±0.004)	0.50 ± 0.10 (0.020 ± 0.004)	0.25 ± 0.05	0.25 ± 0.10 (0.010 ± 0.004)



PERFORMANCE CHARACTERISTICS

0.01µF
±20%
3.0%
-55°C to +85°C
±15%
25V
100,000 Mohms
1 Vrms @ 1 KHz



Automotive MLCC

Automotive



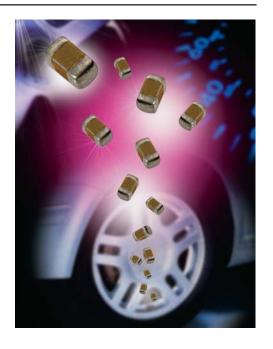
GENERAL DESCRIPTION

AVX Corporation has supported the Automotive Industry requirements for Multilayer Ceramic Capacitors consistently for more than 10 years. Products have been developed and tested specifically for automotive applications and all manufacturing facilities are QS9000 and VDA 6.4 approved.

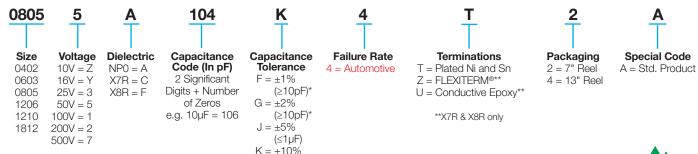
As part of our sustained investment in capacity and state of the art technology, we are now transitioning from the established Pd/Ag electrode system to a Base Metal Electrode system (BME).

AVX is using AECQ200 as the qualification vehicle for this transition. A detailed qualification package is available on request and contains results on a range of part numbers including:

- X7R dielectric components containing BME electrode and copper terminations with a Ni/Sn plated overcoat.
- X7R dielectric components, BME electrode with epoxy finish for conductive glue mounting.
- X7R dielectric components BME electrode and soft terminations with a Ni/Sn plated overcoat.
- NP0 dielectric components containing Pd/Ag electrode and silver termination with a Ni/Sn plated overcoat.



HOW TO ORDER



*NPO only

 $M = \pm 20\%$

Contact factory for availability of Tolerance Options for Specific Part Numbers.

NOTE: Contact factory for non-specified capacitance values. 0402 case size available in T termination only.



COMMERCIAL VS AUTOMOTIVE MLCC PROCESS COMPARISON

	Commercial	Automotive
Administrative	Standard Part Numbers. No restriction on who purchases these parts.	Specific Automotive Part Number. Used to control supply of product to Automotive customers.
Design	Minimum ceramic thickness of 0.020"	Minimum Ceramic thickness of 0.029" (0.74mm) on all X7R product.
Dicing	Side & End Margins = 0.003" min	Side & End Margins = 0.004" min Cover Layers = 0.005" min
Lot Qualification (Destructive Physical Analysis - DPA)	As per EIA RS469	Increased sample plan – stricter criteria.
Visual/Cosmetic Quality	Standard process and inspection	100% inspection
Application Robustness	Standard sampling for accelerated wave solder on X7R dielectrics	Increased sampling for accelerated wave solder on X7R and NP0 followed by lot by lot reliability testing.



Automotive MLCC

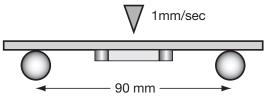
NP0/X7R Dielectric



FLEXITERM® FEATURES

a) Bend Test

The capacitor is soldered to the PC Board as shown:



Typical bend test results are shown below:

Style	Conventional Term	Soft Term
0603	>2mm	>5
0805	>2mm	>5
1206	>2mm	>5

b) Temperature Cycle testing FLEXITERM® has the ability to withstand at least 1000 cycles between –55°C and +125°C

ELECTRODE AND TERMINATION OPTIONS

NPO DIELECTRIC

NPO Ag/Pd Electrode Nickel Barrier Termination PCB Application

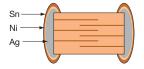


Figure 1 Termination Code T

X7R DIELECTRIC

X7R Dielectric PCB Application

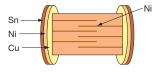


Figure 2 Termination Code T

X7R Nickel Electrode Soft Termination PCB Application

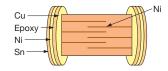


Figure 3 Termination Code Z

Conductive Epoxy Termination Hybrid Application

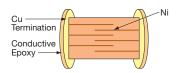


Figure 4 Termination Code U



Automotive MLCC - NP0



Capacitance Range

			0603			0805				1206				1:	210		18	312
		25V	50V	100V	25V	50V	100V	25V	50V	100V	200V	500V	25V	50V	100V	200V	50V	100V
100	10pF	G	G	G	J	J	J	J	J	J	J	J						
120	12	G	G	G	J	J	J	J	J	J	J	J						
150	15	G	G	G	J	J	J	J	J	J	J	J						
180	18	G	G	G	J	J	J	J	J	J	J							
220	22	G	G	G	J	J	J	J	J	J	J							
270	27	G	G	G	J	J	J	J	J	J	J							
330	33	G	G	G	J	J	J	J	J	J	J							
390	39	G	G	G	J	J	J	J	J	J	J							
470	47	G	G	G	J	J	J	J	J	J	J							
510	51	G	G	G	J	J	J	J	J	J	J							
560	56	G	G	G	J	J	J	J	J	J	J							
680	68	G	G	G	J	J	J	J	J	J	J							
820	82	G	G	G	J	J	J	J	J	J	J							
101	100	G	G	G	J	J	J	J	J	J	J							
121	120	G	G	G	J	J	J	J	J	J	J							
151	150	G	G	G	J	J	J	J	J	J	J							
181	180	G	G	G	J	J	J	J	J	J	J							
221	220	G	G	G	J	J	J	J	J	J	J							
271	270	G	G	G	J	J	J	J	J	J	J							
331	330	G	G	G	J	J	J	J	J	J	J							
391	390	G	G		J	J	J	J	J	J	J							
471	470	G	G		J	J	J	J	J	J	J							
561	560				J	J	J	J	J	J	J							
681	680				J	J	J	J	J	J	J							
821	820				J	J	J	J	J	J	J							
102	1000				J	J	J	J	J	J	J		J	J	J	J		
122	1200							J	J	J	J		J	J	M	М		
152	1500							J	М	М	М		J	J	M	М		
182	1800							J	М	М	М		J	J	М	М		
222	2200							J	М	М	М		J	J	М	М		
272	2700				+			J	М				J	J	М			14
332	3300				\perp	1		J	М				J	J	Р		K	K
392	3900												J	J	Р		K	K
472	4700												J	J	Р		K	K
103	10nF	051/	50) /	1001	05)	50)/	1001/	05) (50) /	100):	0001/	5001/	051/	50) (100);	0001/	50) (100:-
		25V	50V	100V	25V	50V	100V	25V	50V	100V	200V	500V	25V	50V	100V	200V	50V	100V
			0603			0805				1206				12	210		18	312
Let	tter	А	С		Е	G	J		K	М	N	ΙР		Q	Х	ΙΥ	Z	
Ma		0.33	0.5		0.71	0.90	0.94		.02	1.27	1.40	1.52		.78	2.29	2.54	2.7	
Thick		(0.013)	(0.02		(0.028)	(0.035)	(0.037		040)	(0.050)	(0.055)	(0.06		070)	(0.090)	(0.100)		
111101		(0.010)	(0.02	,	,	(0.000)	(0.007	(0.	0 10)	(0.000)	(0.000)	,	/ \	,	(0.000)	(0.100)	(0.1	. 5)
				- 1	PAPER							ΕN	JBOSSE	:U				



= Under Development

Automotive MLCC-X7R



Capacitance Range

				0402				0603					0805					12	:06				12	10		18	12	22	220
			16V	25V	50V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	500V	16V	25V	50V	100V	50V	100V	25V	50V
221	Cap	.22																											
271	(nF)	.27																											
331		.33																											
391		.39																											
471		.47																											
561		.56																											
681		.68																											
821		.82																											
102		1				G	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
182		1.8				G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
222		2.2				G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
332		3.3				G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
472		4.7				G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
103		10				G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
123		12				G	G	G			J	J	J	М		J	J	J	J	J		Κ	K	K	K	K	K	$\overline{}$	
153		15				G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
183		18				G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
223		22				G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
273		27				G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
333		33				G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
473		47				G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	K	K	K		
563		56				G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	М	K	K		
683		68				G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	М	K	K		
823		82				G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	M	K	K		
104		100				G	G	G			J	J	М	М		J	J	J	М	J		K	K	K	М	K	K		
124		120									J	J	M			J	J	M	М			K	K	K	Р	K	K		
154		150									М	N	М			J	J	М	М			K	K	K	Р	K	K		
224		220									М	N	М			J	M	M	Q			М	М	М	Р	М	M		
334		330									N	N	М			J	М	Р	Q			Р	Р	Р	Q	Х	X		
474		470									N	N	М			М	М	Р	Q			Р	Р	Р	Q	Х	Χ		
684	(680									N	N				М	Q	Q	Q			Р	Р	Q	Х	Х	Х		
105	Cap	1									N	N				М	Q	Q	Q			Р	Q	Q	Х	Х	Χ		
155		1.5														Q	Q					Р	Q	Z	Z	Х	Х		
225		2.2														Q	Q					Х	Z	Z	Z	Z	Z		
335		3.3																				Х	Z	Z		Z			
475		4.7																				Х	Z	Z		Z			
106		10																											Z
226		22																										Z	
			16V	25V	50V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	500V	16V	25V	50V	100V	50V	100V	25V	50V
				0402				0603					0805					12	06				12	210		18	12	22	20



Letter	А	С	Е	G	J	K	М	N	Р	Q	Χ	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSED			

Automotive MLCC-X8R



Capacitance Range

	SIZ	E			0603	3		08	05			1206	
		WVDC	;	25V		50V		25V	50V		25V	50)V
271	C	ap 270		G		G							
331	(p	F) 330		G		G		J	J				
471		470		G		G		J	J				
681		680		G		G		J	J				
102		1000		G		G		J	J		J		J
152		1500		G		G		J	J		J		J
182		1800		G		G		J	J		J		J
222		2200		G		G		J	J		J		J
272		2700		G		G		J	J		J		J
332		3300		G		G		J	J		J		J
392		3900		G		G		J	J		J		J
472		4700		G		G		J	J		J		J
562		5600		G		G		J	J		J		J
682		6800		G		G		J	J		J		J
822		8200		G		G		J	J		J		J
103		ap 0.01		G		G		J	J		J		J
123	(µ			G		G		J	J		J		J
153		0.015		G		G		J	J		J		J
183		0.018		G		G		J	J		J		J
223		0.022		G		G		J	J		J		J
273		0.027		G		G		J	J		J		J
333		0.033		G		G		J	J		J		J
393		0.039		G		G		J	J		J		J
473		0.047		G		G		J	J		J		J
563		0.056		G				N	N		М	N N	
683		0.068		G				N	N		М	N	
823		0.082						N	N		М	N	
104		0.1						N	N		М	N	
124		0.12						N	N		М	N N	
154		0.15						N	N		М	N	
184		0.18						N			М	N	
224		0.22						N			М	N	
274		0.27									М	N N	
334		0.33									М	N	Л
394		0.39									М		
474		0.47									М		
684		0.68											
824		0.82											
105		1											
		WVDC		25V		50V		25V	50V		25V	50)V
	SIZE				060	3		30	305		1	1206	
Letter	А	С	l E	G	J	K	М	I N	ГР	Q	X	Υ	Z
			_	u	U	1 1				- Q			

 Letter
 A
 C
 E
 G
 J
 K
 M
 N
 P
 Q
 X
 Y
 Z

 Max.
 0.33
 0.56
 0.71
 0.90
 0.94
 1.02
 1.27
 1.40
 1.52
 1.78
 2.29
 2.54
 2.79

 Thickness
 (0.013)
 (0.022)
 (0.028)
 (0.035)
 (0.037)
 (0.040)
 (0.050)
 (0.055)
 (0.060)
 (0.070)
 (0.090)
 (0.100)
 (0.110)

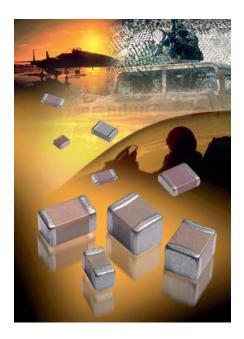
 PAPER
 EMBOSSED

= AEC-Q200 Qualified

APS Series

APS for COTS+ Applications





GENERAL DESCRIPTION

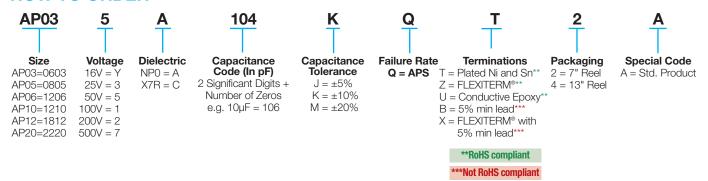
As part of our continuing support to high reliability customers, AVX has launched an Automotive Plus Series of parts (APS) qualified and manufactured in accordance with automotive AEC-Q200 standard. Each production batch is quality tested to an enhanced requirement and shipped with a certificate of conformance. On a quarterly basis a reliability package is issued to all APS customers.

A detailed qualification package is available on request and contains results on a range of part numbers including:

- X7R dielectric components containing BME electrode and copper terminations with a Ni/Sn plated overcoat.
- X7R dielectric components BME electrode and soft terminations with a Ni/Sn plated overcoat (FLEXITERM®).
- X7R for Hybrid applications.
- NP0 dielectric components containing Pd/Ag electrode and silver termination with a Ni/Sn plated overcoat.

We are also able to support customers who require an AEC-Q200 grade component finished with Tin/Lead.

HOW TO ORDER



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.





For RoHS compliant products, please select correct termination style.



NP0 Automotive Plus Series / APS



Capacitance Range

			0603			0805				1206				1:	210		18	312
		25V	50V	100V	25V	50V	100V	25V	50V	100V	200V	500V	25V	50V	100V	200V	50V	100V
100	10pF	G	G	G	J	J	J	J	J	J	J	J						
120	12	G	G	G	J	J	J	J	J	J	J	J						
150	15	G	G	G	J	J	٦	J	J	J	J	J						
180	18	G	G	G	J	J	J	J	J	J	J							
220	22	G	G	G	J	J	7	J	J	J	J							
270	27	G	G	G	J	J	J	J	J	J	J							
330	33	G	G	G	J	J	J	J	J	J	J							
390	39	G	G	G	J	J	J	J	J	J	J							
470	47	G	G	G	J	J	J	J	J	J	J							
510	51	G	G	G	J	J	J	J	J	J	J							
560	56	G	G	G	J	J	J	J	J	J	J							
680	68	G	G	G	J	J	J	J	J	J	J							
820	82	G	G	G	J	J	J	J	J	J	J							
101	100	G	G	G	J	J	J	J	J	J	J							
121	120	G	G	G	J	J	J	J	J	J	J							
151	150	G	G	G	J	J	J	J	J	J	J							
181	180	G	G	G	J	J	J	J	J	J	J							
221	220	G	G	G	J	J	J	J	J	J	J							
271	270	G	G	G	J	J	J	J	J	J	J							
331	330	G	G	G	J	J	J	J	J	J	J							
391	390	G	G		J	J	J	J	J	J	J							
471	470	G	G		J	J	J	J	J	J	J							
561	560				J	J	J	J	J	J	J							
681	680				J	J	J	J	J	J	J							
821	820				J	J	J	J	J	J	J							
102	1000				J	J	J	J	J	J	J		J	J	J	J		
122	1200							J	J	J			J	J	М	М		
152	1500							J	М	М			J	J	М	М		
182	1800							J	М	М			J	J	М	М		
222	2200							J	М	М			J	J	М	М		
272	2700							J	М				J	J	М			
332	3300							J	М				J	J	Р		K	K
392	3900				-	-				+			J	J	Р		K	K
472	4700				-	1				+			J	J	Р		K	K
103	10nF									1								
		25V	50V	100V	25V	50V	100V	25V	50V	100V	200V	500V	25V	50V	100V	200V	50V	100V
			0603			0805				1206				12	210		18	12
Let	ter	А	С		Е	G	J		K	М	N	Р		Q	Χ	Υ	Z	
Ma		0.33	0.5	6	0.71	0.90	0.94		.02	1.27	1.40	1.5		.78	2.29	2.54	2.7	
Thick		(0.013)			0.028)	(0.035)	(0.037			(0.050)	(0.055)	(0.06		.070)	(0.090)	(0.100)		
		(0.0.70)	(2.0.		APER	(2.223)	(2.20)	, (0.	-/	(/	()	,	/BOSSE		()	(550)	(51)	- /
	L			Γ/	u LII							LI	HOUGGL					

AEC-Q200 qualified TS 16949, ISO 9001 certified



X7R Automotive Plus Series / APS



Capacitance Range

				0603					0805					12	206				12	10		18	12	22	20
		16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	500V	16V	25V	50V	100V	50V	100V	25V	50V
102	Cap 1	G	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
182	(nF) 1.8	G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K	$\overline{}$	
222	2.2	G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
332	3.3	G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
472	4.7	G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
103	10	G	G	G	G		J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	K	K		
123	12	G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
153	15	G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
183	18	G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
223	22	G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
273	27	G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
333	33	G	G	G			J	J	J	М		J	J	J	J	J		K	K	K	K	K	K		
473	47	G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	K	K	K		
563	56	G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	М	K	K		
683	68	G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	М	K	K		
823	82	G	G	G			J	J	J	М		J	J	J	М	J		K	K	K	М	K	K		
104	100	G	G	G			J	J	М	М		J	J	J	М	J		K	K	K	М	K	K		
124	120						J	J	М			J	J	М	М			K	K	K	Р	K	K		
154	150						М	N	М			J	J	M	М			K	K	K	Р	K	K		
224	220						М	N	М			J	М	М	Q			М	М	М	Р	М	М		
334	330						N	N	М			J	М	Р	Q			Р	Р	Р	Q	Χ	Χ		
474	470						N	N	М			М	М	Р	Q			Р	Р	Р	Q	Χ	Х		
684	680						N	N				М	Q	Q	Q			Р	Р	Q	Х	Χ	Χ		
105	Cap 1						N	N				М	Q	Q	Q			Р	Q	Q	Х	Χ	Х		
155	(μF) 1.5											Q	Q					Р	Q	Z	Z	Χ	Χ		
225	2.2											Q	Q					Χ	Z	Z	Z	Z	Z		
335	3.3																	Χ	Z	Z		Z			
475	4.7											İ						Χ	Z	Z		Z			
106	10																							\Box	Z
226	22											İ												Ζ	
		16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	500V	16V	25V	50V	100V	50V	100V	25V	50V
				0603					0805					12	206				12	210		18	12	22	20

= Under Development

Letter	А	С	Е	G	J	K	М	N	Р	Q	Х	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						FMBC	SSED			

AEC-Q200 qualified TS 16949, ISO 9001 certified



General Specifications



GENERAL DESCRIPTION

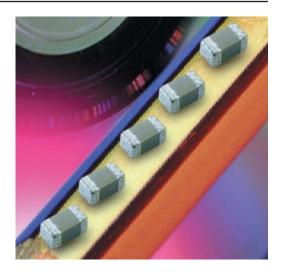
With increased requirements from the automotive industry for additional component robustness, AVX recognized the need to produce a MLCC with enhanced mechanical strength. It was noted that many components may be subject to severe flexing and vibration when used in various under the hood automotive and other harsh environment applications.

To satisfy the requirement for enhanced mechanical strength, AVX had to find a way of ensuring electrical integrity is maintained whilst external forces are being applied to the component. It was found that the structure of the termination needed to be flexible and after much research and development, AVX launched FLEXITERM®. FLEXITERM® is designed to enhance the mechanical flexure and temperature cycling performance of a standard ceramic capacitor with an X7R dielectric. The industry standard for flexure is 2mm minimum. Using FLEXITERM®, AVX provides up to 5mm of flexure without internal cracks. Beyond 5mm, the capacitor will generally fail "open".

As well as for automotive applications FLEXITERM® will provide Design Engineers with a satisfactory solution when designing PCB's which may be subject to high levels of board flexure.

PRODUCT ADVANTAGES

- High mechanical performance able to withstand, 5mm bend test guaranteed.
- Increased temperature cycling performance, 3000 cycles and beyond.
- Flexible termination system.
- Reduction in circuit board flex failures.
- Base metal electrode system.
- Automotive or commercial grade products available.



APPLICATIONS

High Flexure Stress Circuit Boards

 e.g. Depanelization: Components near edges of board.

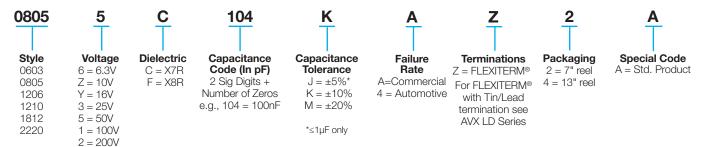
Variable Temperature Applications

- Soft termination offers improved reliability performance in applications where there is temperature variation.
- e.g. All kind of engine sensors: Direct connection to battery rail.

Automotive Applications

- Improved reliability.
- Excellent mechanical performance and thermo mechanical performance.

HOW TO ORDER



NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.







For RoHS compliant products, please select correct termination style.







PERFORMANCE TESTING

AEC-Q200 Qualification:

• Created by the Automotive Electronics Council

 Specification defining stress test qualification for passive components

Testing:

Key tests used to compare soft termination to

AEC-Q200 qualification:

- Bend Test
- Temperature Cycle Test

BOARD BEND TEST PROCEDURE

According to AEC-Q200

Test Procedure as per AEC-Q200: Sample size: 20 components Span: 90mm Minimum deflection spec: 2 mm

- Components soldered onto FR4 PCB (Figure 1)
- Board connected electrically to the test equipment (Figure 2)

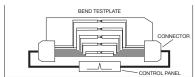


Fig 2 - Board Bend test equipment

al-lo

MOUNTING

CONTROL

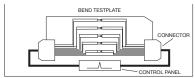
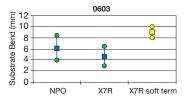
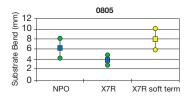


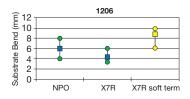
Fig 1 - PCB layout with electrical connections

BOARD BEND TEST RESULTS

AEC-Q200 Vrs AVX FLEXITERM® Bend Test







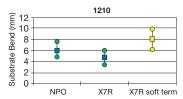


TABLE SUMMARY

Typical bend test results are shown below:

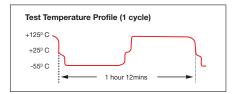
Style Conventional Termination FLEXITERM® 0603 >2mm >5mm 0805 >2mm >5mm 1206 >2mm >5mm

TEMPERATURE CYCLE TEST PROCEDURE

Test Procedure as per AEC-Q200:

The test is conducted to determine the resistance of the component when it is exposed to extremes of alternating high and low temperatures.

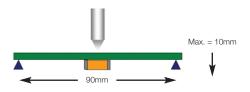
- Sample lot size quantity 77 pieces
- TC chamber cycle from -55°C to +125°C for 1000 cycles
- Interim electrical measurements at 250, 500, 1000 cycles
- Measure parameter capacitance dissipation factor. insulation resistance



AVX ENHANCED SOFT **TERMINATION BEND TEST PROCEDURE**

Bend Test

The capacitor is soldered to the printed circuit board as shown and is bent up to 10mm at 1mm per second:



- The board is placed on 2 supports 90mm apart (capacitor side down)
- The row of capacitors is aligned with the load stressing knife



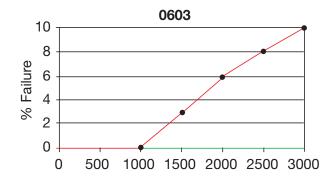
- The load is applied and the deflection where the part starts to crack is recorded (Note: Equipment detects the start of the crack using a highly sensitive current detection
- The maximum deflection capability is 10mm

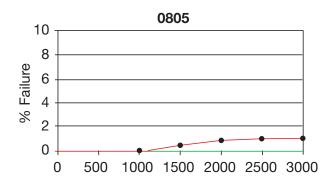


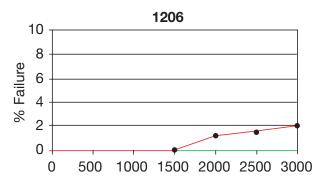


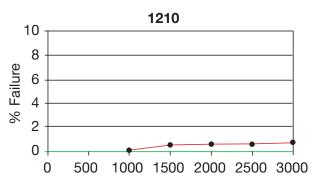


BEYOND 1000 CYCLES: TEMPERATURE CYCLE TEST RESULTS









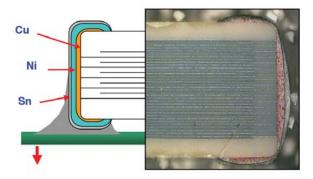
Soft Term - No Defects up to 3000 cycles

AEC-Q200 specification states 1000 cycles compared to AVX 3000 temperature cycles.

FLEXITERM® TEST SUMMARY

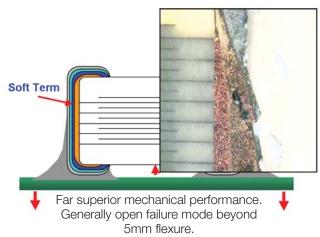
- Qualified to AEC-Q200 test/specification with the exception of using AVX 3000 temperature cycles (up to +150°C bend test guaranteed greater than 5mm).
- FLEXITERM® provides improved performance compared to standard termination systems.
- Board bend test improvement by a factor of 2 to 4 times.
- Temperature Cycling:
 - 0% Failure up to 3000 cycles
 - No ESR change up to 3000 cycles

WITHOUT SOFT TERMINATION



Major fear is of latent board flex failures.

WITH SOFT TERMINATION







X8R Dielectric Capacitance Range

	SIZ	E.			0603	3		08	05			1206	
		WVDC	;	25V		50V		25V	50V		25V	5	OV
271	С	ap 270		G		G							
331	(p	F) 330		G		G		J	J				
471		470		G		G		J	J				
681		680		G		G		J	J				
102		1000		G		G		J	J		J		J
152		1500		G		G		J	J		J		J
182		1800		G		G		J	J		J		J
222		2200		G		G		J	J		J		J
272		2700		G		G		J	J		J		J
332		3300		G		G		J	J		J		J
392		3900		G		G		J	J		J		J
472		4700		G		G		J	J		J		J
562		5600		G		G		J	J		J		J
682		6800		G		G		J	J		J		J
822		8200		G		G		J	J		J		J
103		ap 0.01		G		G		J	J		J		J
123	(µ			G		G		J	J		J		J
153		0.015		G		G		J	J		J		J
183		0.018		G		G		J	J		J		J
223		0.022		G		G		J	J		J		J
273		0.027		G		G		J	J		J		J
333		0.033		G		G		J	J		J		J
393		0.039		G		G		J	J		J		J
473		0.047		G		G		J	J		J		J
563		0.056		G				N	N		М		M
683		0.068		G				N	N		М		M
823		0.082						N	N		М		М
104		0.1						N	N		М		M
124		0.12						N	N		М		M
154		0.15						N	N		М		M
184		0.18						N			М		М
224		0.22						N			М		M
274		0.27									М		M
334		0.33									М	1	M
394		0.39									М		
474		0.47									М		
684		0.68											
824		0.82											
105		1											
		WVDC		25V		50V		25V	50V		25V		0V
	SIZ	E.			060	3		30	305		1	1206	
Letter	А	С	Е	G	J	K	М	N	Р	Q	X	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78		2.54	2.79
Thickness	(0.012)		(0.000)						(0.060)		(0.000)	(0.100)	

 Letter
 A
 C
 E
 G
 J
 K
 M
 N
 P
 Q
 X
 Y
 Z

 Max.
 0.33
 0.56
 0.71
 0.90
 0.94
 1.02
 1.27
 1.40
 1.52
 1.78
 2.29
 2.54
 2.79

 Thickness
 (0.013)
 (0.022)
 (0.028)
 (0.035)
 (0.037)
 (0.040)
 (0.050)
 (0.055)
 (0.060)
 (0.070)
 (0.090)
 (0.100)
 (0.110)

 PAPER
 EMBOSSED

= AEC-Q200 Qualified





X7R Dielectric Capacitance Range

			0603	3				30	305					1206				12	10			18	312			2220	
	16V	25V	50V	100V	200V	10V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	16V	25V	50V	100V	16V	25V	50V	100V	25V	50V	100V
101																											_
121 151																											
181				-								_					_				\vdash						\vdash
221																											\vdash
271	J	J	J	J	J	J																					
331	J	J	J	J	J	J	J	J	J	J	J																
391	J	J	J	J	J	J	J	J	J	J	J																_
471 561	J	J	J	J	J	J	J	J	J	J	J													-			-
681	J	J	J	J	J	J	.l	J	J	J	J	-					_							-	_		\vdash
821	J	J	J	J	J	J	J	J	J	J	J																\vdash
102	J	J	J	J	J	J	J	J	J	J	J	J	J	J	J	J											
122	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J											
152	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J											
182	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J											₩
222 272	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J					-				-		-
332	, l	J	.I	.l		J	J	, J	J	J	,l	J	, l	, J	.l	J					 			+	 	<u> </u>	
392	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J											
472	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J											
562	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J											
682	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J											_
822	J	J	J	J		J	J	J	J	J	J	J	J	J	J	J								-			-
103 123	J	J	J	J		J	J	J	J	J M	J	J	J	J	J	J	-	_			<u> </u>			-	\vdash		₩
153	J	J	J			J	J	J	J	M		J	J	J	J	J											
183	J	J	J			J	J	J	J	М		J	J	J	J	J											
223	J	J	J			J	J	J	J	М		J	J	J	J	J				K							
273	J	J	J			J	J	J	J	М		J	J	J	J	J				K							
333	J	J	J			J	J	J	J	М		J	J	J	J M	J				K							
393 473	J	J	J			J	J	J	J	M		J J	J	J	M	J				K							-
563	J	J	J			J	J	J	J	N		J	J	J	M	J	K	K	K	M	K	K	K	K			
683	J	J	J			J	J	J	J	N		J	J	J	М	J	K	K	K	М	K	K	K	K			\vdash
823	J	J	J			J	J	J	J	N		J	J	J	Р	J	K	K	K	М	K	K	K	K			
104	J	J	J			J	J	J	J	N		J	J	J	Q	J	K	K	K	Р	K	K	K	K	Χ	Х	Х
124						J	J	J	N	N		J	J	Р	Q		K	K	K	Q	K	K	K	K	N/	\ \	- >/
154 184						M M	M M	N N	N N	N N		J	M	P P	Q Q		K M	K M	K M	Q Q	K	K	K	M	Х	Х	Х
224						M	M	N	N	N		J	M	Р	Q		M	M	M	Q	M	M	M	X	Х	Х	Х
274						N	N	N	N	N		J	М	Р	Q		Р	Р	Р	Q	М	М	М	X			
334						N	N	N	N	N		J	М	Р	Q		Р	Р	Р	Q	М	М	М	Х	Χ	Χ	Х
394						N	N	N	N	N		М	М	Р	Q		Р	Р	Р	Q	Х	Х	Х	Х			
474			-	-	_	N	N	N	N	N		M	M	Р	Q		Р	Р	Р	Q	X	X	X	X	X	Х	X
564 684		_		1	-	N N	N N	N N		-	-	M M	Q Q	Q Q	Q Q		P P	Q X	Q X	Q X	X	X	X	7	Y	Х	Y
824				1		N	N	N				M	Q	Q	Q		Р	Z	7	7	X	X	X	7	٨	^	^
105						N	N	N				M	Q	Q	Q		P	Z	Z	Z	X	X	X	Z	Χ	Х	Х
155												Q	Q				Р	Z	Z	Z			Z	Z	Х	Х	Х
185												Q	Q				Z	Z	Z	Z			Z	Z			
225 335				-								Q	Q				Z	Z	Z	Z			Z	Z	Χ	Х	X
335 475		_		1	-	-	-	-	-	-	-	\vdash		-		-	Z	Z 7	Z 7		\vdash	-	Z		-		Z
106		_				 															<u> </u>				Z	Z	
226																									Z		
	16V	25V	50V	100V	200V	10V	16V	25V	50V	100V	200V	16V	25V	50V	100V	200V	16V	25V	50V	100V	16V	25V	50V	100V	25V	50V	100V
			0603						05					1206				12					12			2220	
16	tter	Д		С		Е		G	J		K		М		N I	Р		Q		Χ	Y	/	Z				
	ax.	0.3		0.56		0.71		.90	0.9		1.02		1.27		.40	1.52)	1.78	1	2.29	2.5		2.79	9			
141	мΛι	(0.0		(0.00		0.71		.50	(0.0		1.02		1.21	(0)		(0.00	- 1	(0.070)		2.23	(0.1		2.13				

Letter	А	С	E	G	J	K	М	N	Р	Q	Χ	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSED			

FLEXISAFE MLC Chips

For Ultra Safety Critical Applications



AVX have developed a range of components specifically for safety critical applications.

Utilizing the award-winning FLEXITERM™ layer in conjunction with the cascade design previously used for high voltage MLCCs, a range of ceramic capacitors is now available for customers who require components designed with an industry leading set of safety features.

The FLEXITERM™ layer protects the component from any damage to the ceramic resulting from mechanical stress during PCB assembly or use with end customers. Board flexure type mechanical damage accounts for the majority of MLCC failures. The addition of the cascade structure protects the component from low insulation resistance failure resulting from other common causes for failure; thermal stress damage, repetitive strike ESD damage and placement damage. With the inclusion of the cascade design structure to complement the FLEXITERM™ layer, the FLEXISAFE range of capacitors has unbeatable safety features.

HOW TO ORDER



FS03 = 0603 FS05 = 0805

FS06 = 1206 FS10 = 1210 <u>5</u>

Voltage

16V = Y 25V = 3

50V = 5

100V = 1

C

Dielectric

104

 Capacitance Code (In pF)
 Cap To

 2 Sig. Digits + Number of Zeros
 J : K : Zeros

 e.g. 10µF =106



Capacitance Tolerance $J = \pm 5\%$ $K = \pm 10\%$ $M = \pm 20\%$ Q

Failure Rate A = Commercial 4 = Automotive Q = APS **Z**

Terminations
Z = FLEXITERM™
X = FLEXITERM™
with 5%
min lead

<u>2</u>

Packaging 2 = 7" Reel 4 = 13" Reel **A** |

Special Code A = Std. Product

FLEXISAFE X7R RANGE

Capac	citance		0603				08	05			1206			1210	
Code	nF	16	25	50	100	16	25	50	100	16	25	50	16	25	50
102	1														
182	1.8														
222	2.2														
332	3.3														
472	4.7														
103	10														
123	12														
153	15														
183	18														
223	22														
273	27														
333	33														
473	47														
563	56														
683	68														
823	82														
104	100														
124	120														
154	150														
224	220														
334	330														
474	470														

Qualified In Qualification

Not RoHS Compliant





For RoHS compliant products, please select correct termination style.



Capacitor Array (IPC)



BENEFITS OF USING CAPACITOR ARRAYS

AVX capacitor arrays offer designers the opportunity to lower placement costs, increase assembly line output through lower component count per board and to reduce real estate requirements.

Reduced Costs

Placement costs are greatly reduced by effectively placing one device instead of four or two. This results in increased throughput and translates into savings on machine time. Inventory levels are lowered and further savings are made on solder materials, etc.

Space Saving

Space savings can be quite dramatic when compared to the use of discrete chip capacitors. As an example, the 0508 4-element array offers a space reduction of >40% vs. 4 x 0402 discrete capacitors and of >70% vs. 4 x 0603 discrete capacitors. (This calculation is dependent on the spacing of the discrete components.)

Increased Throughput

Assuming that there are 220 passive components placed in a mobile phone:

A reduction in the passive count to 200 (by replacing discrete components with arrays) results in an increase in throughput of approximately 9%.

A reduction of 40 placements increases throughput by 18%.

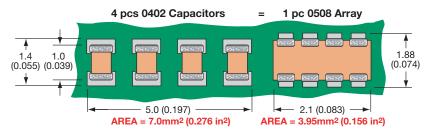
For high volume users of cap arrays using the very latest placement equipment capable of placing 10 components per second, the increase in throughput can be very significant and can have the overall effect of reducing the number of placement machines required to mount components:

If 120 million 2-element arrays or 40 million 4-element arrays were placed in a year, the requirement for placement equipment would be reduced by one machine.

During a 20Hr operational day a machine places 720K components. Over a working year of 167 days the machine can place approximately 120 million. If 2-element arrays are mounted instead of discrete components, then the number of placements is reduced by a factor of two and in the scenario where 120 million 2-element arrays are placed there is a saving of one pick and place machine.

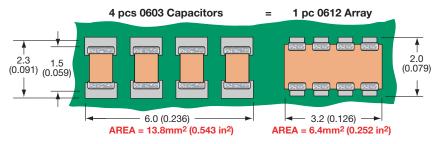
Smaller volume users can also benefit from replacing discrete components with arrays. The total number of placements is reduced thus creating spare capacity on placement machines. This in turn generates the opportunity to increase overall production output without further investment in new equipment.

W2A (0508) Capacitor Arrays



The 0508 4-element capacitor array gives a PCB space saving of over 40% vs four 0402 discretes and over 70% vs four 0603 discrete capacitors.

W3A (0612) Capacitor Arrays

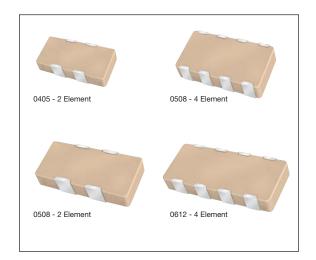


The 0612 4-element capacitor array gives a PCB space saving of over 50% vs four 0603 discretes and over 70% vs four 0805 discrete capacitors.









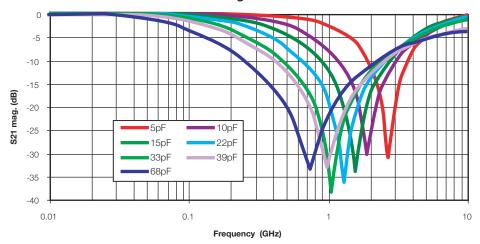
GENERAL DESCRIPTION

AVX is the market leader in the development and manufacture of capacitor arrays. The smallest array option available from AVX, the 0405 2-element device, has been an enormous success in the Telecommunications market. The array family of products also includes the 0612 4-element device as well as 0508 2-element and 4-element series, all of which have received widespread acceptance in the marketplace.

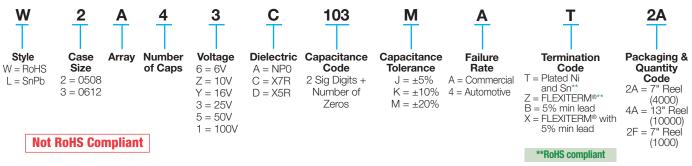
AVX capacitor arrays are available in X5R, X7R and NP0 (C0G) ceramic dielectrics to cover a broad range of capacitance values. Voltage ratings from 6.3 Volts up to 100 Volts are offered. AVX also now offers a range of automotive capacitor arrays qualified to AEC-Q200 (see separate table).

Key markets for capacitor arrays are Mobile and Cordless Phones, Digital Set Top Boxes, Computer Motherboards and Peripherals as well as Automotive applications, RF Modems, Networking Products, etc.

AVX Capacitor Array - W2A41A***K S21 Magnitude



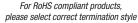
HOW TO ORDER







NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.







Capacitance Range – NP0/C0G

SIZE			0508			0612	
# Elements			4			4	
Soldering	,	Re	eflow/Wav	Δ	Re	eflow/Wav	۵
Packaging			er/Emboss			er/Emboss	
	mm		$.30 \pm 0.15$			$.60 \pm 0.15$	
Length	(in.)	(0.0)	0.00 ± 0.00	06)	(0.0	0.00000000000000000000000000000000000	06)
Width	mm (in.)		.10 ± 0.15			3.20 ± 0.2 126 ± 0.0	-
Max.	mm	,	0.94	,	,	1.35	,
Thickness	(in.)		(0.037)			(0.053)	
WVDC		16	25	50	16	25	50
1R0 Cap	1.0						
1R2 (pF) 1R5	1.2 1.5						
1R8	1.8						
2R2	2.2						
2R7	2.7						
3R3	3.3						
3R9	3.9						
4R7	4.7						
5R6 6R8	5.6 6.8						
8R2	8.2						
100	10						
120	12						
150	15						
180	18						
220 270	22 27						
330	33						
390	39						
470	47						
560	56						
680	68						
820	82						
101 121	100 120						
151	150						
	180						
	220						
	270						
	330						
	390 470						
	560						
	680						
821	820						
	000						
	200						
	500 800		-				
	200						
	700						
	300						
	900						
	700						
	600						
	800 200						
022 0	200		L			<u> </u>	

= Supported Values



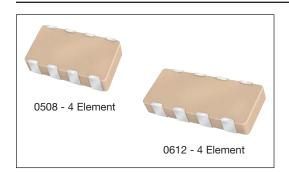
Capacitance Range - X7R

9	SIZE			0.5	508					0.5	508					Of	612		
	ements	\vdash			2			\vdash			4			\vdash			4		-
	oldering				v/Wav	۵					v/Wav	۵					- v/Wav	Δ	-
	ckaging				Paper						mboss						mbos		-
Length	mm				± 0.15						± 0.15						± 0.15		
Lengui	(in.)		(0	.051 :	± 0.00	6)			(0	0.051	± 0.00	16)			((0.063	± 0.00	06)	
Width	mm (in.)				± 0.15 ± 0.00				(0		± 0.15 ± 0.00				((± 0.20 ± 0.00		
Max.	mm			0.	94					0.	.94					1	.35		
Thickne	,				037)						037)					_	053)		
	NDC	6	10	16	25	50	100	6	10	16	25	50	100	6	10	16	25	50	100
	Cap 100 (pF) 120																		
151	150																		
181	180																		
221	220																		
271	270																		
331	330																		
391 471	390 470																		
561	560																		
681	680																		
821	820																		
102	1000																		
122 152	1200 1500																		
182	1800																		
222	2200																		
272	2700																		
332	3300																		
392	3900																		
472 562	4700 5600																		
682	6800																		
822	8200																		
	Cap 0.010																		
	μF) 0.012																		
153	0.015																		
183 223	0.018 0.022																		
273	0.027																		
333	0.033																		
393	0.039																		
473 563	0.047																		\vdash
683	0.056																		
823	0.082																		
104	0.10																		
124	0.12																		
154 184	0.15 0.18										-				_			-	$\vdash\vdash$
224	0.18																		
274	0.27											L						L	
334	0.33																		
474	0.47																		
564 684	0.56													-				-	$\vdash\vdash$
824	0.68																		
105	1.0	L								L		L		L		L	L	L	L ∣
125	1.2																		
155	1.5																		
185	1.8	\vdash						_			_			<u> </u>	_			_	$\vdash\vdash$
225 335	2.2 3.3																		
475	4.7																		
106	10																		
226	22																		
476 107	47 100																		
107	100	<u> </u>																	Ш



Automotive Capacitor Array (IPC)



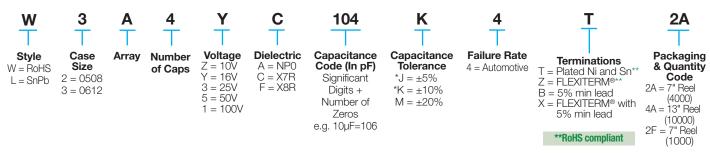


As the market leader in the development and manufacture of capacitor arrays AVX is pleased to offer a range of AEC-Q200 qualified arrays to compliment our product offering to the Automotive industry. Both the AVX 0612 and 0508 4-element capacitor array styles are qualified to the AEC-Q200 automotive specifications.

AEC-Q200 is the Automotive Industry qualification standard and a detailed qualification package is available on request.

All AVX automotive capacitor array production facilities are certified to ISO/TS 16949:2002.

HOW TO ORDER



SIZE

No. of Elements

0508

^{*}Contact factory for availability by part number for $K = \pm 10\%$ and $J = \pm 5\%$ tolerance.

			NF	P0/C	COG				
S	IZE		05	80			06	12	
No. of	Elements			4				4	
	WVDC	16	25	50	100	16	25	50	100
1R0 1R2 1R5	Cap 1.0 (pF) 1.2 1.5								
1R8 2R2 2R7	1.8 2.2 2.7								
3R3 3R9 4R7	3.3 3.9 4.7								
5R6 6R8 8R2	5.6 6.8 8.2								
100 120 150	10 12 15								
180 220 270	18 22 27								
330 390 470	33 39 47								
560 680 820	56 68 82								
101 121 151	100 120 150								
181 221 271	180 220 270								
331 391 471	330 390 470								
561 681 821	560 680 820								
102 122 152	1000 1200 1500								
182 222 272	1800 2200 2700								
332 392 472	3300 3900 4700								
562 682 822	5600 6800 8200								

= NPO/COG

	WVDC	16	25	50	100	16	25	50	100	10	16	25	50	100	16
101 121 151	Cap 100 (pF) 120 150														
181 221 271	180 220 270														
331 391 471	330 390 470														
561 681 821	560 680 820														
102 122 152	1000 1200 1500														
182 222 272	1800 2200 2700														
332 392 472	3300 3900 4700														
562 682 822	5600 6800 8200														
103 123 153	Cap 0.010 (µF) 0.012 0.015														
183 223 273	0.018 0.022 0.027														
333 393 473	0.033 0.039 0.047														
563 683 823	0.056 0.068 0.082														
104 124 154	0.10 0.12 0.15														
224	0.22														
-	X7R														

X7R

0508

= X7R = X8R

Not RoHS Compliant





X8R

0405

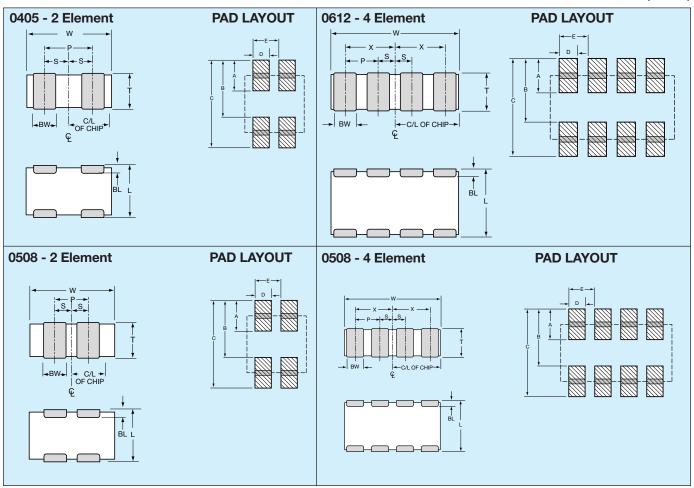
0612





PART & PAD LAYOUT DIMENSIONS

millimeters (inches)



PART DIMENSIONS

0405 - 2 Element

L	W	Т	BW	BL	Р	S
1.00 ± 0.15	1.37 ± 0.15	0.66 MAX	0.36 ± 0.10	0.20 ± 0.10	0.64 REF	0.32 ± 0.10
(0.039 ± 0.006)	(0.054 ± 0.006)	(0.026 MAX)	(0.014 ± 0.004)	(0.008 ± 0.004)	(0.025 REF)	(0.013 ± 0.004)

0508 - 2 Element

L	W	T	BW	BL	Р	S
=	2.10 ± 0.15 (0.083 ± 0.006)	0.94 MAX (0.037 MAX)	0.43 ± 0.10 (0.017 ± 0.004)		1.00 REF (0.039 REF)	0.50 ± 0.10 (0.020 ± 0.004)

0508 - 4 Element

L	W	Т	BW	BL	Р	X	S	
1.30 ± 0.15	2.10 ± 0.15	0.94 MAX	0.25 ± 0.06	0.20 ± 0.08	0.50 REF	0.75 ± 0.10	0.25 ± 0.10	ı
(0.051 ± 0.006)	(0.083 ± 0.006)	(0.037 MAX)	(0.010 ± 0.003)	(0.008 ± 0.003)	(0.020 REF)	(0.030 ± 0.004)	(0.010 ± 0.004)	ı

0612 - 4 Element

L	W	Т	BW	BL	Р	Х	S
1.60 ± 0.20 (0.063 ± 0.008)	3.20 ± 0.20 (0.126 ± 0.008)		0.41 ± 0.10 (0.016 ± 0.004)		0.76 REF (0.030 REF)	1.14 ± 0.10 (0.045 ± 0.004)	

PAD LAYOUT DIMENSIONS

0405 - 2 Element

Α	ВС		D	Е		
0.46	0.74	1.20	0.30	0.64		
(0.018)	(0.029)	(0.047)	(0.012)	(0.025)		

0508 - 2 Element

Α	В	С	D	E		
0.68	1.32	2.00	0.46	1.00		
(0.027)	(0.052)	(0.079)	(0.018)	(0.039)		

0508 - 4 Element

Α	B C		D	E	
0.56	1.32	1.88	0.30	0.50	
(0.022)	(0.052)	(0.074)	(0.012)	(0.020)	

0612 - 4 Element

Α	В	С	D	Е
0.89	1.65	2.54	0.46	0.76
(0.035)	(0.065)	(0.100)	(0.018)	(0.030)



Low Inductance Capacitors

Introduction

The signal integrity characteristics of a Power Delivery Network (PDN) are becoming critical aspects of board level and semiconductor package designs due to higher operating frequencies, larger power demands, and the ever shrinking lower and upper voltage limits around low operating voltages. These power system challenges are coming from mainstream designs with operating frequencies of 300MHz or greater, modest ICs with power demand of 15 watts or more, and operating voltages below 3 volts.

The classic PDN topology is comprised of a series of capacitor stages. Figure 1 is an example of this architecture with multiple capacitor stages.

An ideal capacitor can transfer all its stored energy to a load instantly. A real capacitor has parasitics that prevent instantaneous transfer of a capacitor's stored energy. The true nature of a capacitor can be modeled as an RLC equivalent circuit. For most simulation purposes, it is possible to model the characteristics of a real capacitor with one

capacitor, one resistor, and one inductor. The RLC values in this model are commonly referred to as equivalent series capacitance (ESC), equivalent series resistance (ESR), and equivalent series inductance (ESL).

The ESL of a capacitor determines the speed of energy transfer to a load. The lower the ESL of a capacitor, the faster that energy can be transferred to a load. Historically, there has been a tradeoff between energy storage (capacitance) and inductance (speed of energy delivery). Low ESL devices typically have low capacitance. Likewise, higher capacitance devices typically have higher ESLs. This tradeoff between ESL (speed of energy delivery) and capacitance (energy storage) drives the PDN design topology that places the fastest low ESL capacitors as close to the load as possible. Low Inductance MLCCs are found on semiconductor packages and on boards as close as possible to the load.

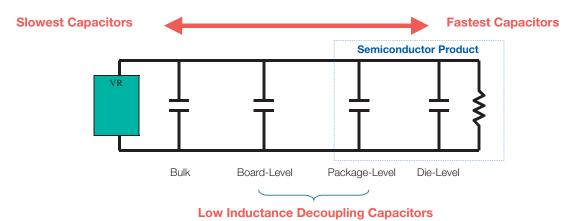


Figure 1 Classic Power Delivery Network (PDN) Architecture

LOW INDUCTANCE CHIP CAPACITORS

The key physical characteristic determining equivalent series inductance (ESL) of a capacitor is the size of the current loop it creates. The smaller the current loop, the lower the ESL. A standard surface mount MLCC is rectangular in shape with electrical terminations on its shorter sides. A Low Inductance Chip Capacitor (LICC) sometimes referred to as Reverse Geometry Capacitor (RGC) has its terminations on the longer side of its rectangular shape.

When the distance between terminations is reduced, the size of the current loop is reduced. Since the size of the current loop is the primary driver of inductance, an 0306 with a smaller current loop has significantly lower ESL then an 0603. The reduction in ESL varies by EIA size, however, ESL is typically reduced 60% or more with an LICC versus a standard MLCC.

INTERDIGITATED CAPACITORS

The size of a current loop has the greatest impact on the ESL characteristics of a surface mount capacitor. There is a secondary method for decreasing the ESL of a capacitor. This secondary method uses adjacent opposing current loops to reduce ESL. The InterDigitated Capacitor (IDC) utilizes both primary and secondary methods of reducing inductance. The IDC architecture shrinks the distance between terminations to minimize the current loop size, then further reduces inductance by creating adjacent opposing current loops.

An IDC is one single capacitor with an internal structure that has been optimized for low ESL. Similar to standard MLCC versus LICCs, the reduction in ESL varies by EIA case size. Typically, for the same EIA size, an IDC delivers an ESL that is at least 80% lower than an MLCC.



Low Inductance Capacitors





LAND GRID ARRAY (LGA) CAPACITORS

Land Grid Array (LGA) capacitors are based on the first Low ESL MLCC technology created to specifically address the design needs of current day Power Delivery Networks (PDNs). This is the 3rd low inductance capacitor technology developed by AVX. LGA technology provides engineers with new options. The LGA internal structure and manufacturing technology eliminates the historic need for a device to be physically small to create small current loops to minimize inductance.

The first family of LGA products are 2 terminal devices. A 2 terminal 0306 LGA delivers ESL performance that is equal to or better than an 0306 8 terminal IDC. The 2 terminal 0805 LGA delivers ESL performance that approaches the 0508 8 terminal IDC. New designs that would have used 8 terminal IDCs are moving to 2 terminal LGAs because the layout is easier for a 2 terminal device and manufacturing yield is better for a 2 terminal LGA versus an 8 terminal IDC.

LGA technology is also used in a 4 terminal family of products that AVX is sampling and will formerly introduce in 2008. Beyond 2008, there are new multi-terminal LGA product families that will provide even more attractive options for PDN designers.

LOW INDUCTANCE CHIP ARRAYS (LICA®)

The LICA® product family is the result of a joint development effort between AVX and IBM to develop a high performance MLCC family of decoupling capacitors. LICA was introduced in the 1980s and remains the leading choice of designers in high performance semiconductor packages and high reliability board level decoupling applications.

LICA® products are used in 99.999% uptime semiconductor package applications on both ceramic and organic substrates. The C4 solder ball termination option is the perfect compliment to flip-chip packaging technology. Mainframe class CPUs, ultimate performance multi-chip modules, and communications systems that must have the reliability of 5 9's use LICA®.

LICA® products with either Sn/Pb or Pb-free solder balls are used for decoupling in high reliability military and aerospace applications. These LICA® devices are used for decoupling of large pin count FPGAs, ASICs, CPUs, and other high power ICs with low operating voltages.

When high reliability decoupling applications require the very lowest ESL capacitors, LICA® products are the best option.

470 nF 0306 Impedance Comparison

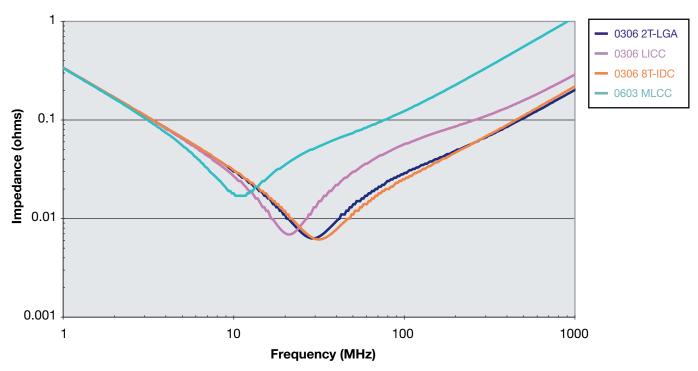


Figure 2 MLCC, LICC, IDC, and LGA technologies deliver different levels of equivalent series inductance (ESL).



Low Inductance Capacitors (RoHS)



0612/0508/0306/0204 LICC (Low Inductance Chip Capacitors)

GENERAL DESCRIPTION

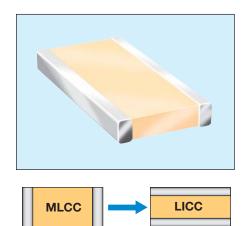
The key physical characteristic determining equivalent series inductance (ESL) of a capacitor is the size of the current loop it creates. The smaller the current loop, the lower the ESL.

A standard surface mount MLCC is rectangular in shape with electrical terminations on its shorter sides. A Low Inductance Chip Capacitor (LICC) sometimes referred to as Reverse Geometry Capacitor (RGC) has its terminations on the longer sides of its rectangular shape. The image on the right shows the termination differences between an MLCC and an LICC.

When the distance between terminations is reduced, the size of the current loop is reduced. Since the size of the current loop is the primary driver of inductance, an 0306 with a smaller current loop has significantly lower ESL then an 0603. The reduction in ESL varies by EIA size, however, ESL is typically reduced 60% or more with an LICC versus a standard MLCC.

AVX LICC products are available with a lead-free finish of plated Nickel/Tin.

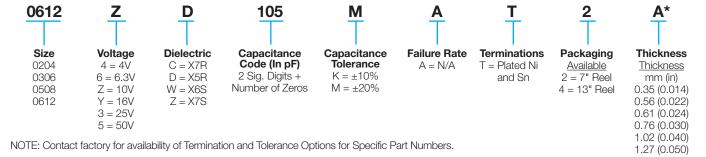




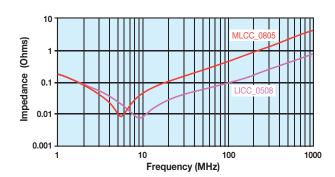
PERFORMANCE CHARACTERISTICS

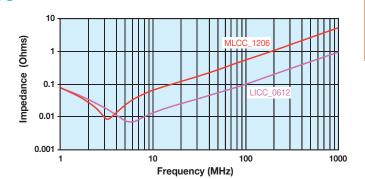
Capacitance Tolerances	$K = \pm 10\%$; $M = \pm 20\%$
Operation	X7R = -55°C to +125°C
Temperature Range	X5R = -55°C to $+85$ °C
	$X7S = -55^{\circ}C \text{ to } +125^{\circ}C$
Temperature Coefficient	X7R, X5R = ±15%; X7S = ±22%
Voltage Ratings	4, 6.3, 10, 16, 25 VDC
Dissipation Factor	4V, 6.3V = 6.5% max; 10V = 5.0% max; 16V = 3.5% max; 25V = 3.0% max
Insulation Resistance (@+25°C, RVDC)	100,000M Ω min, or 1,000M Ω per μF min.,whichever is less

HOW TO ORDER



TYPICAL IMPEDANCE CHARACTERISTICS







Low Inductance Capacitors (RoHS)



0612/0508/0306/0204 LICC (Low Inductance Chip Capacitors)

		UZ	04			0306					0508				0612					
Packaging						Embossed					Embossed				Embossed					
Length mm (in.)						0.81 ± 0.15 (0.032 ± 0.000					1.27 ± 0.25 (0.050 ± 0.010)				1.60 ± 0.25 (0.063 ± 0.010)					
Width mm					Г		1.60 :	€ 0.15	5			2.0	0 ± 0.	.25		3.20 ± 0.25				
WVDC	4	6.3	10	16	4	6.3	10	16	25	50	6.3	10	0 ± 0.	25	50	6.3	10.12	6 ± 0	25	50
CAP 0.001																				
(μF) 0.0022																				
0.0047																				
0.010																				
0.015																				
0.022																				
0.047																				
0.068																				
0.10																				
0.15																				
0.22																				
0.47																				
0.68																				
1.0					Ш															
1.5					L															
2.2																				
3.3											L									
4.7																				
10																				
Solid = X	7F	2				= 2	(5 F	?				= 2	(78	3		= X6S				
	m (in.)					nm	(in.)					nm ((in.)		mm (in.)				
0204					_	D30 Thic					_ ()508	3				(061	2	

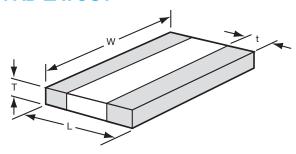
0.61 (0.024)

0.56 (0.022)

0.76 (0.030)

1.02 (0.040)

PHYSICAL DIMENSIONS AND PAD LAYOUT



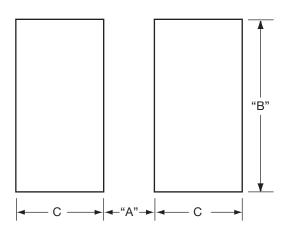
PHYSICAL CHIP DIMENSIONS mm (in)

	L	W	t		
0612	1.60 ± 0.25	3.20 ± 0.25	0.13 min.		
	(0.063 ± 0.010)	(0.126 ± 0.010)	(0.005 min.)		
0508	1.27 ± 0.25	2.00 ± 0.25	0.13 min.		
	(0.050 ± 0.010)	(0.080 ± 0.010)	(0.005 min.)		
0306	0.81 ± 0.15	1.60 ± 0.15	0.13 min.		
	(0.032 ± 0.006)	(0.063 ± 0.006)	(0.005 min.)		
0204	0.50 ± 0.05	1.00 ± 0.05	0.18 ± 0.08		
	(0.020 ± 0.002)	(0.040 ± 0.002)	(0.007 ± 0.003)		

T - See Range Chart for Thickness and Codes

PAD LAYOUT DIMENSIONS mm (in)

			` ,
	А	В	С
0612	0.76 (0.030)	3.05 (0.120)	.635 (0.025)
0508	0.51 (0.020)	2.03 (0.080)	0.51 (0.020)
0306	0.31 (0.012)	1.52 (0.060)	0.51 (0.020)
0204			



0.56 (0.022)

0.76 (0.030)

1.02 (0.040) 1.27 (0.050)

0.35 (0.014)

Low Inductance Capacitors (SnPb)



0612/0508/0306/0204 Tin Lead Termination "B"

GENERAL DESCRIPTION

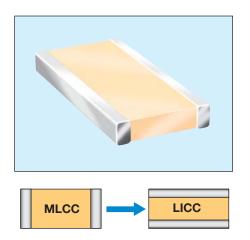
The key physical characteristic determining equivalent series inductance (ESL) of a capacitor is the size of the current loop it creates. The smaller the current loop, the lower the ESL.

A standard surface mount MLCC is rectangular in shape with electrical terminations on its shorter sides. A Low Inductance Chip Capacitor (LICC) sometimes referred to as Reverse Geometry Capacitor (RGC) has its terminations on the longer sides of its rectangular shape. The image on the right shows the termination differences between an MLCC and an LICC.

When the distance between terminations is reduced, the size of the current loop is reduced. Since the size of the current loop is the primary driver of inductance, an 0306 with a smaller current loop has significantly lower ESL then an 0603. The reduction in ESL varies by EIA size, however, ESL is typically reduced 60% or more with an LICC versus a standard MLCC.

AVX LICC products are available with a lead termination for high reliability military and aerospace applications that must avoid tin whisker reliability issues.

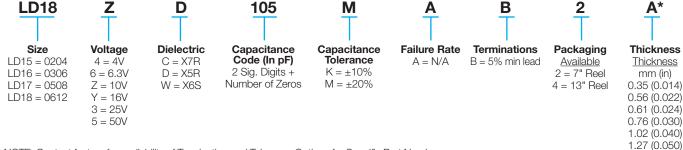
Not RoHS Compliant



PERFORMANCE CHARACTERISTICS

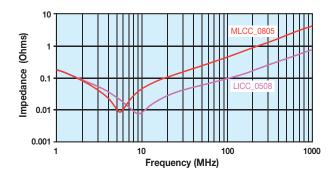
Capacitance Tolerances	$K = \pm 10\%$; $M = \pm 20\%$
Operation	$X7R = -55^{\circ}C \text{ to } +125^{\circ}C$
Temperature Range	X5R = -55°C to $+85$ °C
	$X7S = -55^{\circ}C \text{ to } +125^{\circ}C$
Temperature Coefficient	$X7R, X5R = \pm 15\%; X7S = \pm 22\%$
Voltage Ratings	4, 6.3, 10, 16, 25 VDC
Dissipation Factor	4V, 6.3V = 6.5% max; 10V = 5.0% max; 16V = 3.5% max; 25V = 3.0% max
Insulation Resistance (@+25°C, RVDC)	100,000MΩ min, or 1,000MΩ per μ F min.,whichever is less

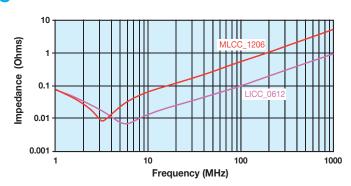
HOW TO ORDER



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

TYPICAL IMPEDANCE CHARACTERISTICS







Low Inductance Capacitors (SnPb)



0612/0508/0306/0204 Tin Lead Termination "B"

PREFERRED SIZES ARE SHADED

;	SIZE		LD	15				LD1	6				LD1	7				LD1	8			
So	ldering						Re	flow	Only			Re	flow	Only			Ref	low/\	Nave	,		
Pa	ckaging							II Pa					III Pa			Paper/Embossed						
(L) Le	(L) Length mm (in.)				0.81 ± 0.15 (0.032 ± 0.006)						(0.0)		0.010)	1.60 ± 0.25 (0.063 ± 0.010)							
(W) W	/idth mm (in.)							60 ± (63 ± (0.006))				0.25 0.010))			20 ± 0 26 ± 0).25).010)			
	WVDC	4	6.3	10	16	6.3	10	16	25	50	6.3	10	16	25	50	6.3	10	16	25	50		
Cap	1000					Α	Α	Α	Α		S	S	S	S	V	S	S	S	S	V		
(pF)	2200					A	A	A	A		S	S	S	S	٧	S	S	S	S	V		
_	4700					Α	Α	Α	Α		S	S	S	S	V	S	S	S	S	V		
Cap	0.010					Α	Α	A	Α		S	S	S	S	V	S	S	S	S	V		
(µF)	0.015					Α	Α	Α	Α		S	S	S	S	V	S	S	S	S	W		
	0.022					Α	Α	Α	Α		S	S	S	S	V	S	S	S	S	W		
	0.047					Α	Α	Α			S	S	S	V	Α	S	S	S	S	W		
	0.068					Α	Α	Α			S	S	S	Α	Α	S	S	S	V	W		
	0.10	С	C			Α	Α	//			S	S	V	Α	Α	S	S	S	V	W		
	0.15					Α	Α				S	S	V			S	S	S	W	W		
	0.22					Α	Α				S	S	Α			S	S	V				
	0.47										V	V	A)			S	S	V				
	0.68										Α	Α				V	V	W				
	1.0										Α	Α				V	V	Α				
	1.5										/K/					W	W					
	2.2															Α	Α					
	3.3															/K/						
	4.7																					
	10																					
	WVDC 4 6.3 10 16					6.3	10	16	25	50	6.3	10	16	25	50	6.3	10	16	25	50		
SIZE 0204							030	6				050	8			0612						

Solid = X7R

mm (in.) LD15 - 0204 Code Thickness 0.35 (0.014)

LD16 - 0306 Code Thickness 0.61 (0.024)

= X5R

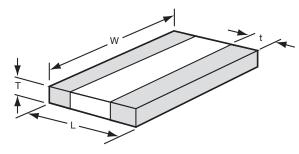




(in.)		mm (in.)
8	LD.	18 - 0612
ess	Code	Thickness
022)	S	0.56 (0.022)
030)	٧	0.76 (0.030)
040)	W	1.02 (0.040)
	Α	1.27 (0.050)

= X6S

PHYSICAL DIMENSIONS AND **PAD LAYOUT**



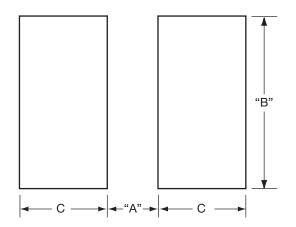
PHYSICAL CHIP DIMENSIONS mm (in)

	L	W	t
0612	1.60 ± 0.25	3.20 ± 0.25	0.13 min.
	(0.063 ± 0.010)	(0.126 ± 0.010)	(0.005 min.)
0508	1.27 ± 0.25	2.00 ± 0.25	0.13 min.
	(0.050 ± 0.010)	(0.080 ± 0.010)	(0.005 min.)
0306	0.81 ± 0.15	1.60 ± 0.15	0.13 min.
	(0.032 ± 0.006)	(0.063 ± 0.006)	(0.005 min.)
0204	0.50 ± 0.05	1.00 ± 0.05	0.18 ± 0.08
	(0.020 ± 0.002)	(0.040 ± 0.002)	(0.007 ± 0.003)

T - See Range Chart for Thickness and Codes

PAD LAYOUT DIMENSIONS mm (in)

	А	В	С
0612	0.76 (0.030)	3.05 (0.120)	.635 (0.025)
0508	0.51 (0.020)	2.03 (0.080)	0.51 (0.020)
0306	0.31 (0.012)	1.52 (0.060)	0.51 (0.020)
0204			





IDC Low Inductance Capacitors (RoHS)

0306/0612/0508 IDC (InterDigitated Capacitors)

GENERAL DESCRIPTION

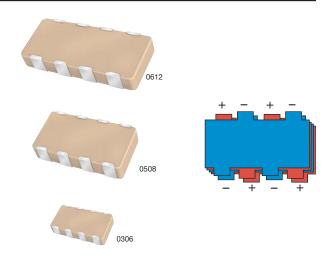
Inter-Digitated Capacitors (IDCs) are used for both semiconductor package and board level decoupling. The equivalent series inductance (ESL) of a single capacitor or an array of capacitors in parallel determines the response time of a Power Delivery Network (PDN). The lower the ESL of a PDN, the faster the response time. A designer can use many standard MLCCs in parallel to reduce ESL or a low ESL Inter-Digitated Capacitor (IDC) device. These IDC devices are available in versions with a maximum height of 0.95mm or 0.55mm.

IDCs are typically used on packages of semiconductor products with power levels of 15 watts or greater. Inter-Digitated Capacitors are used on CPU, GPU, ASIC, and ASSP devices produced on 0.13µ, 90nm, 65nm, and 45nm processes. IDC devices are used on both ceramic and organic package substrates. These low ESL surface mount capacitors can be placed on the bottom side or the top side of a package substrate. The low profile 0.55mm maximum height IDCs can easily be used on the bottom side of BGA packages or on the die side of packages under a heat spreader.

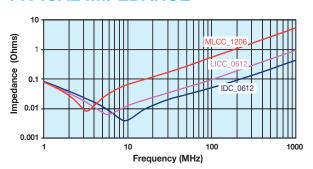
IDCs are used for board level decoupling of systems with speeds of 300MHz or greater. Low ESL IDCs free up valuable board space by reducing the number of capacitors required versus standard MLCCs. There are additional benefits to reducing the number of capacitors beyond saving board space including higher reliability from a reduction in the number of components and lower placement costs based on the need for fewer capacitors.

The Inter-Digitated Capacitor (IDC) technology was developed by AVX. This is the second family of Low Inductance MLCC products created by AVX. IDCs are a cost effective alternative to AVX's first generation low ESL family for high-reliability applications known as LICA (Low Inductance Chip Array).

AVX IDC products are available with a lead-free finish of plated Nickel/Tin.

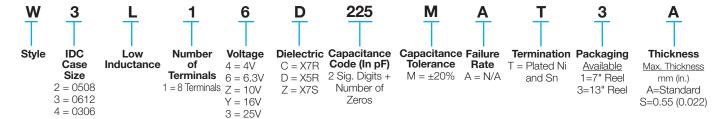


TYPICAL IMPEDANCE





HOW TO ORDER



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

PERFORMANCE CHARACTERISTICS

Capacitance Tolerance	±20% Preferred
Operation	X7R = -55°C to +125°C
Temperature Range	X5R = -55°C to $+85$ °C
	$X7S = -55^{\circ}C \text{ to } +125^{\circ}C$
Temperature Coefficient	±15% (0VDC), ±22% (X7S)
Voltage Ratings	4, 6.3, 10, 16, 25 VDC
Dissipation Factor	≤ 6.3V = 6.5% max; 10V = 5.0% max; ≥ 16V = 3.5% max
Insulation Resistance (@+25°C, RVDC)	100,000MΩ min, or 1,000MΩ per μF min.,whichever is less

Dielectric Strength	No problems observed after 2.5 x RVDC for 5 seconds at 50mA max current
CTE (ppm/C)	12.0
Thermal Conductivity	4-5W/M K
Terminations Available	Plated Nickel and Solder

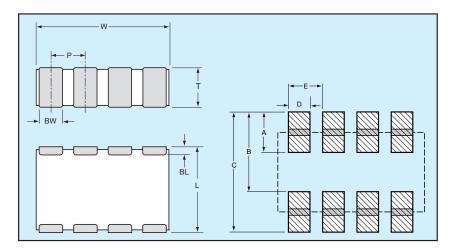


IDC Low Inductance Capacitors (RoHS)

0306/0612/0508 IDC (InterDigitated Capacitors)

SIZE	03	06		Th	in 05	08				0508	}			Thin	0612	2			0612			1	THICK 0612				
Max. mm Thickness (in.)	0.0 (0.0		0.55. (0.022)						0.95 (0.037)					0.55 (0.022)				0.95 (0.037)						22)48)			
WVDC 4 6		6.3	4	6.3	10	16	25	4	6.3	10	16	25	4	6.3	10	16	4	6.3	10	16	25	4	6.3	10	16		
Cap (μF) 0.010																											
0.022																											
0.033																											
0.047																											
0.068																											
0.10																											
0.22																											
0.33																											
0.47																											
0.68																											
1.0																											
1.5																											
2.2																											
3.3																											

PHYSICAL DIMENSIONS AND PAD LAYOUT



Consult factory for additional requirements



PHYSICAL CHIP DIMENSIONS millimeters (inches)

SIZE	W	L	BW	BL	Р
0306	1.60 ± 0.20	0.82 ± 0.10	0.25 ± 0.10	0.20 ± 0.10	0.40 ± 0.05
	(0.063 ± 0.008)	(0.032 ± 0.006	(0.010 ± 0.004)	(0.008± 0.004)	(0.015 ± 0.002)
0508	2.03 ± 0.20	1.27 ± 0.20	0.30 ± 0.10	0.25 ± 0.15	0.50 ± 0.05
	(0.080 ± 0.008)	(0.050 ± 0.008)	(0.012 ± 0.004)	(0.010± 0.006)	(0.020 ± 0.002)
0612	3.20 ± 0.20	1.60 ± 0.20	0.50 ± 0.10	0.25 ± 0.15	0.80 ± 0.10
	(0.126 ± 0.008)	(0.063 ± 0.008)	(0.020 ± 0.004)	(0.010 ± 0.006)	(0.031 ± 0.004)

PAD LAYOUT DIMENSIONS

SIZE	А	В	С	D	Е
0306	0.38	0.89	1.27	0.20	0.40
	(0.015)	(0.035)	(0.050)	(0.008)	(0.015)
0508	0.64	1.27	1.91	0.28	0.50
	(0.025)	(0.050)	(0.075)	(0.011)	(0.020)
0612	0.89	1.65	2.54	0.45	0.80
	(0.035)	(0.065)	(0.010)	(0.018)	(0.031)



IDC Low Inductance Capacitors (SnPb)

0306/0612/0508 IDC with Sn/Pb Termination

GENERAL DESCRIPTION

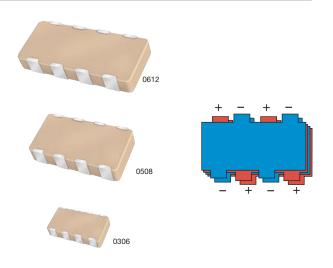
Inter-Digitated Capacitors (IDCs) are used for both semiconductor package and board level decoupling. The equivalent series inductance (ESL) of a single capacitor or an array of capacitors in parallel determines the response time of a Power Delivery Network (PDN). The lower the ESL of a PDN, the faster the response time. A designer can use many standard MLCCs in parallel to reduce ESL or a low ESL Inter-Digitated Capacitor (IDC) device. These IDC devices are available in versions with a maximum height of 0.95mm or 0.55mm.

IDCs are typically used on packages of semiconductor products with power levels of 15 watts or greater. Inter-Digitated Capacitors are used on CPU, GPU, ASIC, and ASSP devices produced on 0.13µ, 90nm, 65nm, and 45nm processes. IDC devices are used on both ceramic and organic package substrates. These low ESL surface mount capacitors can be placed on the bottom side or the top side of a package substrate. The low profile 0.55mm maximum height IDCs can easily be used on the bottom side of BGA packages or on the die side of packages under a heat spreader.

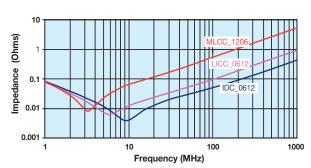
IDCs are used for board level decoupling of systems with speeds of 300MHz or greater. Low ESL IDCs free up valuable board space by reducing the number of capacitors required versus standard MLCCs. There are additional benefits to reducing the number of capacitors beyond saving board space including higher reliability from a reduction in the number of components and lower placement costs based on the need for fewer capacitors.

The Inter-Digitated Capacitor (IDC) technology was developed by AVX. This is the second family of Low Inductance MLCC products created by AVX. IDCs are a cost effective alternative to AVX's first generation low ESL family for high-reliability applications known as LICA (Low Inductance Chip Array).

AVX IDC products are available with a lead termination for high reliability military and aerospace applications that must avoid tin whisker reliability issues.

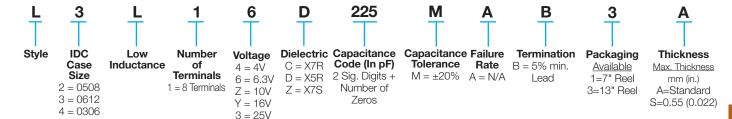


TYPICAL IMPEDANCE



Not RoHS Compliant

HOW TO ORDER



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

PERFORMANCE CHARACTERISTICS

Capacitance Tolerance	±20% Preferred
Operation	X7R = -55°C to +125°C
Temperature Range	X5R = -55°C to +85°C
	X7S = -55°C to +125°C
Temperature Coefficient	±15% (0VDC), ±22% (X7S)
Voltage Ratings	4, 6.3, 10, 16, 25 VDC
Dissipation Factor	\leq 6.3V = 6.5% max;
	10V = 5.0% max;
	≥ 16V = 3.5% max
Insulation Resistance	100,000M Ω min, or 1,000M Ω per
(@+25°C, RVDC)	μF min.,whichever is less

Dielectric Strength	No problems observed after 2.5 x RVDC for 5 seconds at 50mA max current
CTE (ppm/C)	12.0
Thermal Conductivity	4-5W/M K
Terminations Available	Plated Nickel and Solder

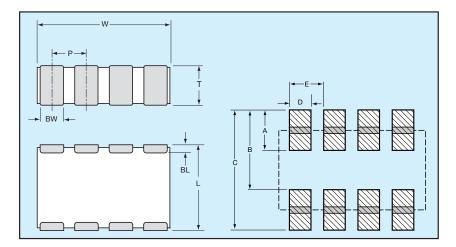


IDC Low Inductance Capacitors (SnPb)

0306/0612/0508 IDC with Sn/Pb Termination

SIZE	03	06		Th	in 05	808		0508						Thin	0612	2			0612			THICK 0612			
Max. mm			0.55.				0.95					0.55				0.95							22		
Thickness (in.)			(0.022)					(0.037)					(0.022)				(0.037)						(0.048)		
WVDC	4	6.3	4	6.3	10	16	25	4	6.3	10	16	25	4	6.3	10	16	4	6.3	10	16	25	4	6.3	10	16
Cap (μF) 0.010																									
0.022																									
0.033																									
0.047																									
0.068																									
0.10																									
0.22																									
0.33																									
0.47																									
0.68																									
1.0																									
1.5																									
2.2																									
3.3																									

PHYSICAL DIMENSIONS AND PAD LAYOUT



Consult factory for additional requirements



PHYSICAL CHIP DIMENSIONS millimeters (inches)

SIZE	W	L	BW	BL	Р
0306	1.60 ± 0.20	0.82 ± 0.10	0.25 ± 0.10	0.20 ± 0.10	0.40 ± 0.05
	(0.063 ± 0.008)	(0.032 ± 0.006	(0.010 ± 0.004)	(0.008± 0.004)	(0.015 ± 0.002)
0508	2.03 ± 0.20 (0.080 ± 0.008)			0.25 ± 0.15 (0.010± 0.006)	0.50 ± 0.05 (0.020 ± 0.002)
0612	3.20 ± 0.20	1.60 ± 0.20	0.50 ± 0.10	0.25 ± 0.15	0.80 ± 0.10
	(0.126 ± 0.008)	(0.063 ± 0.008)	(0.020 ± 0.004)	(0.010 ± 0.006)	(0.031 ± 0.004)

PAD LAYOUT DIMENSIONS

SIZE	А	В	С	D	Е
0306	0.38	0.89	1.27	0.20	0.40
	(0.015)	(0.035)	(0.050)	(0.008)	(0.015)
0508	0.64	1.27	1.91	0.28	0.50
	(0.025)	(0.050)	(0.075)	(0.011)	(0.020)
0612	0.89	1.65	2.54	0.45	0.80
	(0.035)	(0.065)	(0.010)	(0.018)	(0.031)



LGA Low Inductance Capacitors



0204/0306/0805 Land Grid Arrays



Land Grid Array (LGA) capacitors are the latest family of low inductance MLCCs from AVX. These new LGA products are the third low inductance family developed by AVX. The innovative LGA technology sets a new standard for low inductance MLCC performance. *Electronic Products* awarded its 2006 Product of the Year Award to the LGA Decoupling capacitor.

Our initial 2 terminal versions of LGA technology deliver the performance of an 8 terminal IDC low inductance MLCC with a number of advantages including:

- Simplified layout of 2 large solder pads compared to 8 small pads for IDCs
- Opportunity to reduce PCB or substrate contribution to system ESL by using multiple parallel vias in solder pads
- Advanced FCT manufacturing process used to create uniformly flat terminations on the capacitor that resist "tombstoning"
- Better solder joint reliability

APPLICATIONS

Semiconductor Packages

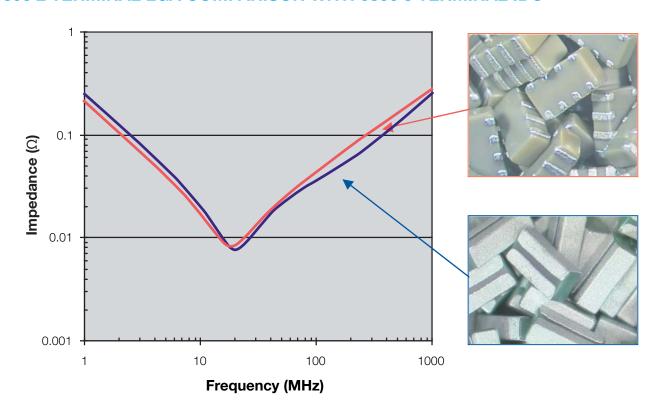
- Microprocessors/CPUs
- Graphics Processors/GPUs
- Chipsets
- FPGAs
- ASICs

Board Level Device Decoupling

- Frequencies of 300 MHz or more
- ICs drawing 15W or more
- Low voltages
- High speed buses



0306 2 TERMINAL LGA COMPARISON WITH 0306 8 TERMINAL IDC

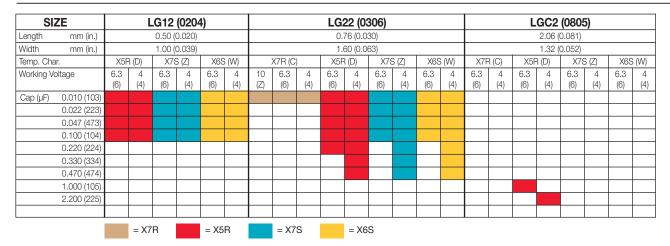




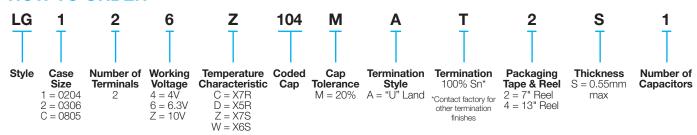
LGA Low Inductance Capacitors

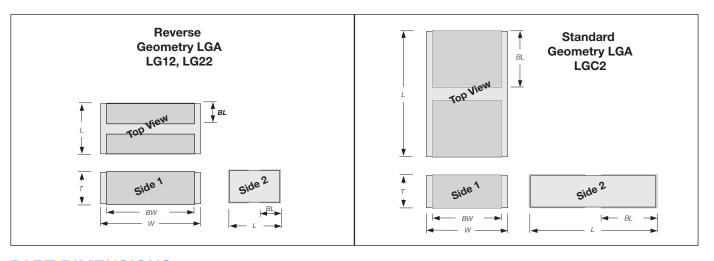


0204/0306/0805 Land Grid Arrays



HOW TO ORDER





PART DIMENSIONS

mm (inches)
------	---------

					, ,
Series	L	W	T	BW	BL
LG12 (0204)	0.5 ± 0.05	1.00 ± 0.10	0.50 ± 0.05	0.8 ± 0.10	0.13 ± 0.08
	(0.020±0.002)	(0.039 ± 0.004)	(0.020 ± 0.002)	(0.031 ± 0.004)	(0.005 ± 0.003)
LG22 (0306)	0.76 ± 0.10	1.60 ± 0.10	0.50 ± 0.05	1.50 ±0.10	0.28 ± 0.08
	(0.030 ± 0.004)	(0.063 ± 0.004)	(0.020 ± 0.002)	(0.059 ± 0.004)	(0.011 ± 0.003)
LGC2 (0805)	2.06 ± 0.10	1.32 ± 0.10	0.50 ± 0.05	1.14 ± 0.10	0.90 ±0.08
	(0.081 ± 0.004)	(0.052 ± 0.004)	(0.020 ± 0.002)	(0.045 ± 0.004)	(0.035 ± 0.003)



RECOMMENDED SOLDER PAD DIMENSIONS mm (inches)



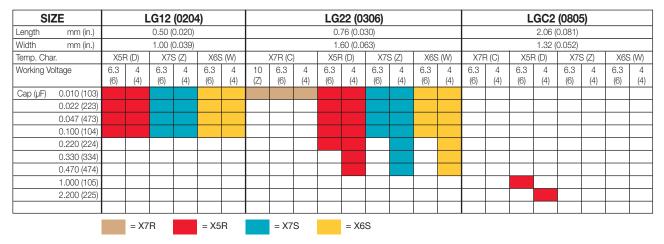
Series	Series PL		G
LG12 (0204)	0.50 (0.020)	1.00 (0.039)	0.20 (0.008)
LG22 (0306)	0.65 (0.026)	1.50 (0.059)	0.20 (0.008)
LGC2 (0805)	1.25 (0.049)	1.40 (0.055)	0.20 (0.008)



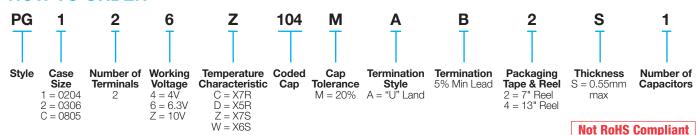
LGA Low Inductance Capacitors

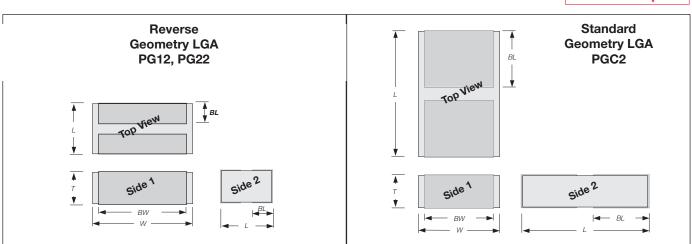


0204/0306/0805 Land Grid Arrays - Tin/Lead Termination "B"



HOW TO ORDER





PART DIMENSIONS

mm (inches)
------	---------

Series	L	W	T	BW	BL
PG12 (0204)	0.5 ± 0.05	1.00 ± 0.10	0.50 ± 0.05	0.8 ± 0.10	0.13 ± 0.08
	(0.020±0.002)	(0.039 ± 0.004)	(0.020 ± 0.002)	(0.031 ± 0.004)	(0.005 ± 0.003)
PG22 (0306)	0.76 ± 0.10	1.60 ± 0.10	0.50 ± 0.05	1.50 ±0.10	0.28 ± 0.08
	(0.030 ± 0.004)	(0.063 ± 0.004)	(0.020 ± 0.002)	(0.059 ± 0.004)	(0.011 ± 0.003)
PGC2 (0805)	2.06 ± 0.10	1.32 ± 0.10	0.50 ± 0.05	1.14 ± 0.10	0.90 ±0.08
	(0.081 ± 0.004)	(0.052 ± 0.004)	(0.020 ± 0.002)	(0.045 ± 0.004)	(0.035 ± 0.003)

RECOMMENDED SOLDER PAD DIMENSIONS mm (inches)



Series	Series PL		G		
PG12 (0204)	0.50 (0.020)	1.00 (0.039)	0.20 (0.008)		
PG22 (0306)	0.65 (0.026)	1.50 (0.059)	0.20 (0.008)		
PGC2 (0805)	1.25 (0.049)	1.40 (0.055)	0.20 (0.008)		



Low Inductance Capacitors



LICA® (Low Inductance Decoupling Capacitor Arrays)



LICA® arrays utilize up to four separate capacitor sections in one ceramic body (see Configurations and Capacitance Options). These designs exhibit a number of technical advancements:

Low Inductance features-

Low resistance platinum electrodes in a low aspect ratio pattern Double electrode pickup and perpendicular current paths C4 "flip-chip" technology for minimal interconnect inductance

HOW TO ORDER

LICA 3 102 M Style Voltage Dielectric Cap/Section Capacitance Height **Termination Reel Packaging** # of 5V = 9 D = X5R (EIA Code) F = C4 Solder M = 7" Reel Caps/Part Code & Tolerance Code Balls-97Pb/3Sn A = Standard Size 6 = 0.500 mmR = 13" Reel 10V = ZT = T55T 102 = 1000 pF $M = \pm 20\%$ 1 = oneP = GMV3 = 0.650mm H = C4 Solder Balls 6 = 2"x2" Waffle Pack B = COTS+25V = 3 S = High K 103 = 10 nF 2 = two8 = 2"x2" Black Waffle 104 = 100 nF1 = 0.875mm Low FSR 4 = fourT55T 5 = 1.100mm G = Lead Free SAC Pack 7 = 1.600mm R = Cr-Cu-Au 7 = 2"x2" Waffle Pack

N = Cr-Ni-Au

X = None

V = Eutectic Lead-

Tin Bump-37%Pb/63%Sn

NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

TABLE 1

.,		
Typical Parameters	T55T/S55S	Units
Capacitance, 25°C	Co	Nanofarads
Capacitance, 55°C	1.45 x Co	Nanofarads
Capacitance, 85°C	0.7 x Co	Nanofarads
Dissipation Factor 25°	15	Percent
ESR (Nominal)	20	Milliohms
DC Resistance	0.2	Ohms
IR (Minimum @25°) (Design Dependent)	300	Megaohms
Dielectric Breakdown, Min	500	Volts
Thermal Coefficient of Expansion	8.5	ppm/°C 25-100°
Inductance: (Design Dependent) (Nominal)	30	Pico-Henries
Frequency of Operation	DC to 5 Gigahertz	
Ambient Temp Range	-55° to 125°C	

Inspection Code Face A = BarB = No Bar C = Dot, S55S X = MIL-PRF-123Dielectrics D = Triangle

w/ termination facing up A = 2"x2" Black Waffle Pack w/ termination facing up C = 4"x4" Waffle Pack

w/ clear lid

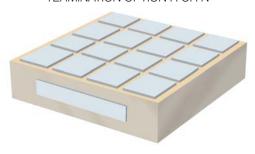


TERMINATION OPTIONS

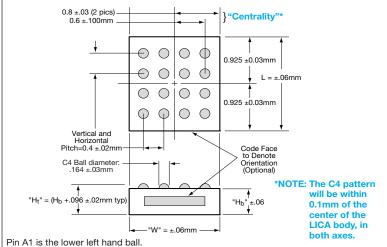
SOLDER BALLS TERMINATION OPTION F, H, G OR V



TERMINATION OPTION R OR N



SOLDER BALL AND PAD DIMENSIONS



Code (Body Height)	Width (W)	Length (L)	Height Body (H _b)				
1	1.600mm	1.850mm	0.875mm				
3	1.600mm	1.850mm	0.650mm				
5	1.600mm	1.850mm	1.100mm				
6	1.600mm	1.850mm	0.500mm				
7	1.600mm	1.850mm	1.600mm				

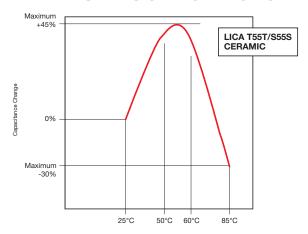


Low Inductance Capacitors

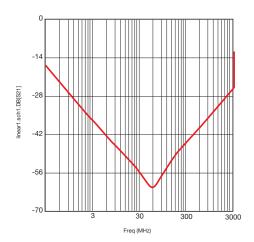


LICA® (Low Inductance Decoupling Capacitor Arrays)

TEMPERATURE VS CAPACITANCE CHANGE



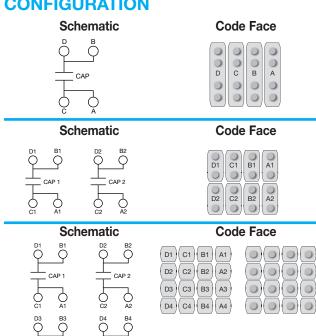
TYPICAL S21 FOR LICA AT SINGLE VIA



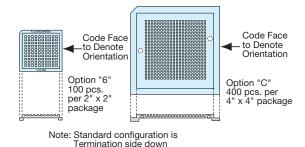
LICA COMMON PART NUMBER LIST

Part Number	Part Number Voltage Ti		Capacitors per Package
LICA3T193M3FC4AA	25	0.650	4
LICA3T153P3FC4AA	25	0.650	4
LICA3T134M1FC1AA	25	0.875	1
LICA3T104P1FC1AA	25	0.875	1
LICA3T333M1FC4AA	25	0.875	4
LICA3T263P3FC4AA	25	0.650	4
LICA3T244M5FC1AA	25	1.100	1
LICA3T194P5FC1AA	25	1.100	1
LICA3T394M7FC1AB	25	1.600	1
LICA3T314P7FC1AB	25	1.600	1
Extended Range			
LICAZT623M3FC4AB	10	0.650	4
LICA3T104M3FC1A	25	0.650	1
LICA3T803P3FC1A	25	0.650	1
LICA3T423M3FC2A	25	0.650	2
LICA3T333P3FC2A	25	0.650	2
LICA3S253M3FC4A	25	0.650	4
LICAZD753M3FC4AD	10	0.650	4
LICAZD504M3FC1AB	10	0.650	1
LICAZD604M7FC1AB	10	1.600	1
LICA3D193M3FC4AB	25	0.650	4

CONFIGURATION

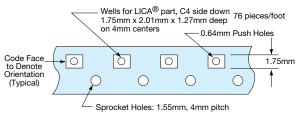


WAFFLE PACK OPTIONS FOR LICA®



LICA® PACKAGING SCHEME "M" AND "R"

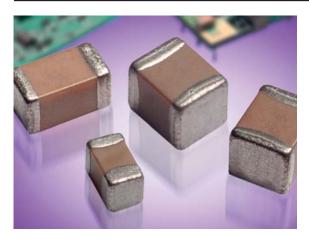
8mm conductive plastic tape on reel: "M"=7" reel max. qty. 3,000, "R"=13" reel max. qty. 8,000





For 600V to 5000V Applications





NEW 630V RANGE

High value, low leakage and small size are difficult parameters to obtain in capacitors for high voltage systems. AVX special high voltage MLC chip capacitors meet these performance characteristics and are designed for applications such as snubbers in high frequency power converters, resonators in SMPS, and high voltage coupling/dc blocking. These high voltage chip designs exhibit low ESRs at high frequencies.

Larger physical sizes than normally encountered chips are used to make high voltage MLC chip products. Special precautions must be taken in applying these chips in surface mount assemblies. The temperature gradient during heating or cooling cycles should not exceed 4°C per second. The preheat temperature must be within 50°C of the peak temperature reached by the ceramic bodies through the soldering process. Chip sizes 1210 and larger should be reflow soldered only. Capacitors may require protective surface coating to prevent external arcing.

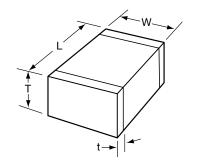
For 1825, 2225 and 3640 sizes, AVX offers leaded version in either thru-hole or SMT configurations (for details see section on high voltage leaded MLC chips).

HOW TO ORDER

1808	A	A	<u>271</u>	K	A	1	1	A
AVX	Voltage	Temperature	Capacitance Code	Capacitance	Test Level	Termination*	Packaging	Special
Style	600V/630V = C	Coefficient	(2 significant digits	Tolerance	A = Standard	1 = Pd/Ag	1 = 7" Reel**	Code
0805	1000V = A	NPO (C0G) = A	+ no. of zeros)	$C0G:J = \pm 5\%$		T = Plated	3 = 13" Reel	A = Standard
1206	1500V = S	X7R = C	Examples:	$K = \pm 10\%$		Ni and Sn		
1210	2000V = G		10 pF = 100	$M = \pm 20\%$		(RoHS Compliant	t)	
1808	2500V = W		100 pF = 101	$X7R:K = \pm 10\%$				
1812	3000V = H		1,000 pF = 102	$M = \pm 20\%$				
1825	4000V = J		22,000 pF = 223	Z = +80%,				
2220	5000V = K		220,000 pF = 224	-20%				
2225			$1 \mu F = 105$					
3640								
***			*No			ad (Pb) is available, se , see pages 89 and 9		88 for LD style.

Notes: Capacitors with X7R dielectrics are not intended for applications across AC supply mains or AC line filtering with polarity reversal. Contact plant for recommendations. Contact factory for availability of Termination and Tolerance options for Specific Part Numbers.

- ** The 3640 Style is not available on 7" Reels.
- *** AVX offers nonstandard chip sizes. Contact factory for details.





DIMENSIONS

millimeters (inches)

SIZE	0805	1206	1210*	1808*	1812*	1825*	2220*	2225*	3640*
(L) Length	2.01 ± 0.20	3.20 ± 0.20	3.20 ± 0.20	4.57 ± 0.25	4.50 ± 0.30	4.50 ± 0.30	5.70 ± 0.40	5.72 ± 0.25	9.14 ± 0.25
	(0.079 ± 0.008)	(0.126 ± 0.008)	(0.126 ± 0.008)	(0.180 ± 0.010)	(0.177 ± 0.012)	(0.177 ± 0.012)	(0.224 ± 0.016)	(0.225 ± 0.010)	(0.360 ± 0.010)
(W) Width	1.25 ± 0.20	1.60 ± 0.20	2.50 ± 0.20	2.03 ± 0.25	3.20 ± 0.20	6.40 ± 0.30	5.00 ± 0.40	6.35 ± 0.25	10.2 ± 0.25
	(0.049 ±0.008)	(0.063 ± 0.008)	(0.098 ± 0.008)	(0.080 ± 0.010)	(0.126 ± 0.008)	(0.252 ± 0.012)	(0.197 ± 0.016)	(0.250 ± 0.010)	(0.400 ± 0.010)
(T) Thickness	1.30	1.52	1.70	2.03	2.54	2.54	3.30	2.54	2.54
Max.	(0.051)	(0.060)	(0.067)	(0.080)	(0.100)	(0.100)	(0.130)	(0.100)	(0.100)
(t) terminal min. max.	0.50 ± 0.25	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.76 (0.030)
	(0.020 ± 0.010)	0.75 (0.030)	0.75 (0.030)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.52 (0.060)

^{*}Reflow Soldering Only



For 600V to 5000V Applications

NP0 (C0G) Dielectric Performance Characteristics

Capacitance Range	10 pF to 0.047 μ F (25°C, 1.0 \pm 0.2 Vrms at 1kHz, for \leq 1000 pF use 1 MHz)
Capacitance Tolerances	±5%, ±10%, ±20%
Dissipation Factor	0.1% max. (+25°C, 1.0 \pm 0.2 Vrms, 1kHz, for \leq 1000 pF use 1 MHz)
Operating Temperature Range	-55°C to +125°C
Temperature Characteristic	0 ±30 ppm/°C (0 VDC)
Voltage Ratings	600, 630, 1000, 1500, 2000, 2500, 3000, 4000 & 5000 VDC (+125°C)
Insulation Resistance (+25°C, at 500 VDC)	100K M Ω min. or 1000 M Ω - μF min., whichever is less
Insulation Resistance (+125°C, at 500 VDC)	10K M Ω min. or 100 M Ω - μ F min., whichever is less
Dielectric Strength	Minimum 120% rated voltage for 5 seconds at 50 mA max. current

NP0 (C0G) CAPACITANCE RANGE PREFERRED SIZES ARE SHADED

- Jas	e Size			0805				1206					1210						18	808				1812 Reflow Only							
	dering			low/W			Re	flow/W				Re	flow O						Reflo												
(L) Length	r	nm	2.	01 ± 0 .	20		3	.20 ± 0.1	20			3	.20 ± 0.2	20					4.57 :	± 0.25							4.50	± 0.30			
(W) Width		(in.) mm		$79 \pm 0.$ $25 \pm 0.$		-		126 ± 0.0					26 ± 0.0						2.03	± 0.010)	<u> </u>						(0.177	± 0.012 ± 0.20)		
		(in.)	(0.0)	49 ± 0 .	008)			0.063 ± 0.0				(0.0	0.0 ± 800	008)					(0.080 :	± 0.010)							(0.126	± 0.008)		
(T) Thickne	ess r	nm (in.)		1.30 (0.051)				1.52 (0.060)					1.70 (0.067)						(0.0	03 080)							(0.	54 100)			
(t) Terminal	1 1	min	0.	$50 \pm 0.$	25		0	.25 (0.01	10)			0.	25 (0.01	0)					0.25 (0.010)							0.25 ((0.010)			
Volt	tage (V)	nax	600	20 ± 0.	1000	600		.75 (0.03 1000	1500	2000	600		75 (0.03		2000	600	630	1000	1.02 (2000	2500	3000	4000	600	630	1000	1.02 (2000	2500	3000	4000
Cap (pF)	1.5	1R5	A	A	1000	X	X	X	X	X	000	000	1000	1000	2000	- 000	000	1000	1000	2000	2000	0000	1000	000	000	1000	1000	2000	2000	0000	1000
	1.8	1R8	Α	Α		Х	Х	Х	Х	Х																					
	2.2	2R2	A	A		X	X	X	X	X								0	0	0	0										
	2.7	2R7 3R3	A	A		X	X	X	X	X								C	C	C	C	C									
-	3.9	3R9	Α	Α		Х	X	X	Х	X								С	С	С	С	С									
	4.7	4R7	Α	Α		Х	Х	Х	Х	Х								С	С	С	С	С									
	5.6 6.8	5R6 6R8	A	A		X	X	X	X	X								С	C	C	С	C									
	8.2	8R2	A	A		X	X	X	X	X								C	C	C	C	C									
	10	100	A	A		X	X	X	X	X	С	С	D	D	D	С	С	С	C	С	С	С		С	С	С	С	С	С	С	
	12	120	Α	Α		Х	Х	Х	Х	Х	С	С	D	D	D	С	С	С	С	С	С	С		С	С	С	С	С	С	С	
	15 18	150 180	A	A		X	X	X	X	X	С	С	D	D D	D	С	С	С	С	С	С	С		С	С	C	С	С	С	C	
	22	220	A	A		X	X	X	X	X	C	C	D D	D	D D	С	C	C	C	C	C	C		C	C	C	C	C	C	C	
	27	270	A	A		X	X	X	X	X	С	С	D	D	D	С	С	С	C	С	С	С		С	С	C	С	С	С	С	
	33	330	Α	Α		Х	Х	Х	D	D	С	С	D	D	D	С	С	С	С	С	С	С		С	С	С	С	С	С	С	
	39	390	A	A		X	X	X	D	D	С	С	D	D	D	С	С	С	С	С	С	С		С	С	С	С	С	С	C	
	47 56	470 560	A	A		X	X	M	D C	D C	C	C	D D	D C	D C	С	C	C	C	C	C	C		C	С	С	C	C	C	C	
	68	680	A	A		X	X	M	C	C	C	C	D	С	С	С	C	C	C	C	C	C		С	С	C	C	C	C	C	
	82	820	Х	Х		Х	Х	С	С	С	С	С	D	С	С	С	С	С	С	С	С	С		С	С	С	С	С	С	С	
	100	101 121	C	C		X	X	C	C E	C E	C	C	C	С	С	С	C	C	C	C	F	F		C	C	C	C	C	C	C	
	120 150	151	С	С		X	X	C	E	E	С	C	С	E	E	С	С	С	F	F	F	F		С	С	С	С	С	С	С	
-	180	181	С	С		Х	X	E	Е	E	С	С	Е	Е	Е	С	С	С	F	F	F	F		С	С	С	С	С	F	F	
	220	221	С	С		Х	Х	Е	Е	Е	С	С	Е	Е	Е	С	С	С	F	F	F	F		С	С	С	С	С	F	F	
	270 330	271 331	C	CC		C	C	E	E	E	C	C	E F	E	E	С	C	C	F	F	F	F		C	C	С	C F	C F	F	F	
-	390	391	C	С		C	C	E	E	E	C	C	E	E	E	C	C	F	F	F	F	F		С	C	C	F	F	F	F	
	470	471	С	С		С	С	Е	Е	Е	С	С	Е	Е	Е	С	С	F	F	F	F	F		С	С	F	F	F	F	F	
	560	561	С	С		С	С	E			С	С	Е	E	Е	С	С	F	F	F				С	С	F	F	F	F	F	
	680 750	681 751	С	0 0		C	C	E			С	C	E	G	F G	С	С	F	F	F				C	С	F	F	F	G G	G G	
	820	821	С	С		E	E	E			С	C	E	G	G	С	С	F	E	E				С	C	F	F	F	G	G	
	1000	102				Е	Е	Е			С	С	Е			С	С	F	Е	Е				С	С	F	F	F	G	G	
	1200	122				E	E				C	С	E			E	E	F	Е	Е				С	С	F	E	E			
	1500 1800	152 182				E	E				C	C	G G			E	E	F						C	C	F	F	F			
	2200	222				E	E				E	E				E	E	-						С	С	E	G	G			
	2700	272				Е	Е				Е	Е				Е	Е							С	С	Е	G	G			
	3300	332 392			-	Е	Е		-		E F	E F				E F	E F							C	C	F					-
	4700	472				\vdash					E	E				E	E			-				C	C	G			-		
	5600	562									E	E				Е	Е							С	С						
	6800	682														F	F							С	С						
Con (v.D	8200 0.010	822 103			-	\vdash	-	-			-		-			_	_	-		-	-			E F	E		-	-	-	-	
Сар (µF)	0.010	103			1	 	1									-	-							F	F						
	0.012	153																						G	G						
	0.018	183				—																		G	G						
	0.018	223																						u	G.						
	0.022	333																													
	0.033	473				<u> </u>																									
	0.056	563																													
	0.068	683																													
	0.100	104																													
Volt	tage (V)		600	630	1000	600	630	1000	1500	2000	600	630	1000	1500	2000	600	630	1000	1500	2000	2500	3000	4000	600	630	1000	1500	2000	2500	3000	4000
	e Size			0805				1206					1210							808								12			





For 600V to 5000V Applications

NP0 (COG) CAPACITANCE RANGE PREFERRED SIZES ARE SHADED

Case Size				1:	825								2220)								2225									3640)			
Soldering					w On	lv							flow (\vdash				flow C					\vdash				low C				
(L) Length mm				4.50	± 0.30	1						5.	70 ± 0	.40							5.	72 ± 0	25							9.	14 ± 0.	25			
(in.) (W) Width mm					± 0.01							(0.2	24 ± 0 00 ± 0	.016)							(0.2	$25 \pm 0.035 \pm 0.000$	010) 25				_				60 ± 0.0				
(in.)				(0.252)	± 0.01	2)						(0.1	97 ± 0	.016)							(0.2	50 ± 0	010)							(0.4	$00 \pm 0.$.010)			
(T) Thickness mm (in.)				(0.	2.54 .100)								3.30))								2.54 (0.100)								2.54 (0.100))			
(t) Terminal min				0.25	(0.010								25 (0.0								0.:	25 (0.0	10)								76 (0.0				
Voltage (V)	600	630	1000		(0.040)	2500	3000	4000	600	630	1000	1500	2000	2500	3000	4000	5000	600	630	1000	1500	02 (0.0	2500	3000	4000	5000	600	630	1000	1500	2000	2500	3000	4000	5000
Cap (pF) 1.5 1R5																																			
1.8 1R8																																			
2.2 2R2 2.7 2R7	-								_									_			-				_		-					_			
3.3 3R3	\vdash																				_						\vdash								
3.9 3R9																																			
4.7 4R7															_			_			_						_								
5.6 5R6 6.8 6R8	\vdash					-		_	\vdash					-	\vdash			\vdash			\vdash	-				_	\vdash		-	-		_			
8.2 8R2	\vdash																										\vdash								
10 100	Е	Е	Е	Е	Е	Е	Е		Е	Е	Е	Е	Е	Е	Е			Е	Е	Е	Е	Е	Е	Е											
12 120 15 150	E	E	E	E	E	E F	E		E	E	E	E F	E	E	E			E	E F	E	E	E	E	E	-		 		-	-	_				
18 180	E	E	E	E	E	E	E		E	E	E	E	E	E	E			E	E	E	E	E	E	E											
22 220	Е	E	Е	Е	Е	Е	E		E	E	E	E	E	Е	E			E	E	Е	E	Е	Е	Е											
27 270	E	E	E	Е	E	E	Е		E	E	Е	Е	Е	E	E			Е	Е	Е	E	E	Е	E											
33 330 39 390	E	E	E	E	E	E	E		E	E	E	E	E	E	E			E	E	E	E	E	E	E			-		-	_	-				-
47 470	E	E	E	E	E	E	E		E	E	E	E	E	E	E			E	E	E	E	E	E	E											G
56 560	Е	Е	Е	Е	Е	Е	Е		Е	Е	Е	Е	Е	Е	Е			Е	Е	Е	Е	Е	Е	Е											G
68 680	E	E	E	E	E	E	E		E	E	E	E F	E	E	E			E	E	E	E	E	E	E F											G G
82 820 100 101	F	F	F	F	F	F	F		F	F	F	E	F	F	F			F	F	F	F	F	E	F			\vdash			G	G	G	G	G	G
120 121	Е	E	Е	E	Е	Е	Е		Е	Е	E	Е	Е	Е	E			Е	E	Е	Е	Е	Е	Е						G	G	G	G	G	G
150 151	Е	Е	Е	Е	Е	Е	Е		Е	Е	Е	Е	Е	Е	Е			Е	Е	Е	Е	Е	Е	Е						G	G	G	G	G	G
180 181 220 221	E	E	E	E	E	E	E		E	E	E	E	E	E	E			E	E	E	E	E	E	E			_			G G	G	G G	G G	G G	G G
270 271	E	E	E	E	E	E	E		E	E	E	E	E	E	E			E	E	E	E	E	E	E	_		\vdash			G	G	G	G	G	G
330 331	Е	Е	Е	Е	Е	Е	Е		Е	Е	Е	Е	Е	Е	Е			Е	Е	Е	Е	Е	Е	Е						G	G	G	G	G	G
390 391	Е	E	E	E	E	E	Е		E	E	Е	Е	E	Е	E			Е	Е	Е	E	E	Е	Е						G	G	G	G	G	G
470 471 560 561	F	F	E	F	F	E F	F		F	E	E	E F	F	E	F			F	F	F	E F	E F	E	E			\vdash		-	G	G	G	G	G G	G
680 681	E	E	E	E	E	F	F		E	E	E	E	E	F	F			E	E	E	E	E	E	E						G	G	G	G	G	G
750 751	Е	Е	Е	Е	Е	F	F		Е	Е	Е	Е	Е	F	F			Е	Е	Е	Е	Е	Е	Е						G	G	G	G	G	G
820 821 1000 102	E	E	E	E	E	F	F		E	E	E	E	E F	F	F			E	E F	E F	E F	E	F	E			G	G	G	G	G	G	G	G G	
1200 122	E	E	E	E	E	G	G		E	E	E	E	E	G	G			E	E	E	E	E	F	F			G	G	G	G	G	G	G	G	
1500 152	Е	Е	Е	F	F	G	G		Е	Е	Е	F	F	G	G			Е	Е	Е	Е	Е	F	F			G	G	G	G	G	G	G		
1800 182	E	E	E	F	F	G	G		E	E	E	F	F	G	G			E	E F	E	E	E	G	G			G	G	G	G	G	G	G		
2200 222 2700 272	E	E	E	G	G				E	E	E	G	G		-	-		E	E	E	E F	E F					G	G	G	G	G G	G	G		
3300 332	Е	Е	Е	G	G				E	Е	Е	G	G					E	E	Е	F	F					G	G	G	G	G	G			
3900 392	Е	E	Е	G	G				E	E	Е	G	G					Е	E	Е	G	G					G	G	G	G	G	G			
4700 472 5600 562	E	E	E	G	G			_	E F	E	E	G G	G		-			F	F	F	G	G					G G	G G	G	G G	G G	-			<u> </u>
6800 682	F	F	F	_	_				F	F	F							F	F	F	G	G					G	G	G	G	G				
8200 822	G	G	G						G	G	G							G	G	G							G	G	G	G					
Cap (µF) 0.010 103	<u> </u>		-					_	-					-	-	-		G	G	G		-		_	<u> </u>		G	G	G	G		_			
0.012 123	_		-		-	-		_	-			-		-	-	-		G	G	G		-			_		G	G	G		_				
0.015 153	_		-	-	-		_	_	-			-		-	-	-		G	G	G		-			_		G	G	G		_	-			
0.018 183	\vdash				-			-	-					-	-	-		G	G	G		-					G	G	G						
0.022 223	_		-					_	-					-	-	-	_	G	G	G		1			\vdash		G	G	G		-				<u> </u>
0.033 333	\vdash	-	_		-	_		\vdash	\vdash			-		_	\vdash	_	<u> </u>	G G	G G	G G		_			\vdash		G G	G G		\vdash	<u> </u>	-			-
0.047 473	\vdash		1						\vdash					-	_	1		G	G	G		1					a	a		_					
0.068 683	\vdash				_	\vdash									\vdash			G	G	G		\vdash					\vdash								_
0.100 104	\vdash				1	_												G	G	G							\vdash								
Voltage (V)	600	630	1000	1500	2000	2500	3000	4000	600	630	1000	1500	2000	2500	3000	4000	5000	600	630		1500	2000	2500	3000	4000	5000	600	630	1000	1500	2000	2500	3000	4000	5000
Case Size	555	, 000	1.000		325	12000	3000		555				2220		10000	1.000	3000	555	000			2225		3000	,,,,,,	5000	000	000	1.000		3640		3000	.000	2000
- COO OILO																																			

Letter	Α	С	E	F	G	X
Max.	0.813	1.448	0.071	1.803	2.794	0.940
Thickness	(0.032)	(0.057)	(0.071)	(0.087)	(0.110)	(0.037)

NOTE: Contact factory for non-specified capacitance values



For 600V to 5000V Applications

X7R Dielectric

Performance Characteristics

Capacitance Range	10 pF to 0.56 μF (25°C, 1.0 ±0.2 Vrms at 1kHz)
Capacitance Tolerances	±10%; ±20%; +80%, -20%
Dissipation Factor	2.5% max. (+25°C, 1.0 ±0.2 Vrms, 1kHz)
Operating Temperature Range	-55°C to +125°C
Temperature Characteristic	±15% (0 VDC)
Voltage Ratings	600, 630, 1000, 1500, 2000, 2500, 3000, 4000 & 5000 VDC (+125°C)
Insulation Resistance (+25°C, at 500 VDC)	100K M Ω min. or 1000 M Ω - μ F min., whichever is less
Insulation Resistance (+125°C, at 500 VDC)	10K M Ω min. or 100 M Ω - μ F min., whichever is less
Dielectric Strength	Minimum 120% rated voltage for 5 seconds at 50 mA max. current

X7R CAPACITANCE RANGE PREFERRED SIZES ARE SHADED

		_									_													1812							
Case S	Size			0805				1206	i				1210						18	308							18	12			
Solder				low/W				flow/W					eflow O							w Only							Reflov				
(L) Length		nm in.)	(0.0	01 ± 0. 179 ± 0.	20 008)			.20 ± 0. 126 ± 0.				(0.1	.20 ± 0.2	20 008)						± 0.25 ± 0.010))						4.50 : (0.177 :				
(W) Width	n	nm	1.	25 ± 0. 149 ± 0.	20		1	.60 ± 0. .63 ± 0.	20			2	.50 ± 0.0	20					2.03	± 0.25 ± 0.010							3.20 :	± 0.20			
(T) Thickness		in.) nm	(0.0	1.30	000)	1	(0.0	1.52				(0.0	1.70	JU0)					2.	.03)						2.	54			
(t) Torminal		in.)	0	(0.051)	25		0	(0.060)				0	(0.067)	10)						080)							(0.1				
(t) Terminal		nin nax	(0.0	$50 \pm 0.$ $120 \pm 0.$	23 010)		0.	.25 (0.0° .75 (0.0°	30)				.75 (0.03						1.02	(0.010) (0.040)							1.02 (0.040)			
Voltage			600	630	_	600	630	1000	_		600	_	1000	1500	_	600	630	1000	1500	2000	2500	3000	4000	600	630	1000	1500	2000	2500	3000	4000
1-4-7	100	101	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е																
	120	121	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е																
	150	151	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е																
	180	181	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е																
	220	221	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е																
	270	271	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е									Е	Е	Е	Е	Е			
	330	331	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	F		Е	Е	Е	Е	Е			
	390	391	Х	Х	С	С	С	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	Е	F		Е	Е	Е	Е	Е			
	170	471	X	X	С	С	С	E	E	E	E	E	E	E	E	E	E	E	E	E	E	F		E	E	E	E	E	E	E	
	560	561	X	X	С	С	С	E	E	E	E	E	E	E	E	E	E	E	E	E	F	F		E	E	E	E	E	E	E	
	380	681	X	X	С	С	С	E	E	E	E	E	E	E	E	E	E	E	E	E	F	F		E	E	E	E	E	F	F	
	750	751	X	X	С	С	С	E	E	Е	E	E	E	E	E	E	E	E	E	E	F	-		E	E	E	E	E	F	F	
	320	821	X	X	С	С	С	E	E	E	E E	E	E	E	E	E	E	E E	E	E	F	F		E E	E E	E	E E	E	F F	F	
	000	102	X	X	C	С	С	_	E	E	_	_	_	E	_	E	E		_	E	F	F		E		E	E	E	F	F	
	200	122	X	X	_	С	С	E		_	E	E	E	E	E	_	E	E	E	_	F	F		_	E	_		E			_
	500	152	X	X	С	С	С	E	E	E	E E	E	E	E	E	E	E	E E	E	E	F	F		E E	E E	E	E E	E	G	G	
	300	182 222	X	X		С	С	E	E	E	E	E	E	E F	E	E	E	E	F	F	F	F		E	E	E	E	E E	G G	G G	
	200 700	272	X	X		С	С	E	E		E	E	E	F	E	E	E	E	F	F	F			E	E	E	E	E	G	G	
	300	332	X	X		С	С	E			F	F	E	F	E	E	E	E	F	F				E	E	E	F	F	G	G	
	900	392	X	X		С	С	E			E	E	E	G	-	E	E	E	F	'				E	E	E	F	F	G	G	
	700	472	X	X		С	С	E			E	E	E	G		E	E	E	F					E	E	E	F	F	G	G	
	300	562	X	X		С	С	E			E	F	F	G		F	F	F	F					E	E	F	G	G	u	u	
	300	682	X	X		С	С	E			F	E	F	- u		E	F	E	F					E	E	E	G	G			
	200	822	X	X		С	С	E			E	E	E			E	E	E	_					E	E	E	G	G			
Cap (µF) 0.0		103	С	С		С	С	E			E	E	E			E	E	E						E	Е	F	G	G			
	015	153	С	С		Е	Е	Е			Е	Е	Е			F	F	F						Е	Е	F	G				
	018	183	С	С		Е	Е				Е	Е	Е			F	F	F						Е	Е	G					
0.0		223	С	С		Е	Е				Е	Е	Е			F	F							Е	Е	G					
0.0	027	273				Е	Е				Е	Е				F	F							Е	Е	G					
0.0	033	333				Е	Е				Е	Е				F	F							Е	Е	G					
0.0	039	393									Е	Е				F	F							Е	Е	G					
0.0)47	473									Е	Е				F	F							Е	Е	G					
0.0	056	563									F	F				F	F							F	F						
0.0	068	683									F	F				F	F							F	F						
0.0	082	823									F	F												F	F						
0.1	100	104									F	F												F	F						
0.1	150	154																						G	G						
0.2	220	224																						G	G						
0.2	270	274																													
	330	334				_																									<u> </u>
0.3		394				_																									
0.4		474				_		_			_																				
0.5		564				_		_			_																				
0.6		684				<u> </u>	-			_	_					_			-												
	320	824				-													-												
	000	105	0.5.5	0	45		0	45	45	05	0.7.7	0	45	45	00	05-	0.55	45	45	05	05	00	40	05-	0	45	45	00	05	05	4077
Voltage Case S		\dashv	600	630 0805	1000	600	630	1000 1206	1500	2000	600	630	1000 1210	1500	2000	600	630	1000		2000	2500	3000	4000	600	630	1000		2000 12	2500	3000	4000
Uase 3	SIZE			0000	'	Ц		1200	'		L		1210						10	,00				L			10	14			





For 600V to 5000V Applications

X7R CAPACITANCE RANGE PREFERRED SIZES ARE SHADED

Case Size				19	325								2220)								2225	;								3640)			
Soldering					v Only	v/							flow (flow C									low C				
(L) Length mm				4.50	± 0.30							5.	70 ± 0	.40							5.	72 ± 0.	.25							9.1	14 ± 0 .	.25			
(in.) (W) Width mm				6.40	± 0.01:							5.	$\frac{24 \pm 0}{00 \pm 0}$.40							6.3	$25 \pm 0.035 \pm 0.000$.25							10	0.0 ± 0.0	.25			
(in.) (T) Thickness mm			(± 0.012	2)						(0.1	97 ± 0 3.30	.016)				_			(0.2	50 ± 0. 2.54	.010)				_			(0.40	$00 \pm 0.$ 2.54	.010)		_	
(in.) (t) Terminal min				(0.	100)								(0.130					_				(0.100					_				(0.100)				
max				1.02	(0.040)							1.0	02 (0.0	40)							1.0	0.0) 02	40)							1.5	52 (0.0	60)			
Voltage (V)	600	630	1000	1500	2000	2500	3000	4000	600	630	1000	1500	2000	2500	3000	4000	5000	600	630	1000	1500	2000	2500	3000	4000	5000	600	630	1000	1500	2000	2500	3000	4000	5000
Cap (pF) 100 101									_									_									_						\vdash	$\vdash\vdash$	
120 121 150 151									-									\vdash									\vdash							$\vdash\vdash$	
180 181									\vdash									\vdash									\vdash							\vdash	
220 221																											\vdash							\vdash	
270 271																																			
330 331									\vdash																									\Box	
390 391																																			
470 471																																			
560 561																																			
680 681																																			
750 751																																			
820 821																																			
1000 102	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	G
1200 122	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	G
1500 152	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	G
1800 182	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	G
2200 222	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	G
2700 272	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	G
3300 332	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	G
3900 392	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	
4700 472	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	
5600 562	F	F	F	F	F	F	F		F	F	F	F	F	F	G			F	F	F	F	F	F	F			G	G	G	G	G	G	G	G	
6800 682	F	F	F	G	G	G	G		F	F	F	F	F	G	G			F	F	F	F	F	G	G			G	G	G	G	G	G	G	G	
8200 822	F	F	F	G	G	G	G		F	F	F	G	G	G	G			F	F	F	F	F	G	G			G	G	G	G	G	G	G	\vdash	
Cap (µF) 0.010 103	F	F	F	G	G	G	G		F	F	F	G	G	G G	G			F	F	F	F	F	G	G			G	G	G	G	G G	G	G	\vdash	
0.015 153	F	F	F	G	G	G			F	F	F	G G	G G	G				F	F	F	G G	G G	G G	G			G G	G G	G	G G	G	G G	G G	\vdash	
0.018 183	F	F	F	G	G				F	F	F	G	G	G				F	F	F	G	G	G				G	G	G	G	G	G	G	$\vdash\vdash$	
0.022 223	F	F	F	G	G				F	F	F	G	G					F	F	F	G	G	u				G	G	G	G	G	G		\vdash	
0.033 333	F	F	F	G					-	F	F	G	u					F	F	F	G	G					G	G	G	G	u			\vdash	
0.039 393	F	F	F	G					F	F	F	G						F	F	F	G	u					G	G	G	G				H	
0.047 473	F	F	F	G					F	F	F	G						F	F	F	G						G	G	G	G					
0.056 563	F	F	F	G					F	F	F	G						F	F	F	G						G	G	G	G					
0.068 683	F	F	G						F	F	G							F	F	F	G						G	G	G	G					
0.082 823	F	F	G						F	F	G							F	F	G							G	G							
0.100 104	F	F	G						F	F	G							F	F	G							G	G							
0.150 154	F	F							F	F	G							F	F	G							G	G							
0.220 224	F	F							F	F	G							F	F								G	G							
0.270 274	F	F							F	F								F	F								G	G							
0.330 334	F	F							F	F								F	F								G	G							
0.390 394	F	F							F	F								F	F								G	G							
0.470 474	F	F							F	F								F	F								G	G					oxdot	\square	
0.560 564	G	G							G	G								F	F															ш	
0.680 684									G	G								G	G															\sqcup	
0.820 824									_									G	G														ш	\sqcup	
1.000 105				_	_	_		1	_				_		_			_							1		_		_				$\vdash \vdash$	\sqcup	
Voltage (V)	600	630	1000			2500	3000	4000	600	630	1000	1500			3000	4000	5000	600	630	1000	1500			3000	4000	5000	600	630	1000	1500			3000	4000	5000
Case Size				18	325								2220	J								2225)								3640)			

Letter	А	С	Е	F	G	X
Max.	0.813	1.448	0.071	1.803	2.794	0.940
Thickness	(0.032)	(0.057)	(0.071)	(0.087)	(0.110)	(0.037)

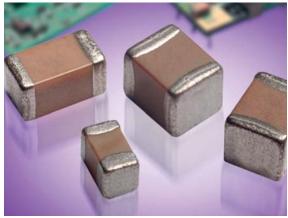
NOTE: Contact factory for non-specified capacitance values



High Voltage MLC Chips Tin/Lead Termination "B"



For 600V to 5000V Applications



NEW 630V RANGE

AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages, a full range of values that we are offering in this "B" termination.

Larger physical sizes than normally encountered chips are used to make high voltage MLC chip product. Special precautions must be taken in applying these chips in surface mount assemblies. The temperature gradient during heating or cooling cycles should not exceed 4°C per second. The preheat temperature must be within 50°C of the peak temperature reached by the ceramic bodies through the soldering process. Chip sizes 1210 and larger should be reflow soldered only. Capacitors may require protective surface coating to prevent external arcing.

For 1825, 2225 and 3640 sizes, AVX offers leaded version in either thru-hole or SMT configurations (for details see section on high voltage leaded MLC chips).

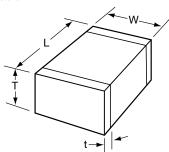
Not RoHS Compliant

HOW TO ORDER

<u>LD08</u>	A	A	<u>271</u>	<u>K</u>	A	<u>B</u>		A
AVX Style LD05 - 0805	Voltage 600V/630V = C 1000V = A	Temperature Coefficient COG = A	Capacitance Code (2 significant digits + no. of zeros)	Capacitance Tolerance COG: J = ±5%	Test Level A = Standard	Termination B = 5% Min Pb	Packaging 1 = 7" Reel 3 = 13" Reel	Special Code A = Standard
LD06 - 1206 LD10 - 1210 LD08 - 1808 LD12 - 1812	1500V = S 2000V = G 2500V = W 3000V = H	X7R = C	Examples: 10 pF = 100 100 pF = 101 1,000 pF = 102	$K = \pm 10\%$ $M = \pm 20\%$ X7R: $K = \pm 10\%$ $M = \pm 20\%$			9 = Bulk	
LD12 - 1812 LD13 - 1825 LD20 - 2220 LD14 - 2225	4000V = J 5000V = K		22,000 pF = 223 220,000 pF = 224 1 uF = 105	Z = +80%, -20%				
LD40 - 3640 ***			ι με = 103					

Notes: Capacitors with X7R dielectrics are not intended for applications across AC supply mains or AC line filtering with polarity reversal. Contact plant for recommendations. Contact factory for availability of Termination and Tolerance options for Specific Part Numbers.

^{***} AVX offers nonstandard chip sizes. Contact factory for details.



DIMENSIONS

millimeters (inches	6
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SIZE	LD05 (0805)	LD06 (1206)	LD10* (1210)	LD08* (1808)	LD12* (1812)	LD13* (1825)	LD20* (2220)	LD14* (2225)	LD40* (3640)
(L) Length	2.01 ± 0.20	3.20 ± 0.20	3.20 ± 0.20	4.57 ± 0.25	4.50 ± 0.30	4.50 ± 0.30	5.70 ± 0.40	5.72 ± 0.25	9.14 ± 0.25
	(0.079 ± 0.008)	(0.126 ± 0.008)	(0.126 ± 0.008)	(0.180 ± 0.010)	(0.177 ± 0.012)	(0.177 ± 0.012)	(0.224 ± 0.016)	(0.225 ± 0.010)	(0.360 ± 0.010)
(W) Width	1.25 ± 0.20	1.60 ± 0.20	2.50 ± 0.20	2.03 ± 0.25	3.20 ± 0.20	6.40 ± 0.30	5.00 ± 0.40	6.35 ± 0.25	10.2 ± 0.25
	(0.049 ±0.008)	(0.063 ± 0.008)	(0.098 ± 0.008)	(0.080 ± 0.010)	(0.126 ± 0.008)	(0.252 ± 0.012)	(0.197 ± 0.016)	(0.250 ± 0.010)	(0.400 ± 0.010)
(T) Thickness	1.30	1.52	1.70	2.03	2.54	2.54	3.30	2.54	2.54
Max.	(0.051)	(0.060)	(0.067)	(0.080)	(0.100)	(0.100)	(0.130)	(0.100)	(0.100)
(t) terminal min. max.	0.50 ± 0.25	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.76 (0.030)
	(0.020 ± 0.010)	0.75 (0.030)	0.75 (0.030)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.52 (0.060)

^{*} Reflow soldering only.



High Voltage MLC Chips Tin/Lead Termination "B"



For 600V to 5000V Applications

C0G Dielectric

Performance Characteristics

Capacitance Range	10 pF to 0.047 μF
	(25°C, 1.0 ±0.2 Vrms at 1kHz, for ≤ 1000 pF use 1 MHz)
Capacitance Tolerances	±5%, ±10%, ±20%
Dissipation Factor	0.1% max. (+25°C, 1.0 ±0.2 Vrms, 1kHz, for ≤ 1000 pF use 1 MHz)
Operating Temperature Range	-55°C to +125°C
Temperature Characteristic	0 ±30 ppm/°C (0 VDC)
Voltage Ratings	600, 630, 1000, 1500, 2000, 2500, 3000, 4000 & 5000 VDC (+125°C)
Insulation Resistance (+25°C, at 500 VDC)	100K M Ω min. or 1000 M Ω - μ F min., whichever is less
Insulation Resistance (+125°C, at 500 VDC)	10K M Ω min. or 100 M Ω - μ F min., whichever is less
Dielectric Strength	Minimum 120% rated voltage for 5 seconds at 50 mA max. current

HIGH VOLTAGE COG CAPACITANCE VALUES

VOLTA	GE	LD05 (0805)	LD06 (1206)	LD10 (1210)	LD08 (1808)	LD12 (1812)	LD13 (1825)	LD20 (2220)	LD14 (2225)	LD40 (3640)
600/630	min.	10pF	10 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF	1000 pF	1000 pF
000/000	max.	330pF	1200 pF	2700 pF	3300 pF	5600 pF	0.012 µF	0.012 µF	0.018 µF	0.047 µF
1000	min.	10pF	10 pF	10 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF	1000 pF
1000	max.	180pF	560 pF	1500 pF	2200 pF	3300 pF	8200 pF	0.010 μF	0.010 µF	0.022 µF
1500	min.		10 pF	10 pF	10 pF	10 pF	100 pF	100 pF	100 pF	100 pF
1500	max.	_	270 pF	680 pF	820 pF	1800 pF	4700 pF	4700 pF	5600 pF	0.010 µF
2000	min.	_	10 pF	10 pF	10 pF	10 pF	100 pF	100 pF	100 pF	100 pF
2000	max.	_	120 pF	270 pF	330 pF	1000 pF	1800 pF	2200 pF	2700 pF	6800 pF
2500	min.	_	_	_	10 pF	10 pF	10 pF	100 pF	100 pF	100 pF
2300	max.	_	_	_	180 pF	470 pF	1200 pF	1500 pF	1800 pF	3900 pF
3000	min.	_	_	-	10 pF	100 pF				
3000	max.	_	_	_	120 pF	330 pF	820 pF	1000 pF	1200 pF	2700 pF
4000	min.	_	_	_	10 pF	100 pF				
4000	max.	_	-	-	47 pF	150 pF	330 pF	470 pF	560 pF	1200 pF
5000	min.	_	_	_	_	_	_	10 pF	10 pF	10 pF
3000	max.	_	_	_	_	_	_	220 pF	270 pF	820 pF

X7R Dielectric

Performance Characteristics

Capacitance Range	10 pF to 0.56 μF (25°C, 1.0 ±0.2 Vrms at 1kHz)
Capacitance Tolerances	±10%; ±20%; +80%, -20%
Dissipation Factor	2.5% max. (+25°C, 1.0 ±0.2 Vrms, 1kHz)
Operating Temperature Range	-55°C to +125°C
Temperature Characteristic	±15% (0 VDC)
Voltage Ratings	600, 630, 1000, 1500, 2000, 2500, 3000, 4000 & 5000 VDC (+125°C)
Insulation Resistance (+25°C, at 500 VDC)	100K M Ω min. or 1000 M Ω - μ F min., whichever is less
Insulation Resistance (+125°C, at 500 VDC)	10K M Ω min. or 100 M Ω - μF min., whichever is less
Dielectric Strength	Minimum 120% rated voltage for 5 seconds at 50 mA max. current

HIGH VOLTAGE X7R MAXIMUM CAPACITANCE VALUES

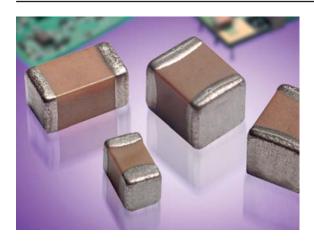
VOLTAGE	0805	1206	1210	1808	1812	1825	2220	2225	3640
600/630 min.	100pF	1000 pF	1000 pF	1000 pF	1000 pF	0.010 µF	0.010 µF	0.010 µF	0.010 μF
max.	6800pF	0.022 µF	0.056 µF	0.068 µF	0.120 μF	0.270 µF	0.270 µF	0.330 µF	0.560 µF
1000 min.	100pF	100 pF	1000 pF	1000 pF	1000 pF	1000 pF	1000 pF	1000 pF	0.010 µF
max.	1500pF	6800 pF	0.015 µF	0.018 µF	0.039 µF	0.100 µF	0.120 µF	0.150 µF	0.220 µF
1500 min.	_	100 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF	1000 pF	1000 pF
max.	_	2700 pF	5600 pF	6800 pF	0.015 µF	0.056 µF	0.056 μF	0.068 µF	0.100 µF
2000 min.	_	10 pF	100 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF	1000 pF
max.	_	1500 pF	3300 pF	3300 pF	8200 pF	0.022 µF	0.027 μF	0.033 µF	0.027 µF
2500 min.	_	_	1	10 pF	10 pF	100 pF	100 pF	100 pF	1000 pF
max.	_	_	_	2200 pF	5600 pF	0.015 µF	0.018 μF	0.022 µF	0.022 µF
3000 min.	_	_	_	10 pF	10 pF	100 pF	100 pF	100 pF	1000 pF
max.	_	_	-	1800 pF	3900 pF	0.010 µF	0.012 µF	0.015 µF	0.018 µF
4000 min.	_	_	_	_	_	_	_	_	100 pF
max.	_		_			_		_	6800 pF
5000 min.	_	_	_	_	_	_	_	_	100 pF
max.	_	_	_	_	_	_	_	_	3300 pF



High Voltage MLC Chips FLEXITERM®



For 600V to 3000V Applications



High value, low leakage and small size are difficult parameters to obtain in capacitors for high voltage systems. AVX special high voltage MLC chips capacitors meet these performance characteristics and are designed for applications such as snubbers in high frequency power converters, resonators in SMPS, and high voltage coupling/DC blocking. These high voltage chip designs exhibit low ESRs at high frequencies.

To make high voltage chips, larger physical sizes than are normally encountered are necessary. These larger sizes require that special precautions be taken in applying these chips in surface mount assemblies. In response to this, and to follow from the success of the FLEXITERM® range of low voltage parts, AVX is delighted to offer a FLEXITERM® high voltage range of capacitors, FLEXITERM®.

The FLEXITERM® layer is designed to enhance the mechanical flexure and temperature cycling performance of a standard ceramic capacitor, giving customers a solution where board flexure or temperature cycle damage are concerns.

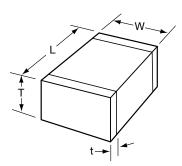


HOW TO ORDER

1808	A	<u>C</u>	272	<u>K</u>	A	<u>Z</u>	1	A
AVX	Voltage	Temperature	Capacitance Code	Capacitance	Test Level	Termination*	Packaging	Special
Style	600V/630V = C	Coefficient	(2 significant digits	Tolerance		Z = FLEXITERM®	1 = 7" Reel	Code
0805	1000V = A	COG = A	+ no. of zeros)	C0G: $J = \pm 5\%$		100% Tin	3 = 13" Reel	A = Standard
1206	1500V = S	X7R = C	Examples:	$K = \pm 10\%$		(RoHS Compliant)	9 = Bulk	
1210	2000V = G		10 pF = 100	$M = \pm 20\%$				
1808	2500V = W		100 pF = 101	X7R: $K = \pm 10\%$				
1812	3000V = H		1,000 pF = 102	$M = \pm 20\%$				
1825			22,000 pF = 223	Z = +80%,				
2220			220,000 pF = 224	-20%				
2225			$1 \mu F = 105$					

Notes: Capacitors with X7R dielectrics are not intended for applications across AC supply mains or AC line filtering with polarity reversal. Contact plant for recommendations. Contact factory for availability of Termination and Tolerance options for Specific Part Numbers.

^{***} AVX offers nonstandard chip sizes. Contact factory for details.



DIMENSIONS millimeters (inches)

SIZE	0805	1206	1210*	1808*	1812*	1825*	2220*	2225*
(L) Length	2.01 ± 0.20	3.20 ± 0.20	3.20 ± 0.20	4.57 ± 0.25	4.50 ± 0.30	4.50 ± 0.30	5.7 ± 0.40	5.72 ± 0.25
	(0.079 ± 0.008)	(0.126 ± 0.008)	(0.126 ± 0.008)	(0.180 ± 0.010)	(0.177 ± 0.012)	(0.177 ± 0.012)	(0.224 ± 0.016)	(0.225 ± 0.010)
(W) Width	1.25 ± 0.20	1.60 ± 0.20	2.50 ± 0.20	2.03 ± 0.25	3.20 ± 0.20	6.40 ± 0.30	5.0 ± 0.40	6.35 ± 0.25
	(0.049 ± 0.008)	(0.063 ± 0.008)	(0.098 ± 0.008)	(0.080 ± 0.010)	(0.126 ± 0.008)	(0.252 ± 0.012)	(0.197 ± 0.016)	(0.250 ± 0.010)
(T) Thickness	1.30	1.52	1.70	2.03	2.54	2.54	3.30	2.54
Max.	(0.051)	(0.060)	(0.067)	(0.080)	(0.100)	(0.100)	(0.130)	(0.100)
(t) terminal min.	0.50 ± 0.25	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)	0.25 (0.010)
max.	(0.020 ± 0.010)	0.75 (0.030)	0.75 (0.030)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)	1.02 (0.040)

*Reflow Soldering Only



High Voltage MLC Chips FLEXITERM®



For 600V to 5000V Applications

C0G Dielectric

Performance Characteristics

Capacitance Range	10 pF to 0.018 μF (25°C, 1.0 ±0.2 Vrms at 1kHz, for ≤ 1000 pF use 1 MHz)
Capacitance Tolerances	±5%, ±10%, ±20%
Dissipation Factor	0.1% max. (+25°C, 1.0 \pm 0.2 Vrms, 1kHz, for \leq 1000 pF use 1 MHz)
Operating Temperature Range	-55°C to +125°C
Temperature Characteristic	0 ±30 ppm/°C (0 VDC)
Voltage Ratings	600, 630, 1000, 1500, 2000, 2500, 3000, 4000 & 5000 VDC (+125°C)
Insulation Resistance (+25°C, at 500 VDC)	100K M Ω min. or 1000 M Ω - μ F min., whichever is less
Insulation Resistance (+125°C, at 500 VDC)	10K M Ω min. or 100 M Ω - μ F min., whichever is less
Dielectric Strength	Minimum 120% rated voltage for 5 seconds at 50 mA max. current

HIGH VOLTAGE COG CAPACITANCE VALUES

VOLTAGE	0805	1206	1210	1808	1812	1825	2220	2225
600/630 min.	10pF	10 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF	1000 pF
max.	330pF	1200 pF	2700 pF	3300 pF	5600 pF	0.012 μF	0.012 μF	0.018 µF
1000 min.	10pF	10 pF	10 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF
max.	180pF	560 pF	1500 pF	2200 pF	3300 pF	8200 pF	0.010 μF	0.010 µF
1500 min.	1 1	10 pF	10 pF	10 pF	10 pF	100 pF	100 pF	100 pF
max.		270 pF	680 pF	820 pF	1800 pF	4700 pF	4700 pF	5600 pF
2000 min.		10 pF	10 pF	10 pF	10 pF	100 pF	100 pF	100 pF
max.		120 pF	270 pF	330 pF	1000 pF	1800 pF	2200 pF	2700 pF
2500 min.		_	_	10 pF	10 pF	10 pF	100 pF	100 pF
max.		_	_	180 pF	470 pF	1200 pF	1500 pF	1800 pF
3000 min.		_	_	10 pF	10 pF	10 pF	10 pF	10 pF
max.		_	_	120 pF	330 pF	820 pF	1000 pF	1200 pF
4000 min.		_	_	10 pF	10 pF	10 pF	10 pF	10 pF
max.		_	_	47 pF	150 pF	330 pF	470 pF	560 pF
5000 min. max.		_ _	_ _	_	_ _	_ _	10 pF 220 pF	10 pF 270 pF

X7R Dielectric

Performance Characteristics

Capacitance Range	10 pF to 0.33 μF (25°C, 1.0 ±0.2 Vrms at 1kHz)
Capacitance Tolerances	±10%; ±20%; +80%, -20%
Dissipation Factor	2.5% max. (+25°C, 1.0 ±0.2 Vrms, 1kHz)
Operating Temperature Range	-55°C to +125°C
Temperature Characteristic	±15% (0 VDC)
Voltage Ratings	600, 630, 1000, 1500, 2000, 2500, 3000, 4000 & 5000 VDC (+125°C)
Insulation Resistance (+25°C, at 500 VDC)	100K M Ω min. or 1000 M Ω - μF min., whichever is less
Insulation Resistance (+125°C, at 500 VDC)	10K M Ω min. or 100 M Ω - μ F min., whichever is less
Dielectric Strength	Minimum 120% rated voltage for 5 seconds at 50 mA max. current

HIGH VOLTAGE X7R MAXIMUM CAPACITANCE VALUES

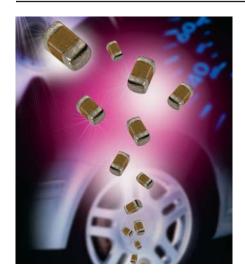
VOLTAGE	0805	1206	1210	1808	1812	1825	2220	2225
600/630 min.	100pF	1000 pF	1000 pF	1000 pF	1000 pF	0.010 µF	0.010 µF	0.010 µF
max.	6800pF	0.022 µF	0.056 µF	0.068 µF	0.120 µF	0.270 µF	0.270 µF	0.330 µF
1000 min. max.	100pF 1500pF	100 pF 6800 pF	1000 pF 0.015 μF	1000 pF 0.018 µF	1000 pF 0.039 μF	1000 pF 0.100 µF	1000 pF 0.120 µF	1000 pF 0.150 µF
1500 min.	_	100 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF	1000 pF
max.	_	2700 pF	5600 pF	6800 pF	0.015 µF	0.056 µF	0.056 µF	0.068 µF
2000 min.	_	10 pF	100 pF	100 pF	100 pF	100 pF	1000 pF	1000 pF
2000 max.	_	1500 pF	3300 pF	3300 pF	8200 pF	0.022 µF	0.027 µF	0.033 µF
2500 min.	_		_	10 pF	10 pF	100 pF	100 pF	100 pF
2500 max.	_	_	_	2200 pF	5600 pF	0.015 µF	0.018 µF	0.022 µF
3000 min.	_	_	_	10 pF	10 pF	100 pF	100 pF	100 pF
max.	_	_	_	1800 pF	3900 pF	0.010 pF	0.012 µF	0.015 µF



High Voltage MLC Chip Capacitors



For 600V to 3000V Automotive Applications - AEC-Q200



Modern automotive electronics could require components capable to work with high voltage (e.g. xenon lamp circuits or power converters in hybrid cars). AVX offer high voltage ceramic capacitors qualified according to AEC-Q200 standard.

High value, low leakage and small size are difficult parameters to obtain in capacitors for high voltage systems. AVX special high voltage MLC chip capacitors meet these performance characteristics and are designed for applications such as snubbers in high frequency power converters, resonators in SMPS, and high voltage coupling / dc blocking. These high voltage chip designs exhibit low ESRs at high frequencies.

Due to high voltage nature, larger physical dimensions are necessary. These larger sizes require special precautions to be taken in applying of MLC chips. The temperature gradient during heating or cooling cycles should not exceed 4°C per second. The preheat temperature must be within 50°C of the peak temperature reached by the ceramic bodies through the soldering process. Chip sizes 1210 and larger should be reflow soldered only. Capacitors may require protective surface coating to prevent external arcing.

To improve mechanical and thermal resistance, AVX recommend to use flexible terminations system - FLEXITERM®.

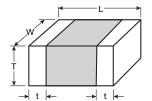
HOW TO ORDER

1210	<u>C</u>	C	223	<u>K</u>	4	Ŧ	1	A
AVX	Voltage	Dielectric	Capacitance Code	Capacitance	Failure Rate	Termination	Packaging	Special
Style	C = 630V	C = X7R	(2 significant digits	Tolerance	4 = Automotive	T = Plated Ni/Sn	1 = 7" Reel	Code
1206	A = 1000V		+ no. of zeros)	$J = \pm 5\%$		$Z = FLEXITERM^{\otimes}$	3 = 13" Reel	A = Standard
1210	S = 1500V		e.g. 103 = 10nF	$K = \pm 10\%$			9 = Bulk	
1808	G = 2000V		(223 = 22nF)	$M = \pm 20\%$				
1812	W = 2500V							
2220	H = 3000V				*AVX offers	nonstandard case size	s. Contact factory	for details.

Notes: Capacitors with X7R dielectrics are not intended for applications across AC supply mains or AC line filtering with polarity reversal. Please contact AVX for recommendations.



CHIP DIMENSIONS DESCRIPTION (See capacitance range chart on page 92)



L = Length
W = Width
T = Thickness
t = Terminal

X7R DIELECTRIC PERFORMANCE CHARACTERISTICS

Parameter/Test	Specification Limits	Measuring Conditions
Operating Temperature Range	-55°C to +125°C	Temperature Cycle Chamber
Capacitance Dissipation Factor Capacitance Tolerance	within specified tolerance 2.5% max. $\pm 5\%$ (J), $\pm 10\%$ (K), $\pm 20\%$ (M)	Freq.: 1kHz ±10% Voltage: 1.0Vrm s ±0.2Vrms T = +25°C, V = 0Vdc
Temperature Characteristics	$X7R = \pm 15\%$	Vdc = 0V, T = (-55°C to +125°C)
Insulation Resistance	100GΩ min. or 1000MΩ • μF min. (whichever is less) 10GΩ min. or 100MΩ • μF min. (whichever is less)	T = +25°C, V = 500Vdc T = +125°C, V = 500Vdc (t ≥ 120 sec, I ≤ 50mA)
Dielectric Strength	No breakdown or visual defect	120% of rated voltage t ≤ 5 sec, I ≤ 50mA



High Voltage MLC Chip Capacitors



For 600V to 3000V Automotive Applications – AEC-Q200

X7R CAPACITANCE RANGE PREFERRED SIZES ARE SHADED

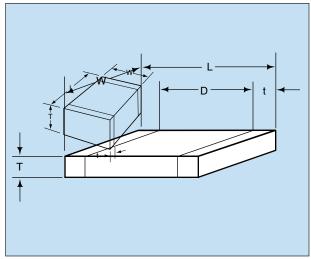
Case Size	,			1206				12	10				18	08					18	312			2220			
Soldering			Ref	flow/W	/ave			Reflov		,				v Only						w Only	/				w Only	,
(L) Length n	nm			.20 ± 0. 26 ± 0.				3.20 :	± 0.20)\			4.57	£ 0.25 £ 0.010)						± 0.30 ± 0.012	`				± 0.40 ± 0.016	
	in.) nm		1.	$.60 \pm 0.$	20			2.50	± 0.20				2.03 ±	£ 0.25					3.20 -	± 0.20				5.00 :	± 0.40	
	in.) nm		(0.0)	1.52				(0.098	70	3)		(2.0	± 0.010) 03)				2.	± 0.008 54)		(0.197 ± 0.016) 3.30			
	in.)		0	(0.060)					0.010)				0.25 ((0.1	00)			_	(0.1	130)	
	nin nax		0.	75 (0.0)	30)			0.25 (0.030)				1.02 (0.040)					1.02 (0.040)				1.02 (0.040)	
Voltage (V)		630	1000	1500	2000	2500	630	1000	1500	2000	630	1000	1500	2000	2500	3000	630	1000	1500	2000	2500	3000	630	1000	1500	2000
Cap (pF) 100	101																						-		<u> </u>	
120	121																						├			
150	151																						\vdash			
180	181																						-		\vdash	
220	221																						-		\vdash	
270	271																						-		\vdash	
330	331																								\vdash	
390	391 471																								\vdash	_
470 560	561																									_
680	681																									_
820	821																									
1000	102																									
1200	122																									
1500	152																									
1800	182																									
2200	222																									
2700	272																									
3300	332																									
3900	392																									
4700	472																									
5600	562																									
6800	682																									
8200	822																									
Cap (μF) 0.01	103																									
0.012	123																									
0.015	153																									
0.018	183																									
0.022	223																									
0.027	273																									<u> </u>
0.033	333																									
0.039	393																									
0.047	473						_																		<u> </u>	
0.056	563										_														\vdash	
0.068	683						-																			_
0.082	823 104				\vdash		\vdash	\vdash								-									$\vdash \vdash$	
0.100	104										-															_
0.120	154																									\vdash
Voltage (V)	1.04	630	1000	1500	2000	2500	630	1000	1500	2000	630	1000	1500	2000	2500	3000	630	1000	1500	2000	2500	3000	630	1000	1500	2000
Case Size				1206					10				_	808			1			12	,	1	1		20	
	,	555					000				555		_			1 2000	555					1 0000				_

NOTE: Contact factory for non-specified capacitance values

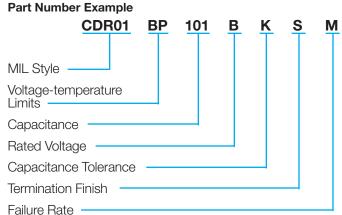


Part Number Example CDR01 thru CDR06





MILITARY DESIGNATION PER MIL-PRF-55681



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

MIL Style: CDR01, CDR02, CDR03, CDR04, CDR05, CDR06

Voltage Temperature Limits:

BP = 0 ± 30 ppm/°C without voltage; 0 ± 30 ppm/°C with rated voltage from -55°C to +125°C

BX = $\pm 15\%$ without voltage; +15-25% with rated voltage from -55° C to $+125^{\circ}$ C

Capacitance: Two digit figures followed by multiplier (number of zeros to be added) e.g., 101 = 100 pF

Rated Voltage: A = 50V, B = 100V

Capacitance Tolerance: J ± 5%, K ± 10%, M ± 20%

Termination Finish:

M = Palladium Silver N = Silver Nickel Gold S = Solder-coated Y = 100% Tin U = Base Metallization/Barrier Metal/Solder Coated* W = Base Metallization/Barrier Metal/Tinned (Tin or Tin/ Lead Alloy)

*Solder shall have a melting point of 200°C or less.

Failure Rate Level: M = 1.0%, P = .1%, R = .01%, S = .001%

Packaging: Bulk is standard packaging. Tape and reel per RS481 is available upon request.

Not RoHS Compliant

CROSS REFERENCE: AVX/MIL-PRF-55681/CDR01 THRU CDR06*

Per	AVX	1	147 HIL (140	Thickr	ness (T)	D		Terminatio	n Band (t)
MIL-PRF-55681	Style	Length (L)	Width (W)	Min.	Max.	Min.	Max.	Min.	Max.
CDR01	0805	.080 ± .015	$.050 \pm .015$.022	.055	.030	_	.010	_
CDR02	1805	.180 ± .015	$.050 \pm .015$.022	.055	-	_	.010	.030
CDR03	1808	.180 ± .015	.080 ± .018	.022	.080	-	_	.010	.030
CDR04	1812	.180 ± .015	.125 ± .015	.022	.080	-	_	.010	.030
CDR05	1825	.180 ^{+.020} 015	.250 +.020 015	.020	.080	_	_	.010	.030
CDR06	2225	.225 ± .020	.250 ± .020	.020	.080	_	_	.010	.030

*For CDR11, 12, 13, and 14 see AVX Microwave Chip Capacitor Catalog



Military Part Number Identification CDR01 thru CDR06



Rated temperature WVDC

100

100

100

100

and voltage-

temperature limits

BP BP

BP

ВХ

100

50

50

CDR01 thru CDR06 to MIL-PRF-55681

Military

Type

Designation

CDR03BP331B---

CDR03BP391B---

CDR03BP471B---

CDR03BP561B---

AVX Style 1808/CDR03

Capacitance

in pF

390

470

560

Capacitance

tolerance

J,K

J J,K

Military Type Designation	Capacitance in pF	Capacitance tolerance	Rated temperature and voltage- temperature limits	WVDC		
AVX Style 0	805/CDR01			,		
CDR01BP100B	10	J,K	BP	100		
CDR01BP120B	12	J	BP	100		
CDR01BP150B	15	J,K	BP	100		
CDR01BP180B	18	J	BP	100		
CDR01BP220B	22	J,K	BP	100		
CDR01BP270B	27	J	BP	100		
CDR01BP330B	33	J,K	BP	100		
CDR01BP390B	39	J	BP	100		
CDR01BP470B	47	J,K	BP	100		
CDR01BP560B	56	J	BP	100		
CDR01BP680B	68	J,K	BP	100		
CDR01BP820B	82	J	BP	100		
CDR01BP101B	100	J,K	BP	100		
CDR01B121B	120	J,K	BP,BX	100		
CDR01B151B	150	J,K	BP,BX	100		
CDR01B181B	180	J,K	BP,BX	100		
CDR01BX221B	220	K,M	BX	100		
CDR01BX271B	270	K	BX	100		
CDR01BX331B	330	K,M	BX	100		
CDR01BX391B	390	K	BX	100		
CDR01BX471B	470	K,M	BX	100		
CDR01BX561B	560	K	BX	100		
CDR01BX681B	680	K,M	BX	100		
CDR01BX821B	820	K	BX	100		
CDR01BX102B	1000	K,M	BX	100		
CDR01BX122B	1200	K	BX	100		
CDR01BX152B	1500	K,M	BX	100		
CDR01BX182B	1800	K	BX	100		
CDR01BX222B	2200	K,M	BX	100		
CDR01BX272B	2700	K	BX	100		
CDR01BX332B	3300	K,M	BX	100		
CDR01BX392A	3900	K	BX	50		
CDR01BX472A	4700	K,M	BX	50		
AVX Style 18	805/CDR02					
CDR02BP221B	220	J,K	BP	100		
CDR02BP271B	270	J	BP	100		
CDR02BX392B	3900	K	BX	100		
CDR02BX472B	4700	K,M	BX	100		
CDR02BX562B	5600	K	BX	100		
CDR02BX682B	6800	K,M	BX	100		
CDR02BX822B	8200	K	BX	100		
CDR02BX103B	10,000	K,M	BX	100		
CDR02BX123A	12,000	K	BX	50		
CDR02BX153A	15,000	K,M	BX	50		
CDR02BX183A	18,000	K	BX	50		
CDR02BX223A	22,000	K,M	BX	50		
Add appropriate failure rate						

- Add appropriate termination finish

Capacitance Tolerance

CDR03BP681B	680	J,K	BP BP	100
CDR03BP821B CDR03BP102B CDR03BX123B CDR03BX153B CDR03BX183B	820 1000 12,000 15,000 18,000	J J,K K K,M K	BP BP BX BX BX	100 100 100 100 100
CDR03BX223B CDR03BX273B CDR03BX333B CDR03BX393A CDR03BX473A	22,000 27,000 33,000 39,000 47,000	K,M K K,M K K,M	BX BX BX BX BX	100 100 100 50 50
CDR03BX563A CDR03BX683A	56,000 68,000	K K,M	BX BX	50 50
AVX Style 18	12/CDR04			
CDR04BP122B CDR04BP152B CDR04BP182B CDR04BP222B CDR04BP332B CDR04BX33B CDR04BX473B CDR04BX563B CDR04BX823A CDR04BX104A CDR04BX124A CDR04BX154A CDR04BX154A CDR04BX184A	1200 1500 1800 2200 2700 3300 39,000 47,000 56,000 82,000 100,000 120,000 180,000	J J,K J,K K,M K,M K,M K,M	BP BP BP BP BX BX BX BX BX BX BX BX BX BX	100 100 100 100 100 100 100 100 50 50 50
AVX Style 18	25/CDR05			
CDR05BP392B CDR05BP472B CDR05BP562B CDR05BX683B CDR05BX823B	3900 4700 5600 68,000 82,000	J,K J,K J,K K,M K	BP BP BP BX BX	100 100 100 100 100
CDR05BX104B CDR05BX124B CDR05BX154B CDR05BX224A CDR05BX274A	100,000 120,000 150,000 220,000 270,000	K,M K K,M K,M	BX BX BX BX BX	100 100 100 50 50
CDR05BX334A	330,000	K,M	BX	50
AVX Style 22	25/CDR06	I		I
CDR06BP682B CDR06BP103B	6800 8200	J,K J,K	BP BP	100 100

Add appropriate failure rate

10,000

390,000

470.000

Add appropriate termination finish

J,K

K K,M

Capacitance Tolerance

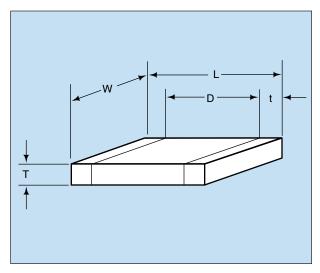
CDR06BP103B---

CDR06BX394A---

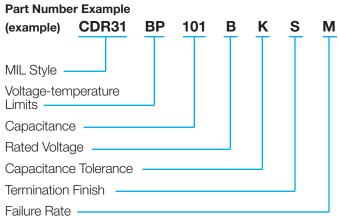
CDR06BX474A--

Part Number Example CDR31 thru CDR35





MILITARY DESIGNATION PER MIL-PRF-55681



NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

MIL Style: CDR31, CDR32, CDR33, CDR34, CDR35

Voltage Temperature Limits:

BP = 0 ± 30 ppm/°C without voltage; 0 ± 30 ppm/°C with rated voltage from -55°C to +125°C

BX = $\pm 15\%$ without voltage; +15-25% with rated voltage from -55°C to +125°C

Capacitance: Two digit figures followed by multiplier (number of zeros to be added) e.g., 101 = 100 pF

Rated Voltage: A = 50V, B = 100V

Capacitance Tolerance: B \pm .10 pF, C \pm .25 pF, D \pm .5 pF, $F \pm 1\%$, $J \pm 5\%$, $K \pm 10\%$,

 $M \pm 20\%$

Termination Finish:

M = Palladium Silver N = Silver Nickel Gold

S = Solder-coated Y = 100% Tin

U = Base Metallization/Barrier Metal/Solder Coated*

W = Base Metallization/Barrier Metal/Tinned (Tin or Tin/ Lead Alloy)

*Solder shall have a melting point of 200°C or less.

Failure Rate Level: M = 1.0%, P = .1%, R = .01%, S = .001%

Packaging: Bulk is standard packaging. Tape and reel per RS481 is available upon request.

Not RoHS Compliant

CROSS REFERENCE: AVX/MIL-PRF-55681/CDR31 THRU CDR35

Per MIL-PRF-55681	AVX	Length (L)	Width (W)	Thickness (T)	D	Termination Band (t)			
(Metric Sizes)	Style	(mm)	(mm)	Max. (mm)	Min. (mm)	Max. (mm)	Min. (mm)		
CDR31	0805	2.00	1.25	1.3	.50	.70	.30		
CDR32	1206	3.20	1.60	1.3	_	.70	.30		
CDR33	1210	3.20	2.50	1.5	_	.70	.30		
CDR34	1812	4.50	3.20	1.5	_	.70	.30		
CDR35	1825	4.50	6.40	1.5	_	.70	.30		





Military Part Number Identification CDR31

CDR31 to MIL-PRF-55681/7

Military Type Designation <u>1</u> /	Capacitance in pF	Capacitance tolerance	Rated temperature and voltage-temperature limits	WVDC
AVX Style 08	305/CDR31	(BP)		•
CDR31BP1R0B	1.0	B,C	BP	100
CDR31BP1R1B	1.1	B,C	BP	100
CDR31BP1R2B	1.2	B,C	BP	100
CDR31BP1R3B	1.3	B,C	BP	100
CDR31BP1R5B	1.5	B,C	BP	100
CDR31BP1R6B	1.6	B,C	BP	100
CDR31BP1R8B	1.8	B,C	BP	100
CDR31BP2R0B	2.0	B,C	BP	100
CDR31BP2R2B	2.2	B,C	BP	100
CDR31BP2R4B	2.4	B,C	BP	100
CDR31BP2R7B	2.7	B,C,D	BP	100
CDR31BP3R0B	3.0	B,C,D	BP	100
CDR31BP3R3B	3.3	B,C,D	BP	100
CDR31BP3R6B	3.6	B,C,D	BP	100
CDR31BP3R9B	3.9	B,C,D	BP	100
CDR31BP4R3B	4.3	B,C,D	BP	100
CDR31BP4R7B	4.7	B,C,D	BP	100
CDR31BP5R1B	5.1	B,C,D	BP	100
CDR31BP5R6B	5.6	B,C,D	BP	100
CDR31BP6R2B	6.2	B,C,D	BP	100
CDR31BP6R8B	6.8	B,C,D	BP	100
CDR31BP7R5B	7.5	B,C,D	BP	100
CDR31BP8R2B	8.2	B,C,D	BP	100
CDR31BP9R1B	9.1	B,C,D	BP	100
CDR31BP100B	10	F,J,K	BP	100
CDR31BP110B	11	F,J,K	BP	100
CDR31BP120B	12	F,J,K	BP	100
CDR31BP130B	13	F,J,K	BP	100
CDR31BP150B	15	F,J,K	BP	100
CDR31BP160B	16	F,J,K	BP	100
CDR31BP180B	18	F,J,K	BP	100
CDR31BP200B	20	F,J,K	BP	100
CDR31BP220B	22	F,J,K	BP	100
CDR31BP240B	24	F,J,K	BP	100
CDR31BP270B	27	F,J,K	BP	100
CDR31BP300B	30	F,J,K	BP	100
CDR31BP330B	33	F,J,K	BP	100
CDR31BP360B	36	F,J,K	BP	100
CDR31BP390B	39	F,J,K	BP	100
CDR31BP430B	43	F,J,K	BP	100
CDR31BP470B	47	F,J,K	BP	100
CDR31BP510B	51	F,J,K	BP	100
CDR31BP560B	56	F,J,K	BP	100
CDR31BP620B	62	F,J,K	BP	100
CDR31BP680B	68	F,J,K	BP	100
CDR31BP750B	75	F,J,K	BP	100
CDR31BP820B	82	F,J,K	BP	100
CDR31BP910B	91	F,J,K	BP	100

Add appropriate failure rate
 Add appropriate termination finish
 Capacitance Tolerance

Military Type Designation <u>1</u> /	Capacitance in pF	Capacitance tolerance	Rated temperature and voltage- temperature limits	WVDC
AVX Style 08	305/CDR31	(BP) cont	'd	
CDR31BP101B	100	F,J,K	BP	100
CDR31BP111B	110	F,J,K	BP	100
CDR31BP121B	120	F,J,K	BP	100
CDR31BP131B	130	F,J,K	BP	100
CDR31BP151B	150	F,J,K	BP	100
CDR31BP161B	160	F,J,K	BP	100
CDR31BP181B	180	F,J,K	BP	100
CDR31BP201B	200	F,J,K	BP	100
CDR31BP221B	220	F,J,K	BP	100
CDR31BP241B	240	F,J,K	BP	100
CDR31BP271B	270	F,J,K	BP	100
CDR31BP301B	300	F,J,K	BP	100
CDR31BP331B	330	F,J,K	BP	100
CDR31BP361B	360	F,J,K	BP	100
CDR31BP391B	390	F,J,K	BP	100
CDR31BP431B	430	F,J,K	BP	100
CDR31BP471B	470	F,J,K	BP	100
CDR31BP511A	510	F,J,K	BP	50
CDR31BP561A	560	F,J,K	BP	50
CDR31BP621A	620	F,J,K	BP	50
CDR31BP681A	680	F,J,K	BP	50
AVX Style 08	305/CDR31	(BX)		ı
CDR31BX471B CDR31BX561B CDR31BX881B CDR31BX821B CDR31BX102B CDR31BX122B CDR31BX122B CDR31BX152B CDR31BX182B	470 560 680 820 1,000 1,200 1,500 1,800	K,M K,M K,M K,M K,M K,M K,M	BX BX BX BX BX BX BX BX	100 100 100 100 100 100 100
CDR31BX222B	2,200	K,M	BX	100
CDR31BX272B	2,700	K,M	BX	
CDR31BX332B	3,300	K,M	BX	100
CDR31BX392B	3,900	K,M	BX	100
CDR31BX472B	4,700	K,M	BX	100
CDR31BX562A	5,600	K,M	BX	50
CDR31BX682A	6,800	K,M	BX	50
CDR31BX822A CDR31BX103A CDR31BX123A CDR31BX153A CDR31BX183A	8,200 10,000 12,000 15,000 18,000	K,M K,M K,M K,M	BX BX BX BX BX	50 50 50 50 50

Add appropriate failure rate

- Add appropriate termination finish

Capacitance Tolerance



^{1/} The complete part number will include additional symbols to indicate capacitance tolerance, termination and failure rate level.



Military Part Number Identification CDR32

CDR32 to MIL-PRF-55681/8

Military Type Designation <u>1</u> /	Capacitance in pF	Capacitance tolerance	Rated temperature and voltage-temperature limits	WVDC
AVX Style 12	206/CDR32	(BP)		
CDR32BP1R0B	1.0	B,C	BP	100
CDR32BP1R1B	1.1	B,C	BP	100
CDR32BP1R2B	1.2	B,C	BP	100
CDR32BP1R3B	1.3	B,C	BP	100
CDR32BP1R5B	1.5	B,C	BP	100
CDR32BP1R6B	1.6	B,C	BP	100
CDR32BP1R8B	1.8	B,C	BP	100
CDR32BP2R0B	2.0	B,C	BP	100
CDR32BP2R2B	2.2	B,C	BP	100
CDR32BP2R4B	2.4	B,C	BP	100
CDR32BP2R7B	2.7	B,C,D	BP	100
CDR32BP3R0B	3.0	B,C,D	BP	100
CDR32BP3R3B	3.3	B,C,D	BP	100
CDR32BP3R6B	3.6	B,C,D	BP	100
CDR32BP3R9B	3.9	B,C,D	BP	100
CDR32BP4R3B	4.3	B,C,D	BP	100
CDR32BP4R7B	4.7	B,C,D	BP	100
CDR32BP5R1B	5.1	B,C,D	BP	100
CDR32BP5R6B	5.6	B,C,D	BP	100
CDR32BP6R2B	6.2	B,C,D	BP	100
CDR32BP6R8B	6.8	B,C,D	BP	100
CDR32BP7R5B	7.5	B,C,D	BP	100
CDR32BP8R2B	8.2	B,C,D	BP	100
CDR32BP9R1B	9.1	B,C,D	BP	100
CDR32BP100B	10	F,J,K	BP	100
CDR32BP110B	11	F,J,K	BP	100
CDR32BP120B	12	F,J,K	BP	100
CDR32BP130B	13	F,J,K	BP	100
CDR32BP150B	15	F,J,K	BP	100
CDR32BP160B	16	F,J,K	BP	100
CDR32BP180B CDR32BP200B CDR32BP220B CDR32BP240B CDR32BP270B	18	F,J,K	BP	100
	20	F,J,K	BP	100
	22	F,J,K	BP	100
	24	F,J,K	BP	100
	27	F,J,K	BP	100
CDR32BP300B CDR32BP330B CDR32BP360B CDR32BP390B CDR32BP430B	30	F,J,K	BP	100
	33	F,J,K	BP	100
	36	F,J,K	BP	100
	39	F,J,K	BP	100
	43	F,J,K	BP	100
CDR32BP470B CDR32BP510B CDR32BP560B CDR32BP620B CDR32BP680B	47	F,J,K	BP	100
	51	F,J,K	BP	100
	56	F,J,K	BP	100
	62	F,J,K	BP	100
	68	F,J,K	BP	100
CDR32BP750B	75	F,J,K	BP	100
CDR32BP820B	82	F,J,K	BP	100
CDR32BP910B	91	F,J,K	BP	100

Add appropriate failure rate
 Add appropriate termination finish
 Capacitance Tolerance

B.#1114			Bata ditamanana!	WA/DC
Military Type Designation <u>1</u> /	Capacitance in pF	Capacitance tolerance	Rated temperature and voltage- temperature limits	WVDC
AVX Style 12	206/CDR32	(BP) cont	'd	
CDR32BP101B	100	F,J,K	BP	100
CDR32BP111B	110	F,J,K	BP	100
CDR32BP121B	120	F,J,K	BP	100
CDR32BP131B	130	F,J,K	BP	100
CDR32BP151B	150	F,J,K	BP	100
CDR32BP161B	160	F,J,K	BP	100
CDR32BP181B	180	F,J,K	BP	100
CDR32BP201B	200	F,J,K	BP	100
CDR32BP221B	220	F,J,K	BP	100
CDR32BP241B	240	F,J,K	BP	100
CDR32BP271B	270	F,J,K	BP	100
CDR32BP301B	300	F,J,K	BP	100
CDR32BP331B	330	F,J,K	BP	100
CDR32BP361B	360	F,J,K	BP	100
CDR32BP391B	390	F,J,K	BP	100
CDR32BP431B	430	F,J,K	BP	100
CDR32BP471B	470	F,J,K	BP	100
CDR32BP511B	510	F,J,K	BP	100
CDR32BP561B	560	F,J,K	BP	100
CDR32BP621B	620	F,J,K	BP	100
CDR32BP681B	680	F,J,K	BP	100
CDR32BP751B	750	F,J,K	BP	100
CDR32BP821B	820	F,J,K	BP	100
CDR32BP911B	910	F,J,K	BP	100
CDR32BP102B	1,000	F,J,K	BP	100
CDR32BP112A	1,100	F,J,K	BP	50
CDR32BP122A	1,200	F,J,K	BP	50
CDR32BP132A	1,300	F,J,K	BP	50
CDR32BP152A	1,500	F,J,K	BP	50
CDR32BP162A	1,600	F,J,K	BP	50
CDR32BP182A	1,800	F,J,K	BP	50
CDR32BP202A	2,000	F,J,K	BP	50
CDR32BP222A	2,200	F,J,K	BP	50
AVX Style 12	206/CDR32	(BX)		
CDR32BX472B CDR32BX562B CDR32BX682B CDR32BX822B CDR32BX103B CDR32BX123B	4,700 5,600 6,800 8,200 10,000	K,M K,M K,M K,M K,M	BX BX BX BX BX	100 100 100 100 100 100
CDR32BX153B CDR32BX183A CDR32BX223A CDR32BX273A CDR32BX333A	15,000 18,000 22,000 27,000 33,000	K,M K,M K,M K,M	BX BX BX BX	100 50 50 50 50
CDR32BX393A	39,000	K,M	BX	50

1/ The complete part number will include additional symbols to indicate capacitance tolerance, termination and failure rate level.

Add appropriate failure rate

- Capacitance Tolerance

Add appropriate termination finish





Military Part Number Identification CDR33/34/35

CDR33/34/35 to MIL-PRF-55681/9/10/11

Military Type Designation <u>1</u> /	Capacitance in pF	Capacitance tolerance	Rated temperature and voltage- temperature limits	WVDC
AVX Style 12	210/CDR33	(BP)		
CDR33BP102B CDR33BP112B CDR33BP132B CDR33BP152B CDR33BP162B CDR33BP162B CDR33BP202B CDR33BP222B CDR33BP242A CDR33BP272A CDR33BP302A CDR33BP302A	1,000 1,100 1,200 1,300 1,500 1,600 1,800 2,000 2,200 2,400 2,700 3,000 3,300	F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K	BP BP BP BP BP BP BP BP BP BP BP	100 100 100 100 100 100 100 100 100 50 50
AVX Style 12	210/CDR33	(BX)		
CDR33BX153B CDR33BX183B CDR33BX223B CDR33BX273B CDR33BX473A CDR33BX563A CDR33BX563A CDR33BX683A CDR33BX823A CDR33BX104A	15,000 18,000 22,000 27,000 39,000 47,000 56,000 68,000 82,000 100,000	K,M K,M K,M K,M K,M K,M K,M K,M	BX BX BX BX BX BX BX BX BX BX	100 100 100 100 50 50 50 50 50 50
AVX Style 18	312/CDR34	(BP)		
CDR34BP222B CDR34BP242B CDR34BP302B CDR34BP302B CDR34BP332B CDR34BP392B CDR34BP432B CDR34BP432B CDR34BP472B CDR34BP512A CDR34BP622A CDR34BP682A CDR34BP682A CDR34BP752A CDR34BP822A	2,200 2,400 2,700 3,000 3,300 3,600 3,900 4,300 4,700 5,100 5,600 6,200 6,800 7,500 8,200	F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K	BP BP BP BP BP BP BP BP BP BP BP BP BP	100 100 100 100 100 100 100 100 50 50 50 50
CDR34BP912A CDR34BP103A	9,100 10,000	F,J,K F,J,K	BP BP	50 50
	Add appropriateAdd appropriateCapacitance Tole	termination finis	h	

Military Type Designation <u>1</u> /	Capacitance in pF	Capacitance tolerance	Rated temperature and voltage-temperature limits	WVDC
AVX Style 18	812/CDR34	(BX)		
CDR34BX273B CDR34BX333B CDR34BX393B CDR34BX473B CDR34BX563B	27,000 33,000 39,000 47,000 56,000	K,M K,M K,M K,M K,M	BX BX BX BX BX	100 100 100 100 100
CDR34BX104A CDR34BX124A CDR34BX154A CDR34BX184A	100,000 120,000 150,000 180,000	K,M K,M K,M K,M	BX BX BX BX	50 50 50 50
AVX Style 18	825/CDR35	(BP)		
CDR35BP472B CDR35BP562B CDR35BP622B CDR35BP682B CDR35BP752B CDR35BP912B CDR35BP103B CDR35BP113A CDR35BP133A CDR35BP153A CDR35BP183A CDR35BP183A CDR35BP183A CDR35BP183A CDR35BP183A CDR35BP183A CDR35BP183A CDR35BP183A CDR35BP183A	4,700 5,100 5,600 6,200 6,800 7,500 8,200 9,100 10,000 11,000 13,000 15,000 16,000 18,000 20,000 22,000	F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K F,J,K	BP BP BP BP BP BP BP BP BP BP BP BP BP B	100 100 100 100 100 100 100 100 50 50 50 50 50 50
AVX Style 18	325/CDR35	(BX)		
CDR35BX563B CDR35BX823B CDR35BX104B CDR35BX124B CDR35BX154B CDR35BX154B CDR35BX224A CDR35BX274A CDR35BX334A CDR35BX394A CDR35BX35BX474A	56,000 68,000 82,000 100,000 120,000 150,000 180,000 220,000 270,000 330,000 470,000	K,M K,M K,M K,M K,M K,M K,M K,M K,M	BX BX BX BX BX BX BX BX BX BX BX BX	100 100 100 100 100 100 100 50 50 50 50 50
	 Add appropriate 	failure rate		

 $[\]underline{1}/$ The complete part number will include additional symbols to indicate capacitance tolerance, termination and failure rate level.

Add appropriate termination finish

Capacitance Tolerance



Packaging of Chip Components



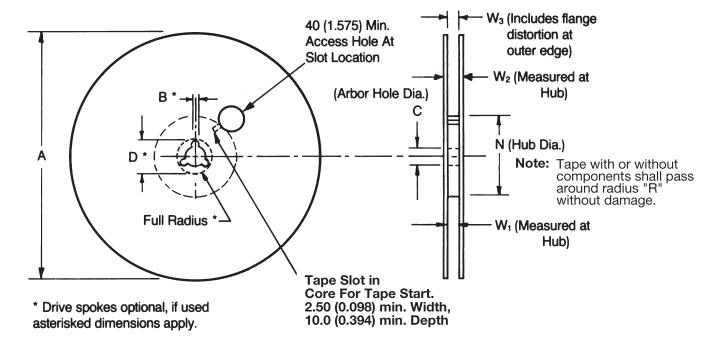
Automatic Insertion Packaging

TAPE & REEL QUANTITIES

All tape and reel specifications are in compliance with RS481.

	4mm	8mm	12mm	
Paper or Embossed Carrier		0612, 0508, 0805, 1206, 1210		
Embossed Only	0101		1808	1812, 1825 2220, 2225
Paper Only		0101, 0201, 0306, 0402, 0603		
Qty. per Reel/7" Reel	4,000	2,000, 3,000 or 4,000, 10,000, 15,000, 20,000 Contact factory for exact quantity	3,000	500, 1,000 Contact factory for exact quantity
Qty. per Reel/13" Reel		5,000, 10,000, 50,000 Contact factory for exact quantity	10,000	4,000

REEL DIMENSIONS



Tape Size [®]	A Max.	B* Min.	С	D* Min.	N Min.	W ₁	W ₂ Max.	W ₃
4mm	1.80	1.5	13.0±0.5	20.2	60.0	4.35±0.3	7.95	
4111111	(7.087)	(0.059)	(0.522±0.020)	(0.795)	(2.362)	(0.171±0.011)	(0.312)	
8mm	330	1.5	13.0 +0.50	20.2	50.0	8.40 ^{+1.5} (0.331 ^{+0.059})	14.4 (0.567)	7.90 Min. (0.311) 10.9 Max. (0.429)
12mm	(12.992)	(0.059)	(0.512 ±0.000)	(0.795)	(1.969)	12.4 ½0 (0.488 ±0.0 ⁷⁹)	18.4 (0.724)	11.9 Min. (0.469) 15.4 Max. (0.607)

Metric dimensions will govern.

English measurements rounded and for reference only.

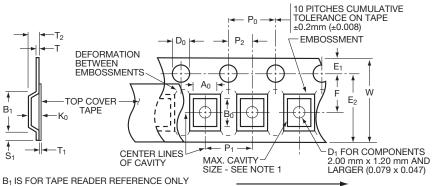
⁽¹⁾ For tape sizes 16mm and 24mm (used with chip size 3640) consult EIA RS-481 latest revision.

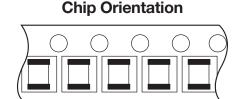


Embossed Carrier Configuration



4, 8 & 12mm Tape Only





B₁ IS FOR TAPE READER REFERENCE ONLY INCLUDING DRAFT CONCENTRIC AROUND B₀

User Direction of Feed

4, 8 & 12mm Embossed Tape Metric Dimensions Will Govern

CONSTANT DIMENSIONS

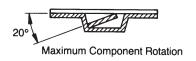
Tape Size	D ₀	E ₁	P ₀	P ₂	S ₁ Min.	T Max.	T ₁ Max.
4mm	0.80±0.04	0.90±0.05	2.0±0.04	1.00±0.02	1.075	0.26	0.06
7111111	(0.031±0.001)	(0.035±0.001)	(0.078±0.001)	(0.039±0.0007)	(0.042)	(0.010)	(0.002)
8mm	1.50 +0.10	1.75 ± 0.10	4.0 ± 0.10	2.0 ± 0.05	0.60	0.60	0.10
& 12mm		(0.069 ± 0.004)	(0.157 ± 0.004)	(0.079 ± 0.002)	(0.024)	(0.024)	(0.004)

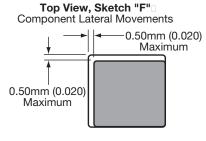
VARIABLE DIMENSIONS

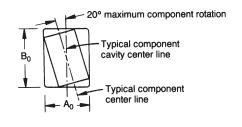
Tape Size	B ₁ Max.	D₁ Min.	E ₂ Min.	F	P ₁ See Note 5	R Min. See Note 2	T ₂	W Max.	$A_0 B_0 K_0$
8mm	4.35 (0.171)	1.00 (0.039)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	4.00 ± 0.10 (0.157 ± 0.004)	25.0 (0.984)	2.50 Max. (0.098)	8.30 (0.327)	See Note 1
12mm	8.20 (0.323)	1.50 (0.059)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	4.00 ± 0.10 (0.157 ± 0.004)	30.0 (1.181)	6.50 Max. (0.256)	12.3 (0.484)	See Note 1
8mm 1/2 Pitch	4.35 (0.171)	1.00 (0.039)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	2.00 ± 0.10 (0.079 ± 0.004)	25.0 (0.984)	2.50 Max. (0.098)	8.30 (0.327)	See Note 1
12mm Double Pitch	8.20 (0.323)	1.50 (0.059)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	8.00 ± 0.10 (0.315 ± 0.004)	30.0 (1.181)	6.50 Max. (0.256)	12.3 (0.484)	See Note 1

NOTES

- 1. The cavity defined by A₀, B₀, and K₀ shall be configured to provide the following: Surround the component with sufficient clearance such that:
 - a) the component does not protrude beyond the sealing plane of the cover tape.
 - b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the cover tape has been removed.
 - c) rotation of the component is limited to 20° maximum (see Sketches D & E).
 - d) lateral movement of the component is restricted to 0.5mm maximum (see Sketch F).
- 2. Tape with or without components shall pass around radius "R" without damage.
- Bar code labeling (if required) shall be on the side of the reel opposite the round sprocket holes. Refer to EIA-556.
- 4. B₁ dimension is a reference dimension for tape feeder clearance only.
- 5. If $P_{\scriptscriptstyle 1}=2.0\text{mm},$ the tape may not properly index in all tape feeders.





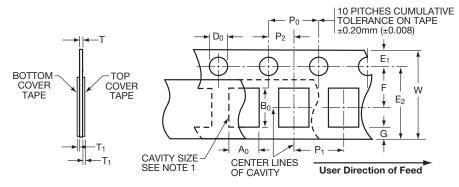




Paper Carrier Configuration



8 & 12mm Tape Only



8 & 12mm Paper Tape Metric Dimensions Will Govern

CONSTANT DIMENSIONS

Tape Size	D ₀	E	P ₀	P ₂	T ₁	G. Min.	R Min.
8mm and 12mm	1.50 ±0.10 (0.059 ±0.004)	1.75 ± 0.10 (0.069 ± 0.004)	4.00 ± 0.10 (0.157 ± 0.004)	2.00 ± 0.05 (0.079 ± 0.002)	0.10 (0.004) Max.	0.75 (0.030) Min.	25.0 (0.984) See Note 2 Min.

VARIABLE DIMENSIONS

Tape Size	P ₁ See Note 4	E ₂ Min.	F	W	$A_0 B_0$	Т
8mm	4.00 ± 0.10 (0.157 ± 0.004)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	8.00 ^{+0.30} (0.315 ^{+0.012})	See Note 1	1.10mm
12mm	4.00 ± 0.010 (0.157 ± 0.004)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	12.0 ± 0.30 (0.472 ± 0.012)		(0.043) Max. for Paper Base Tape and
8mm 1/2 Pitch	2.00 ± 0.05 (0.079 ± 0.002)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	8.00 ±0.30 (0.315 ±0.004)		1.60mm (0.063) Max. for Non-Paper Base Compositions
12mm Double Pitch	8.00 ± 0.10 (0.315 ± 0.004)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	12.0 ± 0.30 (0.472 ± 0.012)		Dase Compositions

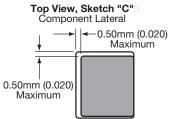
holes. Refer to EIA-556.

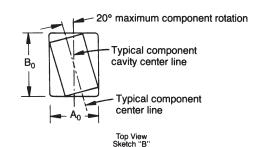
NOTES

- The cavity defined by A₀, B₀, and T shall be configured to provide sufficient clearance surrounding the component so that:
 - a) the component does not protrude beyond either surface of the carrier tape;
 - b) the component can be removed from the cavity in a vertical direction without mechanical restriction after the top cover tape has been removed;
 - c) rotation of the component is limited to 20° maximum (see Sketches A & B);
 - d) lateral movement of the component is restricted to 0.5mm maximum (see Sketch C).

Maximum Component Rotation

Side or Front Sectional View Sketch "4"





2. Tape with or without components shall pass around radius "R" without damage.

4. If $P_1 = 2.0$ mm, the tape may not properly index in all tape feeders.

3. Bar code labeling (if required) shall be on the side of the reel opposite the sprocket

Bar Code Labeling Standard

AVX bar code labeling is available and follows latest version of EIA-556



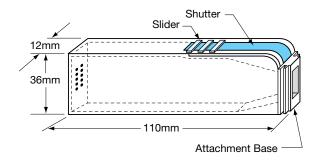
Bulk Case Packaging



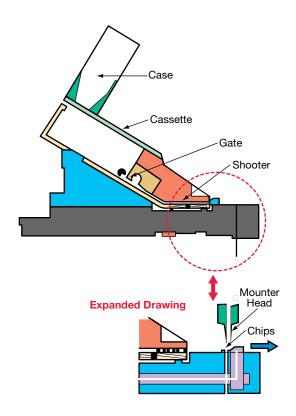
BENEFITS

- Easier handling
- Smaller packaging volume (1/20 of T/R packaging)
- Easier inventory control
- Flexibility
- Recyclable

CASE DIMENSIONS



BULK FEEDER



CASE QUANTITIES

Part Size	0402	0603	0805	1206
Qty. (pcs / cassette)	80,000	15,000	10,000 (T=.023") 8,000 (T=.031") 6,000 (T=.043")	5,000 (T=.023") 4,000 (T=.032") 3,000 (T=.044")



Basic Capacitor Formulas



I. Capacitance (farads)

English:
$$C = \frac{.224 \text{ K A}}{T_{\text{D}}}$$

Metric: $C = \frac{.0884 \text{ K A}}{T_{\text{D}}}$

II. Energy stored in capacitors (Joules, watt - sec)

III. Linear charge of a capacitor (Amperes)

$$I = C \frac{dV}{dt}$$

IV. Total Impedance of a capacitor (ohms)

$$Z = \sqrt{R_S^2 + (X_C - X_L)^2}$$

V. Capacitive Reactance (ohms)

$$x_C = \frac{1}{2 \pi fC}$$

VI. Inductive Reactance (ohms)

$$x_L = 2 \pi fL$$

VII. Phase Angles:

Ideal Capacitors: Current leads voltage 90° Ideal Inductors: Current lags voltage 90° Ideal Resistors: Current in phase with voltage

VIII. Dissipation Factor (%)

D.F.=
$$\tan \delta$$
 (loss angle) = $\frac{\text{E.S.R.}}{\text{X}_{\text{C}}}$ = (2 π fC) (E.S.R.)

IX. Power Factor (%)

P.F. = Sine δ (loss angle) = Cos ϕ (phase angle) P.F. = (when less than 10%) = DF

X. Quality Factor (dimensionless)

Q = Cotan
$$\delta$$
 (loss angle) = $\frac{1}{D.F.}$

XI. Equivalent Series Resistance (ohms)

E.S.R. = (D.F.) (Xc) = (D.F.) / (2
$$\pi$$
 fC)

XII. Power Loss (watts)

Power Loss = $(2 \pi fCV^2)$ (D.F.)

XIII. KVA (Kilowatts)

$$KVA = 2 \pi fCV^2 \times 10^{-3}$$

XIV. Temperature Characteristic (ppm/°C)

T.C. =
$$\frac{Ct - C_{25}}{C_{25} (T_t - 25)} \times 10^6$$

XV. Cap Drift (%)

C.D. =
$$\frac{C_1 - C_2}{C_1}$$
 x 100

XVI. Reliability of Ceramic Capacitors

$$\begin{array}{c} L_{o} = \left(\frac{V_{t}}{V_{o}} \right) X & \left(\frac{T_{t}}{T_{o}} \right) \end{array} Y$$

XVII. Capacitors in Series (current the same)

Any Number:
$$\frac{1}{C_T} = \frac{1}{C_1} + \frac{1}{C_2} - \cdots \frac{1}{C_N}$$
 Two: $C_T = \frac{C_1 C_2}{C_1 + C_2}$

XVIII. Capacitors in Parallel (voltage the same)

$$C_T = C_1 + C_2 - - + C_N$$

XIX. Aging Rate

A.R. =
$$\%\Delta$$
 C/decade of time

XX. Decibels

$$db = 20 \log \frac{V_1}{V_2}$$

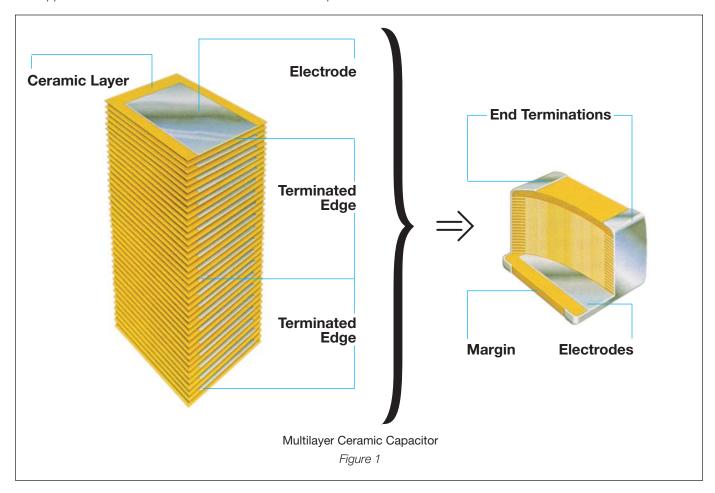
METRIC PREFIXES SYMBOLS

Pico	X 10 ⁻¹²
Nano	X 10 ⁻⁹
Micro	X 10 ⁻⁶
Milli	X 10 ⁻³
Deci	X 10 ⁻¹
Deca	X 10 ⁺¹
Kilo	X 10+3
Mega	X 10 ⁺⁶
Giga	X 10+9
Tera	X 10 ⁺¹²



Basic Construction – A multilayer ceramic (MLC) capacitor is a monolithic block of ceramic containing two sets of offset, interleaved planar electrodes that extend to two opposite surfaces of the ceramic dielectric. This simple

structure requires a considerable amount of sophistication, both in material and manufacture, to produce it in the quality and quantities needed in today's electronic equipment.



Formulations - Multilayer ceramic capacitors are available in both Class 1 and Class 2 formulations. Temperature compensating formulation are Class 1 and temperature stable and general application formulations are classified as Class 2.

Class 1 – Class 1 capacitors or temperature compensating capacitors are usually made from mixtures of titanates where barium titanate is normally not a major part of the mix. They have predictable temperature coefficients and in general, do not have an aging characteristic. Thus they are the most stable capacitor available. The most popular Class 1 multilayer ceramic capacitors are COG (NPO) temperature compensating capacitors (negative-positive 0 ppm/°C).

Class 2 – EIA Class 2 capacitors typically are based on the chemistry of barium titanate and provide a wide range of capacitance values and temperature stability. The most commonly used Class 2 dielectrics are X7R and Y5V. The X7R provides intermediate capacitance values which vary only ±15% over the temperature range of -55°C to 125°C. It finds applications where stability over a wide temperature range is required.

The Y5V provides the highest capacitance values and is used in applications where limited temperature changes are expected. The capacitance value for Y5V can vary from 22% to -82% over the -30°C to 85°C temperature range.

All Class 2 capacitors vary in capacitance value under the influence of temperature, operating voltage (both AC and DC), and frequency. For additional information on performance changes with operating conditions, consult AVX's software, SpiCap.





Table 1: EIA and MIL Temperature Stable and General Application Codes

EIA CODE Percent Capacity Change Over Temperature Range					
RS198	Temperature Range				
X7 X6	-55°C to +125°C -55°C to +105°C				
X5	-55°C to +85°C				
Y5 Z5	-30°C to +85°C +10°C to +85°C				
Code	Percent Capacity Change				
D	±3.3%				
E F	±4.7% ±7.5%				
P	±10%				
R	±15%				
S	±22%				
T	+22%, -33%				
U	+22%, - 56%				
V	+22%, -82%				

EXAMPLE – A capacitor is desired with the capacitance value at 25°C to increase no more than 7.5% or decrease no more than 7.5% from -30°C to +85°C. EIA Code will be Y5F.

	MIL CODE								
Symbol	Temperature Range								
A B C	-55°C to +85°C -55°C to +125°C -55°C to +150°C								
Symbol	Cap. Change Zero Volts	Cap. Change Rated Volts							
R S W X Y	+15%, -15% +22%, -22% +22%, -56% +15%, -15% +30%, -70% +20%, -20%	+15%, -40% +22%, -56% +22%, -66% +15%, -25% +30%, -80% +20%, -30%							

Temperature characteristic is specified by combining range and change symbols, for example BR or AW. Specification slash sheets indicate the characteristic applicable to a given style of capacitor.

In specifying capacitance change with temperature for Class 2 materials, EIA expresses the capacitance change over an operating temperature range by a 3 symbol code. The first symbol represents the cold temperature end of the temperature range, the second represents the upper limit of the operating temperature range and the third symbol represents the capacitance change allowed over the operating temperature range. Table 1 provides a detailed explanation of the EIA system.

Effects of Voltage – Variations in voltage have little effect on Class 1 dielectric but does affect the capacitance and dissipation factor of Class 2 dielectrics. The application of DC voltage reduces both the capacitance and dissipation factor while the application of an AC voltage within a reasonable range tends to increase both capacitance and dissipation factor readings. If a high enough AC voltage is applied, eventually it will reduce capacitance just as a DC voltage will. Figure 2 shows the effects of AC voltage.

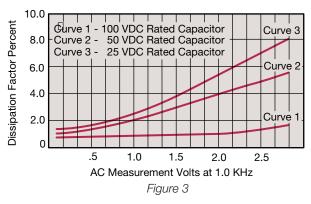




Figure 2

Capacitor specifications specify the AC voltage at which to measure (normally 0.5 or 1 VAC) and application of the wrong voltage can cause spurious readings. Figure 3 gives the voltage coefficient of dissipation factor for various AC voltages at 1 kilohertz. Applications of different frequencies will affect the percentage changes versus voltages.

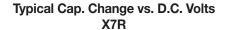
D.F. vs. A.C. Measurement Volts X7R

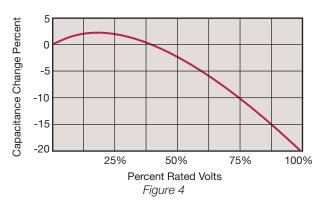


Typical effect of the application of DC voltage is shown in Figure 4. The voltage coefficient is more pronounced for higher K dielectrics. These figures are shown for room temperature conditions. The combination characteristic known as voltage temperature limits which shows the effects of rated voltage over the operating temperature range is shown in Figure 5 for the military BX characteristic.

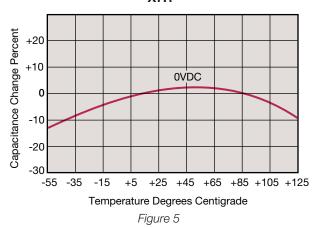








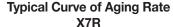
Typical Cap. Change vs. Temperature X7R



Effects of Time - Class 2 ceramic capacitors change capacitance and dissipation factor with time as well as temperature, voltage and frequency. This change with time is known as aging. Aging is caused by a gradual re-alignment of the crystalline structure of the ceramic and produces an exponential loss in capacitance and decrease in dissipation factor versus time. A typical curve of aging rate for semistable ceramics is shown in Figure 6.

If a Class 2 ceramic capacitor that has been sitting on the shelf for a period of time, is heated above its curie point, (125°C for 4 hours or 150°C for ½ hour will suffice) the part will de-age and return to its initial capacitance and dissi-pation factor readings. Because the capacitance changes rapidly, immediately after de-aging, the basic capacitance measurements are normally referred to a time period sometime after the de-aging process. Various manufacturers use different time bases but the most popular one is one day or twenty-four hours after "last heat." Change in the aging curve can be caused by the application of voltage and other stresses. The possible changes in capacitance due to de-aging by heating the unit explain why capacitance changes are allowed after test, such as temperature cycling, moisture resistance, etc., in MIL specs. The application of high voltages such as dielectric withstanding voltages also tends to de-age

capacitors and is why re-reading of capacitance after 12 or 24 hours is allowed in military specifications after dielectric strength tests have been performed.



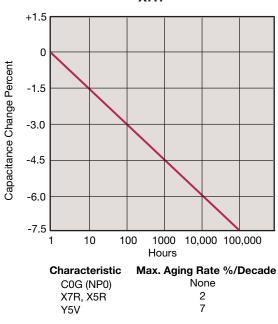


Figure 6

Effects of Frequency - Frequency affects capacitance and impedance characteristics of capacitors. This effect is much more pronounced in high dielectric constant ceramic formulation than in low K formulations. AVX's SpiCap software generates impedance, ESR, series inductance, series resonant frequency and capacitance all as functions of frequency, temperature and DC bias for standard chip sizes and styles. It is available free from AVX and can be downloaded for free from AVX website: www.avx.com.







Effects of Mechanical Stress - High "K" dielectric ceramic capacitors exhibit some low level piezoelectric reactions under mechanical stress. As a general statement, the piezoelectric output is higher, the higher the dielectric constant of the ceramic. It is desirable to investigate this effect before using high "K" dielectrics as coupling capacitors in extremely low level applications.

Reliability - Historically ceramic capacitors have been one of the most reliable types of capacitors in use today. The approximate formula for the reliability of a ceramic capacitor is:

$$\frac{L_o}{L_t} = \left(\frac{V_t}{V_o}\right)^X \left(\frac{T_t}{T_o}\right)^Y$$

where

 $\mathbf{T_t}$ = test temperature and $\mathbf{T_o}$ = operating temperature L_o = operating life **L**_t = test life

V_t = test voltage

V_o = operating voltage X,Y = see text

Historically for ceramic capacitors exponent X has been considered as 3. The exponent Y for temperature effects typically tends to run about 8.

A capacitor is a component which is capable of storing electrical energy. It consists of two conductive plates (electrodes) separated by insulating material which is called the dielectric. A typical formula for determining capacitance is:

$$C = \frac{.224 \text{ KA}}{t}$$

C = capacitance (picofarads)

K = dielectric constant (Vacuum = 1)

 \mathbf{A} = area in square inches

t = separation between the plates in inches (thickness of dielectric)

.224 = conversion constant

(.0884 for metric system in cm)

Capacitance - The standard unit of capacitance is the farad. A capacitor has a capacitance of 1 farad when 1 coulomb charges it to 1 volt. One farad is a very large unit and most capacitors have values in the micro (10-6), nano (10⁻⁹) or pico (10⁻¹²) farad level.

Dielectric Constant – In the formula for capacitance given above the dielectric constant of a vacuum is arbitrarily chosen as the number 1. Dielectric constants of other materials are then compared to the dielectric constant of a vacuum.

Dielectric Thickness - Capacitance is indirectly proportional to the separation between electrodes. Lower voltage requirements mean thinner dielectrics and greater capacitance per volume.

Area - Capacitance is directly proportional to the area of the electrodes. Since the other variables in the equation are usually set by the performance desired, area is the easiest parameter to modify to obtain a specific capacitance within a material group.

Energy Stored - The energy which can be stored in a capacitor is given by the formula:

E = energy in joules (watts-sec)

V = applied voltage

C = capacitance in farads

Potential Change - A capacitor is a reactive component which reacts against a change in potential across it. This is shown by the equation for the linear charge of a capacitor:

$$I_{ideal} = C \frac{dV}{dt}$$

where

I = Current

C = Capacitance

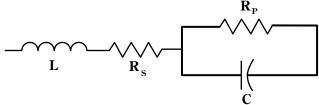
dV/dt = Slope of voltage transition across capacitor

Thus an infinite current would be required to instantly change the potential across a capacitor. The amount of current a capacitor can "sink" is determined by the above equation.

Equivalent Circuit - A capacitor, as a practical device, exhibits not only capacitance but also resistance and inductance. A simplified schematic for the equivalent circuit

C = Capacitance

L = Inductance



 $\mathbf{R}_{\mathbf{p}}$ = Parallel Resistance $\mathbf{R_s}$ = Series Resistance **Reactance** - Since the insulation resistance (R_p) is normally very high, the total impedance of a capacitor is:

$$Z = \sqrt{R_s^2 + (X_c - X_1)^2}$$

where

Z = Total Impedance

 $\mathbf{R}_{\mathrm{S}} = \text{Series Resistance}$ $\mathbf{X}_{\mathrm{C}} = \text{Capacitive Reactance} =$

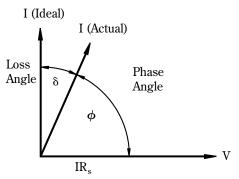
 \mathbf{X}_{1} = Inductive Reactance = $2 \pi fL$

The variation of a capacitor's impedance with frequency determines its effectiveness in many applications.

Phase Angle - Power Factor and Dissipation Factor are often confused since they are both measures of the loss in a capacitor under AC application and are often almost identical in value. In a "perfect" capacitor the current in the capacitor will lead the voltage by 90°.





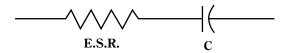


In practice the current leads the voltage by some other phase angle due to the series resistance $R_{\rm S}$. The complement of this angle is called the loss angle and:

Power Factor (P.F.) = Cos ϕ or Sine δ Dissipation Factor (D.F.) = $\tan \delta$

for small values of δ the tan and sine are essentially equal which has led to the common interchangeability of the two terms in the industry.

Equivalent Series Resistance - The term E.S.R. or Equivalent Series Resistance combines all losses both series and parallel in a capacitor at a given frequency so that the equivalent circuit is reduced to a simple R-C series connection.



Dissipation Factor - The DF/PF of a capacitor tells what percent of the apparent power input will turn to heat in the capacitor.

Dissipation Factor =
$$\frac{\text{E.S.R.}}{\text{X}_{\odot}}$$
 = (2 π fC) (E.S.R.)

The watts loss are:

Watts loss =
$$(2 \pi fCV^2)$$
 (D.F.)

Very low values of dissipation factor are expressed as their reciprocal for convenience. These are called the "Q" or Quality factor of capacitors.

Parasitic Inductance – The parasitic inductance of capacitors is becoming more and more important in the decoupling of today's high speed digital systems. The relationship between the inductance and the ripple voltage induced on the DC voltage line can be seen from the simple inductance equation:

$$V = L \frac{di}{dt}$$

The $\frac{dl}{dt}$ seen in current microprocessors can be as high as 0.3 A/ns, and up to 10A/ns. At 0.3 A/ns, 100pH of parasitic inductance can cause a voltage spike of 30mV. While this does not sound very drastic, with the Vcc for microprocessors decreasing at the current rate, this can be a fairly large percentage.

Another important, often overlooked, reason for knowing the parasitic inductance is the calculation of the resonant frequency. This can be important for high frequency, bypass capacitors, as the resonant point will give the most signal attenuation. The resonant frequency is calculated from the simple equation:

$$f_{\text{res}} = \frac{1}{2\pi\sqrt{LC}}$$

Insulation Resistance - Insulation Resistance is the resistance measured across the terminals of a capacitor and consists principally of the parallel resistance Rp shown in the equivalent circuit. As capacitance values and hence the area of dielectric increases, the I.R. decreases and hence the product (C x IR or RC) is often specified in ohm farads or more commonly megohm-microfarads. Leakage current is determined by dividing the rated voltage by IR (Ohm's Law).

Dielectric Strength - Dielectric Strength is an expression of the ability of a material to withstand an electrical stress. Although dielectric strength is ordinarily expressed in volts, it is actually dependent on the thickness of the dielectric and thus is also more generically a function of volts/mil.

Dielectric Absorption - A capacitor does not discharge instantaneously upon application of a short circuit, but drains gradually after the capacitance proper has been discharged. It is common practice to measure the dielectric absorption by determining the "reappearing voltage" which appears across a capacitor at some point in time after it has been fully discharged under short circuit conditions.

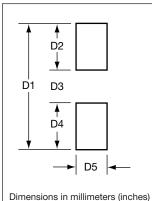
Corona - Corona is the ionization of air or other vapors which causes them to conduct current. It is especially prevalent in high voltage units but can occur with low voltages as well where high voltage gradients occur. The energy discharged degrades the performance of the capacitor and can in time cause catastrophic failures.



MLC Chip Capacitors



REFLOW SOLDERING



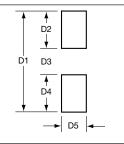
Case Size	D1	D2	D3	D4	D5
0201	0.85 (0.033)	0.30 (0.012)	0.25 (0.010)	0.30 (0.012)	0.35 (0.014)
0402	1.70 (0.067)	0.60 (0.024)	0.50 (0.020)	0.60 (0.024)	0.50 (0.020)
0603	2.30 (0.091)	0.80 (0.031)	0.70 (0.028)	0.80 (0.031)	0.75 (0.030)
0805	3.00 (0.118)	1.00 (0.039)	1.00 (0.039)	1.00 (0.039)	1.25 (0.049)
1206	4.00 (0.157)	1.00 (0.039)	2.00 (0.079)	1.00 (0.039)	1.60 (0.063)
1210	4.00 (0.157)	1.00 (0.039)	2.00 (0.079)	1.00 (0.039)	2.50 (0.098)
1808	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	2.00 (0.079)
1812	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	3.00 (0.118)
1825	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	6.35 (0.250)
2220	6.60 (0.260)	1.00 (0.039)	4.60 (0.181)	1.00 (0.039)	5.00 (0.197)
2225	6.60 (0.260)	1.00 (0.039)	4.60 (0.181)	1.00 (0.039)	6.35 (0.250)

Component Pad Design

Component pads should be designed to achieve good solder filets and minimize component movement during reflow soldering. Pad designs are given below for the most common sizes of multilayer ceramic capacitors for both wave and reflow soldering. The basis of these designs is:

- Pad width equal to component width. It is permissible to decrease this to as low as 85% of component width but it is not advisable to go below this.
- Pad overlap 0.5mm beneath component.
- Pad extension 0.5mm beyond components for reflow and 1.0mm for wave soldering.

WAVE SOLDERING

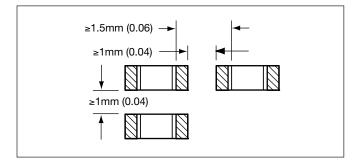


Case Size	D1	D2	D3	D4	D5
0603	3.10 (0.12)	1.20 (0.05)	0.70 (0.03)	1.20 (0.05)	0.75 (0.03)
0805	4.00 (0.15)	1.50 (0.06)	1.00 (0.04)	1.50 (0.06)	1.25 (0.05)
1206	5.00 (0.19)	1.50 (0.06)	2.00 (0.09)	1.50 (0.06)	1.60 (0.06)

Dimensions in millimeters (inches)

Component Spacing

For wave soldering components, must be spaced sufficiently far apart to avoid bridging or shadowing (inability of solder to penetrate properly into small spaces). This is less important for reflow soldering but sufficient space must be allowed to enable rework should it be required.



Preheat & Soldering

The rate of preheat should not exceed 4°C/second to prevent thermal shock. A better maximum figure is about 2°C/second.

For capacitors size 1206 and below, with a maximum thickness of 1.25mm, it is generally permissible to allow a temperature differential from preheat to soldering of 150°C. In all other cases this differential should not exceed 100°C.

For further specific application or process advice, please consult AVX.

Cleaning

Care should be taken to ensure that the capacitors are thoroughly cleaned of flux residues especially the space beneath the capacitor. Such residues may otherwise become conductive and effectively offer a low resistance bypass to the capacitor.

Ultrasonic cleaning is permissible, the recommended conditions being 8 Watts/litre at 20-45 kHz, with a process cycle of 2 minutes vapor rinse, 2 minutes immersion in the ultrasonic solvent bath and finally 2 minutes vapor rinse.



Recommended Soldering Profiles



REFLOW SOLDER PROFILES

AVX RoHS compliant products utilize termination finishes (e.g.Sn or SnAg) that are compatible with all Pb-Free soldering systems and are fully reverse compatible with SnPb soldering systems. A recommended SnPb profile is shown for comparison; for Pb-Free soldering, IPC/JEDECJ-STD-020C may be referenced. The upper line in the chart shows the maximum envelope to which products are qualified (typically 3x reflow cycles at 260°C max). The center line gives the recommended profile for optimum wettability and soldering in Pb-Free Systems.

Recommended Reflow Profiles 275 250 200 175 150 100 75 50 20 20 40 60 80 100 120 140 160 180 200 220 240 260 280 300 320 340 360 380 400 420 Time / secs

Preheat:

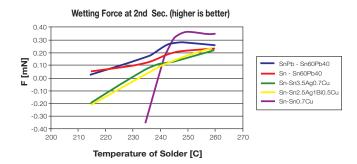
The pre-heat stabilizes the part and reduces the temperature differential prior to reflow. The initial ramp to 125°C may be rapid, but from that point (2-3)°C/sec is recommended to allow ceramic parts to heat uniformly and plastic encapsulated parts to stabilize through the glass transition temperature of the body (~ 180°C).

Reflow:

In the reflow phase, the maximum recommended time > 230°C is 40secs. Time at peak reflow is 10secs max.; optimum reflow is achieved at 250°C, (see wetting balance chart opposite) but products are qualified to 260°C max. Please reference individual product datasheets for maximum limits

Cool Down:

Cool down should not be forced and 6°C/sec is recommended. A slow cool down will result in a finer grain structure of the reflow solder in the solder fillet.



IMPORTANT NOTE: Typical Pb-Free reflow solders have a more dull and grainy appearance compared to traditional SnPb. Elevating the reflow temperature will not change this, but extending the cool down can help improve the visual appearance of the joint.

WAVE SOLDER PROFILES

For wave solder, there is no change in the recommended wave profile; all standard Pb-Free (SnCu/SnCuAg) systems operate at the same 260°C max recommended for SnPb systems.

Preheat:

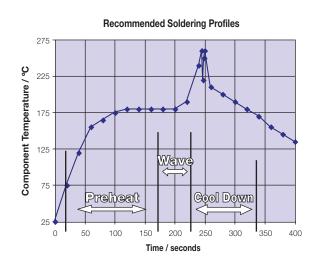
This is more important for wave solder; a higher temperature preheat will reduce the thermal shock to SMD parts that are immersed (please consult individual product data sheets for SMD parts that are suited to wave solder). SMD parts should ideally be heated from the bottom-Side prior to wave. PTH (Pin through hole) parts on the topside should not be separately heated.

Wave:

250°C - 260°C recommended for optimum solderability.

Cool Down:

As with reflow solder, cool down should not be forced and 6°C/sec is recommended. Any air knives at the end of the 2nd wave should be heated.





MLC Chip Capacitors



APPLICATION NOTES

Storage

The components should be stored in their "as received packaging" where possible. If the components are removed from their original packaging then they should be stored in an airtight container (e.g. a heat sealed plastic bag) with desiccant (e.g. silica gel). Storage area temperature should be kept between +5 degrees C and +30 degrees C with humidity < 70% RH. Storage atmosphere must be free of gas containing sulfur and chlorine. Avoid exposing the product to saline moisture or to temperature changes that might result in the formation of condensation. To assure good solderability performance we recommend that the product be used within 6 months from our shipping date, but can be used for up to 12 months. Chip capacitors may crack if exposed to hydrogen (H2) gas while sealed or if coated with silicon, which generates hydrogen gas.

Solderability

Terminations to be well soldered after immersion in a 60/40 tin/lead solder bath at $235 \pm 5^{\circ}$ C for 2 ± 1 seconds.

Leaching

Terminations will resist leaching for at least the immersion times and conditions shown below.

Termination Type	Solder	Solder	Immersion Time
	Tin/Lead/Silver	Temp. °C	Seconds
Nickel Barrier	60/40/0	260 ± 5	30 ± 1

Lead-Free Wave Soldering

The recommended peak temperature for lead-free wave soldering is 250°C-260°C for 3-5 seconds. The other parameters of the profile remains the same as above.

The following should be noted by customers changing from lead based systems to the new lead free pastes.

- a) The visual standards used for evaluation of solder joints will need to be modified as lead free joints are not as bright as with tin-lead pastes and the fillet may not be as large.
- b) Lead-free solder pastes do not allow the same self alignment as lead containing systems. Standard mounting pads are acceptable, but machine set up may need to be modified.

General

Surface mounting chip multilayer ceramic capacitors are designed for soldering to printed circuit boards or other substrates. The construction of the components is such that they will withstand the time/temperature profiles used in both wave and reflow soldering methods.

Handling

Chip multilayer ceramic capacitors should be handled with care to avoid damage or contamination from perspiration and skin oils. The use of tweezers or vacuum pick ups is strongly recommended for individual components. Bulk

handling should ensure that abrasion and mechanical shock are minimized. Taped and reeled components provides the ideal medium for direct presentation to the placement machine. Any mechanical shock should be minimized during handling chip multilayer ceramic capacitors.

Preheat

It is important to avoid the possibility of thermal shock during soldering and carefully controlled preheat is therefore required. The rate of preheat should not exceed 4°C/second and a target figure 2°C/second is recommended. Although an 80°C to 120°C temperature differential is preferred, recent developments allow a temperature differential between the component surface and the soldering temperature of 150°C (Maximum) for capacitors of 1210 size and below with a maximum thickness of 1.25mm. The user is cautioned that the risk of thermal shock increases as chip size or temperature differential increases.

Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder to give a good joint should be used. Excessive solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. AVX terminations are suitable for all wave and reflow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Cooling

Natural cooling in air is preferred, as this minimizes stresses within the soldered joint. When forced air cooling is used, cooling rate should not exceed 4°C/second. Quenching is not recommended but if used, maximum temperature differentials should be observed according to the preheat conditions above.

Cleaning

Flux residues may be hygroscopic or acidic and must be removed. AVX MLC capacitors are acceptable for use with all of the solvents described in the specifications MIL-STD-202 and EIA-RS-198. Alcohol based solvents are acceptable and properly controlled water cleaning systems are also acceptable. Many other solvents have been proven successful, and most solvents that are acceptable to other components on circuit assemblies are equally acceptable for use with ceramic capacitors.

Prevention of Metallic Migration

Note that when components with Sn plating on the end terminations are to be used in applications that are likely to experience conditions of high humidity under bias voltage, we strongly recommend that the circuit boards be conformally coated to protect the Sn from moisture that might lead to migration and eventual current leakage.

When using Capacitor Arrays we recommend that there is no differential in applied voltage between adjacent elements.



MLC Chip Capacitors



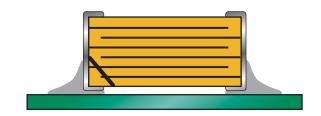
POST SOLDER HANDLING

Once SMP components are soldered to the board, any bending or flexure of the PCB applies stresses to the soldered joints of the components. For leaded devices, the stresses are absorbed by the compliancy of the metal leads and generally don't result in problems unless the stress is large enough to fracture the soldered connection.

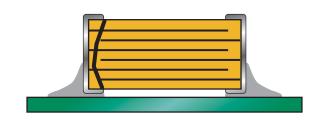
Ceramic capacitors are more susceptible to such stress because they don't have compliant leads and are brittle in nature. The most frequent failure mode is low DC resistance or short circuit. The second failure mode is significant loss of capacitance due to severing of contact between sets of the internal electrodes.

Cracks caused by mechanical flexure are very easily identified and generally take one of the following two general forms:

Mechanical cracks are often hidden underneath the termination and are difficult to see externally. However, if one end termination falls off during the removal process from PCB, this is one indication that the cause of failure was excessive mechanical stress due to board warping.



Type A:
Angled crack between bottom of device to top of solder joint.



Type B: Fracture from top of device to bottom of device.



MLC Chip Capacitors



COMMON CAUSES OF MECHANICAL CRACKING

The most common source for mechanical stress is board depanelization equipment, such as manual breakapart, v-cutters and shear presses. Improperly aligned or dull cutters may cause torqueing of the PCB resulting in flex stresses being transmitted to components near the board edge. Another common source of flexural stress is contact during parametric testing when test points are probed. If the PCB is allowed to flex during the test cycle, nearby ceramic capacitors may be broken.

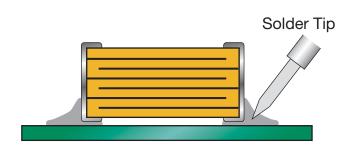
A third common source is board to board connections at vertical connectors where cables or other PCBs are connected to the PCB. If the board is not supported during the plug/unplug cycle, it may flex and cause damage to nearby components.

Special care should also be taken when handling large (>6" on a side) PCBs since they more easily flex or warp than smaller boards.

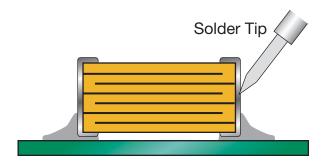
REWORKING OF MLCS

Thermal shock is common in MLCs that are manually attached or reworked with a soldering iron. AVX strongly recommends that any reworking of MLCs be done with hot air reflow rather than soldering irons. It is practically impossible to cause any thermal shock in ceramic capacitors when using hot air reflow.

However direct contact by the soldering iron tip often causes thermal cracks that may fail at a later date. If rework by soldering iron is absolutely necessary, it is recommended that the wattage of the iron be less than 30 watts and the tip temperature be <300°C. Rework should be performed by applying the solder iron tip to the pad and not directly contacting any part of the ceramic capacitor.



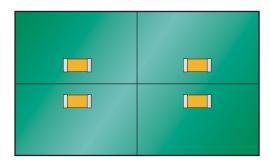
Preferred Method - No Direct Part Contact



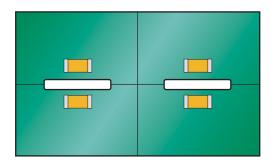
Poor Method - Direct Contact with Part

PCB BOARD DESIGN

To avoid many of the handling problems, AVX recommends that MLCs be located at least .2" away from nearest edge of board. However when this is not possible, AVX recommends that the panel be routed along the cut line, adjacent to where the MLC is located.



No Stress Relief for MLCs



Routed Cut Line Relieves Stress on MLC



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